



PolarFire® FPGA

Overview

This datasheet covers the electrical AC and DC specifications for four temperature grades of devices. AC and DC electrical characteristics and parametric values, unless otherwise noted, apply to all temperature grade devices. For example, worst-case STD speed grade applies to all temperature grade devices and –1 speed grade applies to all temperature grade devices except Military. In addition, Low Power “L” devices are equivalent in performance to STD speed grade devices where offered. Users are expected to close timing using SmartTime for the speed and temperature grade of the device chosen.

Table 1. PolarFire Minimum and Maximum Junction Temperatures by Temperature Grade

Temperature Grade	Minimum Junction Temperature	Maximum Junction Temperature
Extended Commercial (E)	0 °C	100 °C
Industrial (I)	–40 °C	100 °C
Automotive T2 (T2)	–40 °C	125 °C
Military (M)	–55 °C	125 °C

Table 2. PolarFire Speed Grade Options by Temperature Grade

Temperature Grade	Standard Speed Grade	–1 Speed Grade
Extended Commercial (E)	Available	Available
Industrial (I)	Available	Available
Automotive T2 (T2)	Available	Available
Military (M)	Available	Not Available

Table 3. PolarFire Package Ball Composition by Temperature Grade

Temperature Grade	Ball Material Composition	Package Decoupling Capacitor Solder Paste (FC484, FC784, FC1152)
Extended Commercial (E)	RoHS	RoHS
Industrial (I)	RoHS	RoHS
Automotive T2 (T2)	RoHS	RoHS
Military (M)	Pb	Pb

PolarFire device programming functions (Programming, Verify, and Digest Check) are only allowed over the Industrial temperature range regardless of the temperature grade of the device selected. Retention characteristics for each temperature range explicitly describe the retention characteristics for that temperature-grade device. You cannot, for example, use the retention characteristics at 110 °C and apply them to the Extended Commercial or Industrial devices with a maximum T_J of 100 °C. Retention characteristics for Military-grade devices and Automotive-grade devices at the absolute maximum junction temperature of 125 °C can be profiled using the PolarFire Retention Calculator, which can be obtained by contacting technical support at soc.microsemi.com/Portal/Default.aspx.

Table of Contents

Overview.....	1
1. References.....	3
2. Device Offering.....	4
3. Silicon and Libero Tool Status.....	5
4. DC Characteristics.....	7
4.1. Absolute Maximum Rating.....	7
4.2. Recommended Operating Conditions.....	7
4.3. Input and Output.....	17
5. AC Switching Characteristics.....	27
5.1. I/O Standards Specifications.....	27
5.2. Clocking Specifications.....	45
5.3. Fabric Specifications.....	50
5.4. Transceiver Switching Characteristics.....	53
5.5. Transceiver Protocol Characteristics.....	67
5.6. Non-Volatile Characteristics.....	75
5.7. System Services.....	84
5.8. Fabric Macros.....	85
5.9. Power-Up to Functional Timing.....	89
5.10. Dedicated Pins.....	93
5.11. User Crypto.....	96
6. Revision History.....	102
The Microchip Website.....	105
Product Change Notification Service.....	105
Customer Support.....	105
Microchip Devices Code Protection Feature.....	105
Legal Notice.....	106
Trademarks.....	106
Quality Management System.....	107
Worldwide Sales and Service.....	108

1. References

The following documents are recommended references. For more information about PolarFire static and dynamic power data, see the PolarFire Power Estimator Spreadsheet.

- PO0137: PolarFire FPGA Product Overview
- ER0217: PolarFire FPGA Pre-Production Device Errata
- UG0722: PolarFire FPGA Packaging and Pin Descriptions User Guide
- UG0726: PolarFire FPGA Board Design User Guide
- UG0686: PolarFire FPGA User I/O User Guide
- UG0680: PolarFire FPGA Fabric User Guide
- UG0714: PolarFire FPGA Programming User Guide
- UG0684: PolarFire FPGA Clocking Resources User Guide
- UG0687: PolarFire FPGA 1G Ethernet Solutions User Guide
- UG0727: PolarFire FPGA 10G Ethernet Solutions User Guide
- UG0748: PolarFire FPGA Low Power User Guide
- UG0676: PolarFire FPGA DDR Memory Controller User Guide
- UG0743: PolarFire FPGA Debugging User Guide
- UG0725: PolarFire FPGA Device Power-Up and Resets User Guide
- UG0677: PolarFire FPGA Transceiver User Guide
- UG0685: PolarFire FPGA PCI Express User Guide
- UG0753: PolarFire FPGA Security User Guide
- UG0752: PolarFire FPGA Power Estimator User Guide

2. Device Offering

The following table lists the PolarFire FPGA device options using the MPF300T as an example. The MPF100T, MPF200T, and MPF500T device densities have identical offerings.

Table 2-1. PolarFire FPGA Device Options

Device Options	Extended Commercial 0 °C–100 °C	Industrial –40 °C–100 °C	STD	–1	Transceivers T	Lower Static Power L	Data Security S
MPF300T	Yes	Yes	Yes	Yes	Yes	—	—
MPF300TL	Yes	Yes	Yes	—	Yes	Yes	—
MPF300TS	—	Yes	Yes	Yes	Yes	—	Yes
MPF300TLS	—	Yes	Yes	—	Yes	Yes	Yes

Table 2-2. Orderable Military (–55 °C T_J to 125 °C T_J) Device Part Numbers

STD Speed Grade	–1 Speed Grade
MPF200TS-FCS325M	N/A
MPF300TS-FC484M	N/A
MPF300TS-FCV484M	N/A
MPF300TS-FCS536M	N/A
MPF300TS-FC784M	N/A
MPF500TS-FC784M	N/A
MPF500TS-FC1152M	N/A

Table 2-3. Orderable Automotive (–40 °C T_J to 125 °C T_J) Device Part Numbers

STD Speed Grade	–1 Speed Grade
MPF100T-FCG484T2	MPF100T-1FCG484T2
MPF100T-FCVG484T2	MPF100T-1FCVG484T2
MPF100T-FCSG325T2	MPF100T-1FCSG325T2
MPF200T-FCG484T2	MPF200T-1FCG484T2
MPF200T-FCVG484T2	MPF200T-1FCVG484T2
MPF200T-FCSG325T2	MPF200T-1FCSG325T2
MPF200T-FCSG536T2	MPF200T-1FCSG536T2
MPF300T-FCVG484T2	MPF300T-1FCVG484T2
MPF300T-FCSG536T2	MPF300T-1FCSG536T2

3. Silicon and Libero Tool Status

There are three status levels:

- Advanced—initial estimated information based on simulations
- Preliminary—information based on simulation and/or initial characterization
- Production—final production data

The following tables list the status of the PolarFire FPGA silicon and Libero Timing and Power tool.

Table 3-1. PolarFire FPGA Silicon Status

Product	Silicon
MPF100T, TS, TL, TLS	Production - all temperature grades
MPF200T, TS, TL, TLS	Production - all temperature grades
MPF300T, TS, TL, TLS	Production - all temperature grades
MPF500T, TS, TL, TLS	Production - all temperature grades

Table 3-2. PolarFire FPGA Tool Status

Device	Status	Libero Version							
		Timing				Power			
		Extended Commercial		Industrial		Extended Commercial		Industrial	
		STD	–1	STD	–1	STD	–1	STD	–1
MPF100T, TS, TL, TLS	Production Vdd = 1.0 V	12.1	12.1	12.1	12.1	12.1	12.1	12.1	12.1
	Production Vdd = 1.05 V	12.2	12.2	12.2	12.2	12.2	12.2	12.2	12.2
MPF200T, TS, TL, TLS	Production Vdd = 1.0 V	12.1	12.1	12.1	12.1	12.1	12.1	12.1	12.1
	Production Vdd = 1.05 V	12.2	12.2	12.2	12.2	12.2	12.2	12.2	12.2
MPF300T, TS, TL, TLS	Production Vdd = 1.0 V	12.1	12.0	12.1	12.1	12.1	12.1	12.1	12.1
	Production Vdd = 1.05 V	12.2	12.2	12.2	12.2	12.2	12.2	12.2	12.2
MPF500T, TS, TL, TLS	Production Vdd = 1.0 V	12.2	12.2	12.2	12.2	12.2	12.2	12.2	12.2
	Production Vdd = 1.05 V	12.2	12.2	12.2	12.2	12.2	12.2	12.2	12.2

Table 3-3. Military

Device	Status	Libero Version	
		Timing	Power
		Military	Military
		STD	STD
MPF200TS	Production Vdd = 1.0 V	12.5	12.5
	Production Vdd = 1.05 V	12.5	12.5
MPF300TS	Production Vdd = 1.0 V	12.3	12.3
	Production Vdd = 1.05 V	12.5	12.5
MPF500TS	Production Vdd = 1.0 V	12.5	12.5
	Production Vdd = 1.05 V	12.5	12.5

Table 3-4. Automotive T2

Device	Status	Libero Version			
		Timing		Power	
		Automotive T2		Automotive T2	
		STD	–1	STD	–1
MPF100T	Production Vdd = 1.0 V	12.6	12.6	12.6	12.6
	Production Vdd = 1.05 V	12.6	12.6	12.6	12.6
MPF200T	Production Vdd = 1.0 V	12.6	12.6	12.6	12.6
	Production Vdd = 1.05 V	12.6	12.6	12.6	12.6
MPF300T	Production Vdd = 1.0 V	12.6	12.6	12.6	12.6
	Production Vdd = 1.05 V	12.6	12.6	12.6	12.6

4. DC Characteristics

This section lists the DC characteristics of the PolarFire FPGA device.

4.1 Absolute Maximum Rating

The following table lists the absolute maximum ratings for PolarFire devices.

Table 4-1. Absolute Maximum Rating

Parameter	Symbol	Min	Max	Unit
FPGA core power supply	V_{DD}	-0.5	1.13	V
Transceiver Tx and Rx lanes supply	V_{DDA}	-0.5	1.13	V
Programming and HSIO receiver supply	V_{DD18}	-0.5	2.0	V
FPGA core and FPGA PLL high-voltage supply	V_{DD25}	-0.5	2.7	V
Transceiver PLL high-voltage supply	V_{DDA25}	-0.5	2.7	V
Transceiver reference clock supply	$V_{DD_XCVR_CLK}$	-0.5	3.6	V
Global V_{REF} for transceiver reference clocks	$XCVR_{VREF}$	-0.5	3.6	V
HSIO DC I/O supply ²	V_{DDIx}	-0.5	2.0	V
GPIO DC I/O supply ²	V_{DDIx}	-0.5	3.6	V
Dedicated I/O DC supply for JTAG and SPI	V_{DDI3}	-0.5	3.6	V
GPIO auxiliary power supply for I/O bank x ²	V_{DDAUXx}	-0.5	3.6	V
Maximum DC input voltage on GPIO	V_{IN}	-0.5	3.8	V
Maximum DC input voltage on HSIO	V_{IN}	-0.5	2.2	V
Transceiver receiver absolute input voltage	Transceiver V_{IN}	-0.5	1.26	V
Transceiver reference clock absolute input voltage	Transceiver REFCLK V_{IN}	-0.5	3.6	V
Storage temperature (ambient) ¹	T_{STG}	-65	150	°C
Junction temperature ¹	T_J	-55	135	°C
Maximum soldering temperature RoHS	$T_{SOLROHS}$		260	°C

1. See FPGA Programming Cycles vs Retention Characteristics for retention time vs temperature. The total time used in calculating the device retention includes the device operating temperature time and temperature during storage time.
2. The power supplies for a given I/O bank x are shown as V_{DDIx} and V_{DDAUXx} .

4.2 Recommended Operating Conditions

The following table lists the recommended operating conditions.

Table 4-2. Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Condition
FPGA core supply at 1.0 V mode ^{1, 6}	V _{DD}	0.97	1.00	1.03	V	
FPGA core supply at 1.05 V mode ^{1, 6}	V _{DD}	1.02	1.05	1.08	V	
Transceiver TX and RX lanes supply (1.0 V mode) ^{6, 7}	V _{DDA}	0.97	1.00	1.03	V	When all lane rates are 10.3125 Gbps or less. ¹
Transceiver TX and RX lanes supply (1.05 V mode) ⁶	V _{DDA}	1.02	1.05	1.08	V	Must when any lane rate is greater than 10.3125 Gbps. Lane rates 10.3125 Gbps or less may also be powered in 1.05 V mode. ¹
Programming and HSIO receiver supply ⁶	V _{DD18}	1.71	1.80	1.89	V	
FPGA core and FPGA PLL high-voltage supply ⁶	V _{DD25}	2.425	2.50	2.575	V	
Transceiver PLL high-voltage supply ⁶	V _{DDA25}	2.425	2.50	2.575	V	
Transceiver reference clock supply ^{6, 7}	V _{DD_XCVR_CLK}	3.135	3.3	3.465	V	3.3 V nominal
		2.375	2.5	2.625	V	2.5 V nominal
Global V _{REF} for transceiver reference clocks ³	XCVR _{VREF}	Ground		V _{DD_XCVR_CLK}	V	
HSIO DC I/O supply ⁶	V _{DDIx}	1.14	Various	1.89	V	Allowed nominal options: 1.2 V, 1.35 V, 1.5 V, and 1.8 V ^{4, 5}
GPIO DC I/O supply ⁶	V _{DDIx}	1.14	Various	3.465	V	Allowed nominal options: 1.2 V, 1.5 V, 1.8 V, 2.5 V, and 3.3 V ^{2, 4, 5}
Dedicated I/O DC supply for JTAG and SPI (GPIO Bank 3) ⁶	V _{DDI3}	1.71	Various	3.465	V	Allowed nominal options: 1.8 V, 2.5 V, and 3.3 V
GPIO auxiliary supply ⁶	V _{DDAUXx}	3.135	3.3	3.465	V	For I/O bank x with V _{DDIx} = 3.3 V nominal ^{2, 4, 5}
		2.375	2.5	2.625	V	For I/O bank x with V _{DDIx} = 2.5 V nominal or lower ^{2, 4, 5}
Extended commercial temperature range	T _J	0		100	°C	
Industrial temperature range	T _J	−40		100	°C	
Automotive T2 temperature range	T _J	−40		125	°C	
Military temperature range	T _J	−55		125	°C	

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Extended commercial programming temperature range	T_{PRG}	0		100	°C	
Industrial programming temperature range	T_{PRG}	–40		100	°C	

1. V_{DD} and V_{DDA} can independently operate at 1.0 V or 1.05 V nominal. These supplies are not dynamically adjustable.
2. For GPIO buffers where I/O bank is designated as bank number, if V_{DDIx} is 2.5 V nominal or 3.3 V nominal, V_{DDAUXx} must be connected to the V_{DDIx} supply for that bank. If V_{DDIx} for a given GPIO bank is <2.5 V nominal, V_{DDAUXx} per I/O bank must be powered at 2.5 V nominal.
3. $XCVR_{VREF}$ globally sets the reference voltage of the transceiver's single-ended reference clock input buffers. It is typically near $V_{DD_XCVR_CLK}/2$ V but is allowed in the specified range.
4. The power supplies for a given I/O bank x are shown as V_{DDIx} and V_{DDAUXx} .
5. At power up and power down the V_{DDIx} and V_{DDAUXx} supply sequencing can cause signal glitches. Refer to UG0686: PolarFire FPGA I/O User Guide and UG0726: PolarFire FPGA Board Design User Guide for detailed explanation and recommended steps.
6. The recommended power supply tolerances include DC offset of the supply plus any power supply ripple over the customer design frequencies of interest, as measured at the device package pins. An example for a valid power supply that meets the recommendations for the V_{DD} supply is 1.0 V ± 10 mV or 1.05 V ± 10 mV for DC offset with an additional power supply ripple of ± 20 mV for a total of 1.0 V ± 30 mV or 1.05 V ± 30 mV.
7. Both V_{DDA} and $V_{DD_XCVR_CLK}$ supplies must be powered when any of the transceivers are used. $V_{DD_XCVR_CLK}$ must power on within the I/O calibration time (as specified for the device in Libero). V_{DDA} and $V_{DD_XCVR_CLK}$ must both then remain powered during operation. If V_{DDA} needs to be powered down, $V_{DD_XCVR_CLK}$ must also be powered down. There is no required sequence for powering up or down V_{DDA} and $V_{DD_XCVR_CLK}$.

4.2.1 DC Characteristics over Recommended Operating Conditions

The following table lists the DC characteristics over recommended operating conditions.

Table 4-3. DC Characteristics over Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit	Condition
Input pin capacitance ¹	C_{IN} (GPIO)		5.6	pf	
	Dedicated input pins				
	C_{IN} (HSIO)		2.8	pf	
Input or output leakage current per pin	I_L (GPIO)		10	μA	I/O disabled, high—Z
	I_L (HSIO)		10	μA	I/O disabled, high—Z
Pad pull-up when $V_{IN} = 0$	I_{PU}	137	220	μA	$V_{DDIx} = 3.3$ V
Pad pull-up when $V_{IN} = 0$		102	166	μA	$V_{DDIx} = 2.5$ V
Pad pull-up when $V_{IN} = 0$		68	115	μA	$V_{DDIx} = 1.8$ V
Pad pull-up when $V_{IN} = 0$		51	88	μA	$V_{DDIx} = 1.5$ V
Pad pull-up when $V_{IN} = 0$		29	73	μA	$V_{DDIx} = 1.35$ V
Pad pull-up when $V_{IN} = 0$		16	46	μA	$V_{DDIx} = 1.2$ V

.....continued

Parameter	Symbol	Min	Max	Unit	Condition
Pad pull-down when $V_{IN} = 3.3\text{ V}$ (GPIO only)	I_{PD}	65	187	μA	$V_{DDIX} = 3.3\text{ V}$
Pad pull-down when $V_{IN} = 2.5\text{ V}$ (GPIO only)		63	160	μA	$V_{DDIX} = 2.5\text{ V}$
Pad pull-down when $V_{IN} = 1.8\text{ V}$		60	117	μA	$V_{DDIX} = 1.8\text{ V}$
Pad pull-down when $V_{IN} = 1.5\text{ V}$		57	95	μA	$V_{DDIX} = 1.5\text{ V}$
Pad pull-down when $V_{IN} = 1.35\text{ V}$		52	86	μA	$V_{DDIX} = 1.35\text{ V}$
Pad pull-down when $V_{IN} = 1.2\text{ V}$		47	79	μA	$V_{DDIX} = 1.2\text{ V}$

1. Represents the die input capacitance at the pad (not the package).

Table 4-4. Minimum and Maximum Rise and Fall times

Parameter	Symbol	Min	Max	Unit	Maximum frequency	Condition
Input rise time ^{1,4}	T_{RISE}	200 ps ^{2,3}	10% signal period	ps	$F \leq 100\text{ KHz}$	Min (10% signal period, 1 μs) ⁵
Input fall time ^{1,4}	T_{FALL}		12.5% signal period	ps	$100\text{ KHz} < F \leq 400\text{ KHz}$	Min (12.5% signal period, 300 ns) ⁶
			20% signal period	ps	$400\text{ KHz} < F \leq 50\text{ MHz}$	Min (20% signal period, 50 ns) ⁷
			4	ns	$50\text{ MHz} < F \leq 125\text{ MHz}$	Not to exceed 4 ns ⁸
			50% signal period	ns	$125\text{ MHz} < F \leq 800\text{ MHz}$	Sawtooth waveform ⁹

1. Voltage ramp must be monotonic. For single-ended IO standards, input rise time is specified from 10%–90% of V_{DDIX} and input fall time is specified from 90%–10% of V_{DDIX} . For voltage referenced and differential IO configurations, ramp times must always comply with I/O standard requirements to ensure compliance.
2. Input slew rates must be controlled to never exceed PAD overshoot/undershoot requirements. Input pad overshoot and undershoot specifications are shown in section Maximum Allowed Overshoot and Undershoot.
3. Rise and fall times in this table are for unterminated inputs. When inputs are terminated, minimum ramp time is not restricted. Recommended minimum ramp time is 25% of bit period, not to exceed a rate of 5 V/ns.
4. Ramp times must not exceed I/O standard requirements to ensure compliance.
5. For signal frequencies $< 100\text{ KHz}$, maximum rise time is 1 μs . For example, if signal frequency (F) is 100 KHz, 10% of signal period is 1 μs . The maximum ramp time allowed is the 1 μs limit. However, if signal frequency is 10 KHz, then 10% of signal period is 10 μs which exceeds the maximum limit of 1 μs . The maximum ramp time allowed is therefore 1 μs .
6. For $100\text{ KHz} < \text{signal frequencies} \leq 400\text{ KHz}$, maximum rise time is 300 ns. For example, if signal frequency is 400 KHz, then 12.5% of signal period is 312.5 ns. The maximum ramp time allowed is 300 ns. If the signal

frequency is 200 KHz, then 12.5% of signal period is 625 ns. The maximum ramp time allowed is therefore 300 ns.

7. For 400 KHz < signal frequencies $\leq$ 50 MHz, maximum rise time is 50 ns or 20% of signal period, whichever is less. For example, if signal frequency is 50 MHz, then 20% of signal period is 4 ns. The maximum ramp time allowed is therefore 4 ns, even if the max limit is 50 ns. If the signal frequency is 1 MHz, then 20% of signal period is 200 ns. The maximum ramp time allowed is therefore 50 ns.
8. For 50 MHz < signal frequencies $\leq$ 125 MHz, maximum rise time is 4 ns. For example, if signal frequency is 125 MHz, then the maximum ramp time allowed is 4 ns (sawtooth signal). If the signal frequency is 75 MHz, the maximum ramp time allowed at 75 MHz is still 4 ns.
9. For 125 MHz < signal frequencies $\leq$ 800 MHz, maximum rise time is 50% of signal frequency (sawtooth signal). For example, if signal frequency is 250 MHz, then the maximum ramp time allowed is 2 ns. If the signal frequency is 800 MHz, the maximum ramp time allowed is 0.625 ns.

4.2.2 Maximum Allowed Overshoot and Undershoot

During transitions, input signals may overshoot and undershoot the voltage listed as follows. Input currents must be limited to less than 100 mA per latch-up specifications.

The maximum overshoot duration is specified as a high-time percentage over the lifetime of the device. A DC signal is equivalent to 100% of the duty-cycle.

The following tables list the maximum AC input voltage (V_{IN}) overshoot duration for HSIO.

Table 4-5. Maximum Overshoot During Transitions for HSIO at $T_J = 100^\circ\text{C}$

AC (V_{IN}) Overshoot Duration as % at $T_J = 100^\circ\text{C}$	Condition (V)
100	1.8
100	1.85
100	1.9
100	1.95
100	2
100	2.05
100	2.1
100	2.15
100	2.2
90	2.25
30	2.3
7.5	2.35
1.9	2.4

Note: Overshoot level is for VDDI at 1.8 V.

Table 4-6. Maximum Overshoot During Transitions for HSIO at $T_J = 125^\circ\text{C}$

AC (V_{IN}) Overshoot Duration as % at $T_J = 125^\circ\text{C}$	Condition (V)
100	1.8
100	1.85

.....continued

AC (V_{IN}) Overshoot Duration as % at $T_J = 125\text{ }^{\circ}\text{C}$	Condition (V)
100	1.9
100	1.95
100	2
100	2.05
100	2.1
100	2.15
100	2.2
35	2.25
8	2.3
2	2.35
0.5	2.4

Note: Overshoot level is for VDDI at 1.8 V.

The following table lists the maximum AC input voltage (V_{IN}) undershoot duration for HSIO.

Table 4-7. Maximum Undershoot During Transitions for HSIO at $T_J = 100\text{ }^{\circ}\text{C}$

AC (V_{IN}) Undershoot Duration as % at $T_J = 100\text{ }^{\circ}\text{C}$	Condition (V)
100	-0.05
100	-0.1
100	-0.15
100	-0.2
100	-0.25
100	-0.3
100	-0.35
100	-0.4
44	-0.45
14	-0.5
4.8	-0.55
1.6	-0.6

Table 4-8. Maximum Undershoot During Transitions for HSIO at $T_J = 125\text{ }^{\circ}\text{C}$

AC (V_{IN}) Undershoot Duration as % at $T_J = 125\text{ }^{\circ}\text{C}$	Condition (V)
100	-0.05
100	-0.1
100	-0.15

.....continued

AC (V_{IN}) Undershoot Duration as % at $T_J = 125\text{ }^{\circ}\text{C}$	Condition (V)
100	-0.2
100	-0.25
100	-0.3
86	-0.35
26	-0.4
8	-0.45
2.6	-0.5
0.8	-0.55
0.3	-0.6

The following table lists the maximum AC input voltage (V_{IN}) overshoot duration for GPIO.

Table 4-9. Maximum Overshoot During Transitions for GPIO at $T_J = 100\text{ }^{\circ}\text{C}$

AC (V_{IN}) Overshoot Duration as % at $T_J = 100\text{ }^{\circ}\text{C}$	Condition (V)
100	3.8
100	3.85
100	3.9
100	3.95
70	4
50	4.05
33	4.1
22	4.15
14	4.2
9.8	4.25
6.5	4.3
4.4	4.35
3	4.4
2	4.45
1.4	4.5
0.9	4.55
0.6	4.6

Note: Overshoot level is for V_{DDI} at 3.3 V.

Table 4-10. Maximum Overshoot During Transitions for GPIO at $T_J = 125\text{ }^{\circ}\text{C}$

AC (V_{IN}) Overshoot Duration as % at $T_J = 125\text{ }^{\circ}\text{C}$	Condition (V)
100	3.8
84	3.85
54	3.9
35	3.95
23	4
15	4.05
10	4.1
6.6	4.15
4.4	4.2
2.9	4.25
1.9	4.3
1.3	4.35
0.9	4.4
0.6	4.45
0.4	4.5
0.28	4.55
0.19	4.6

Note: Overshoot level is V_{DDI} at 3.3 V.

The following table lists the maximum AC input voltage (V_{IN}) undershoot duration for GPIO.

Table 4-11. Maximum Undershoot During Transitions for GPIO at $T_J = 100\text{ }^{\circ}\text{C}$

AC (V_{IN}) Undershoot Duration as % at $T_J = 100\text{ }^{\circ}\text{C}$	Condition (V)
100	-0.5
100	-0.55
100	-0.6
100	-0.65
100	-0.7
100	-0.75
100	-0.8
100	-0.85
100	-0.9
100	-0.95
100	-1

.....continued	
AC (V_{IN}) Undershoot Duration as % at $T_J = 100\text{ }^{\circ}\text{C}$	Condition (V)
100	-1.05
100	-1.1
100	-1.15
100	-1.2
69	-1.25
45	-1.3

Table 4-12. Maximum Undershoot During Transitions for GPIO at $T_J = 125\text{ }^{\circ}\text{C}$

AC (V_{IN}) Undershoot Duration as % at $T_J = 125\text{ }^{\circ}\text{C}$	Condition (V)
100	-0.5
100	-0.55
100	-0.6
100	-0.65
100	-0.7
100	-0.75
100	-0.8
100	-0.85
100	-0.9
100	-0.95
100	-1
100	-1.05
78	-1.1
50	-1.15
32	-1.2
20	-1.25
13	-1.3

4.2.2.1 Power Supply Ramp Times

The following table lists the allowable power-up ramp times. Times shown correspond to the ramp of the supply from 0 V to the minimum recommended voltage as specified in the section Recommended Operating Conditions. All supplies must rise and fall monotonically.

Table 4-13. Power Supply Ramp Times

Parameter	Symbol	Min	Max	Unit
FPGA core supply	V_{DD}	0.2	50	ms
Transceiver core supply	V_{DDA}	0.2	50	ms

.....continued

Parameter	Symbol	Min	Max	Unit
Must connect to 1.8 V supply	V_{DD18}	0.2	50	ms
Must connect to 2.5 V supply	V_{DD25}	0.2	50	ms
Must connect to 2.5 V supply	V_{DDA25}	0.2	50	ms
HSIO bank I/O power supplies	$V_{DDI[0,1,6,7]}$	0.2	50	ms
GPIO bank I/O power supplies	$V_{DDI[2,4,5]}$	0.2	50	ms
Bank 3 dedicated I/O buffers (GPIO)	V_{DDI3}	0.2	50	ms
GPIO bank auxiliary power supplies	$V_{DDAUX[2,4,5]}$	0.2	50	ms
Transceiver reference clock supply	$V_{DD_XCVR_CLK}$	0.2	50	ms
Global V_{REF} for transceiver reference clocks	$XCVR_{VREF}$	0.2	50	ms

Note: For proper operation of programming recovery mode, if a VDD supply brownout occurs during programming, a minimum supply ramp down time for only the VDD supply is recommended to be 10 ms or longer by using a programmable regulator or on-board capacitors.

4.2.2.2 Hot Socketing

The following table lists the hot socketing DC characteristics over recommended operating conditions.

Table 4-14. Hot Socketing DC Characteristics over Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Current per transceiver Rx input pin (P or N single-ended) ^{1, 2}	$XCVR_{RX_HS}$			± 4	mA	$V_{DDA} = 0\text{ V}$
Current per transceiver Tx output pin (P or N single-ended) ³	$XCVR_{TX_HS}$			± 10	mA	$V_{DDA} = 0\text{ V}$
Current per transceiver reference clock input pin (P or N single-ended) ⁴	$XCVR_{REF_HS}$			± 1	mA	$V_{DD_XCVR_CLK} = 0\text{ V}$
Current per GPIO pin (P or N single-ended) ⁵	I_{GPIO_HS}			± 1	mA	$V_{DDIx} = 0\text{ V}$
Current per HSIO pin (P or N single-ended)						Hot socketing is not supported in HSIO.

1. Assumes device is powered-down, all supplies are grounded, AC-coupled interface, and input pin pairs are driven by a CML driver at the maximum amplitude (1 V pk-pk) that is toggling at any rate with PRBS7 data.
2. Each P and N transceiver input has less than the specified maximum input current.
3. Each P and N transceiver output is connected to a 40 Ω resistor (50 Ω CML termination—20% tolerance) to the maximum allowed output voltage ($V_{DDAmax} + 0.3\text{ V} = 1.4\text{ V}$) through an AC-coupling capacitor with all PolarFire device supplies grounded. This shows the current for a worst-case DC coupled interface. As an AC-coupled interface, the output signal will settle at ground and no hot socket current will be seen.
4. $V_{DD_XCVR_CLK}$ is powered down and the device is driven to $-0.3\text{ V} < V_{IN} < V_{DD_XCVR_CLK}$.
5. V_{DDIx} is powered down and the device is driven to $-0.3\text{ V} < V_{IN} < \text{GPIO } V_{DDImax}$.

Note: The following dedicated pins do not support hot socketing: TMS, TDI, TRSTB, and DEVRST_N. Weak pull-up (as specified in GPIO) is always enabled.

4.3 Input and Output

The following section describes DC I/O levels, differential and complementary differential DC I/O levels, HSIO and GPIO on-die termination specifications, and LVDS specifications.

4.3.1 DC Input and Output Levels

The following tables list the DC I/O levels.

Table 4-15. DC Input Levels

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{IL} Min (V)	V _{IL} Max (V)	V _{IH} Min (V)	V _{IH} ¹ Max (V)
PCI	3.15	3.3	3.45	−0.3	$0.3 \times V_{DDI}$	$0.5 \times V_{DDI}$	3.45
LVTTL	3.15	3.3	3.45	−0.3	0.8	2	3.45
LVC MOS33	3.15	3.3	3.45	−0.3	0.8	2	3.45
LVC MOS25	2.375	2.5	2.625	−0.3	0.7	1.7	2.625
LVC MOS18	1.71	1.8	1.89	−0.3	$0.35 \times V_{DDI}$	$0.65 \times V_{DDI}$	1.89
LVC MOS15	1.425	1.5	1.575	−0.3	$0.35 \times V_{DDI}$	$0.65 \times V_{DDI}$	1.575
LVC MOS12	1.14	1.2	1.26	−0.3	$0.35 \times V_{DDI}$	$0.65 \times V_{DDI}$	1.26
SSTL25I ²	2.375	2.5	2.625	−0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	2.625
SSTL25II ²	2.375	2.5	2.625	−0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	2.625
SSTL18I ²	1.71	1.8	1.89	−0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	1.89
SSTL18II ²	1.71	1.8	1.89	−0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	1.89
SSTL15I	1.425	1.5	1.575	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575
SSTL15II	1.425	1.5	1.575	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575
SSTL135I	1.283	1.35	1.418	−0.3	$V_{REF} - 0.09$	$V_{REF} + 0.09$	1.418
SSTL135II	1.283	1.35	1.418	−0.3	$V_{REF} - 0.09$	$V_{REF} + 0.09$	1.418
HSTL15I	1.425	1.5	1.575	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575
HSTL15II	1.425	1.5	1.575	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.575
HSTL135I	1.283	1.35	1.418	−0.3	$V_{REF} - 0.09$	$V_{REF} + 0.09$	1.418
HSTL135II	1.283	1.35	1.418	−0.3	$V_{REF} - 0.09$	$V_{REF} + 0.09$	1.418
HSTL12I	1.14	1.2	1.26	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.26
HSTL12II	1.14	1.2	1.26	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.26
HSUL18I	1.71	1.8	1.89	−0.3	$0.3 \times V_{DDI}$	$0.7 \times V_{DDI}$	1.89
HSUL18II	1.71	1.8	1.89	−0.3	$0.3 \times V_{DDI}$	$0.7 \times V_{DDI}$	1.89
HSUL12I	1.14	1.2	1.26	−0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	1.26

.....continued

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{IL} Min (V)	V _{IL} Max (V)	V _{IH} Min (V)	V _{IH} ¹ Max (V)
POD12I	1.14	1.2	1.26	-0.3	V _{REF} - 0.08	V _{REF} + 0.08	1.26
POD12II	1.14	1.2	1.26	-0.3	V _{REF} - 0.08	V _{REF} + 0.08	1.26

1. GPIO V_{IH} max is 3.45 V with PCI clamp diode turned off regardless of mode, that is, over-voltage tolerant.
2. For external stub-series resistance. This resistance is on-die for GPIO.
3. PolarFire FPGA inputs are designed to support mixing assignment for certain I/O standards, allowing I/O using compatible standards to be placed in the same I/O bank. Refer to the description of the mixed IO receiver capability in [UG0686: PolarFire FPGA User I/O User Guide](#).

Note: 3.3 V and 2.5 V are only supported in GPIO banks.

Table 4-16. DC Output Levels

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{OL} Max (V)	V _{OH} Min (V)	I _{OL} ^{2,6} mA	I _{OH} ^{2,6} mA
PCI ¹	3.15	3.3	3.45	0.1 × V _{DDI}	0.9 × V _{DDI}	1.5	0.5
LVTTTL	3.15	3.3	3.45	0.4	2.4	Refer to note 2	
LVC MOS33	3.15	3.3	3.45	0.4	V _{DDI} - 0.4		
LVC MOS25	2.375	2.5	2.625	0.4	V _{DDI} - 0.4		
LVC MOS18	1.71	1.8	1.89	0.45	V _{DDI} - 0.45		
LVC MOS15	1.425	1.5	1.575	0.25 × V _{DDI}	0.75 × V _{DDI}		
LVC MOS12	1.14	1.2	1.26	0.25 × V _{DDI}	0.75 × V _{DDI}		
SSTL25I ³	2.375	2.5	2.625	V _{TT} - 0.608	V _{TT} + 0.608	8.1	8.1
SSTL25II ³	2.375	2.5	2.625	V _{TT} - 0.810	V _{TT} + 0.810	16.2	16.2
SSTL18I ³	1.71	1.8	1.89	V _{TT} - 0.603	V _{TT} + 0.603	6.7	6.7
SSTL18II ³	1.71	1.8	1.89	V _{TT} - 0.603	V _{TT} + 0.603	13.4	13.4
SSTL15I ⁴	1.425	1.5	1.575	0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /40	(V _{DDI} - V _{OH})/40
SSTL15II ⁴	1.425	1.5	1.575	0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /34	(V _{DDI} - V _{OH})/34
SSTL135I ⁴	1.283	1.35	1.418	0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /40	(V _{DDI} - V _{OH})/40
SSTL135II ⁴	1.283	1.35	1.418	0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /34	(V _{DDI} - V _{OH})/34
HSTL15I	1.425	1.5	1.575	0.4	V _{DDI} - 0.4	8	8
HSTL15II	1.425	1.5	1.575	0.4	V _{DDI} - 0.4	16	16
HSTL135I ⁴	1.283	1.35	1.418	0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /50	(V _{DDI} - V _{OH})/50
HSTL135II ⁴	1.283	1.35	1.418	0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /25	(V _{DDI} - V _{OH})/25
HSTL12I ⁴	1.14	1.2	1.26	0.1 × V _{DDI}	0.9 × V _{DDI}	V _{OL} /50	(V _{DDI} - V _{OH})/50

.....continued

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{OL} Max (V)	V _{OH} Min (V)	I _{OL} ^{2,6} mA	I _{OH} ^{2,6} mA
HSTL12II ⁴	1.14	1.2	1.26	$0.1 \times V_{DDI}$	$0.9 \times V_{DDI}$	$V_{OL}/25$	$(V_{DDI} - V_{OH})/25$
HSUL18I ⁴	1.71	1.8	1.89	$0.1 \times V_{DDI}$	$0.9 \times V_{DDI}$	$V_{OL}/55$	$(V_{DDI} - V_{OH})/55$
HSUL18II ⁴	1.71	1.8	1.89	$0.1 \times V_{DDI}$	$0.9 \times V_{DDI}$	$V_{OL}/25$	$(V_{DDI} - V_{OH})/25$
HSUL12I ⁴	1.14	1.2	1.26	$0.1 \times V_{DDI}$	$0.9 \times V_{DDI}$	$V_{OL}/40$	$(V_{DDI} - V_{OH})/40$
POD12I ^{4,5}	1.14	1.2	1.26	$0.5 \times V_{DDI}$		$V_{OL}/48$	$(V_{DDI} - V_{OH})/48$
POD12II ^{4,5}	1.14	1.2	1.26	$0.5 \times V_{DDI}$		$V_{OL}/34$	$(V_{DDI} - V_{OH})/34$

1. Drive strengths per PCI specification V/I curves.
2. Refer to UG0686: PolarFire FPGA User I/O User Guide for details on supported drive strengths.
3. For external stub-series resistance. This resistance is on-die for GPIO.
4. I_{OL}/I_{OH} units for impedance standards in amps (not mA).
5. V_{OH_MAX} based on external pull-up termination (pseudo-open drain).
6. The total DC sink/source current of all IOs within a lane is limited as follows:
 - 6.1. HSIO lane: 120 mA per 12 IO buffers.
 - 6.2. GPIO lane: 160 mA per 12 IO buffers.

Note: 3.3 V and 2.5 V are only supported in GPIO banks.

4.3.2 Differential DC Input and Output Levels

The follow tables list the differential DC I/O levels.

Table 4-17. Differential DC Input Levels

I/O Standard	Bank Type	VICM_RANGE Libero Setting	V _{ICM} ^{1,3} Min (V)	V _{ICM} ^{1,3} Typ (V)	V _{ICM} ^{1,3} Max (V)	V _{ID} ² Min (V)	V _{ID} Typ (V)	V _{ID} Max (V)
LVDS33	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.35	0.6
		Low	0.05	0.4	0.8	0.1	0.35	0.6
LVDS25 ⁷	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.35	0.6
		Low	0.05	0.4	0.8	0.1	0.35	0.6
LVDS18 ⁴	GPIO	Mid (default)	0.6	1.25	1.65	0.1	0.35	0.6
		Low	0.05	0.4	0.8	0.1	0.35	0.6
LVDS18 ⁷	HSIO	Mid (default)	0.6	1.25	1.65	0.1	0.35	0.6
		Low	0.05	0.4	0.8	0.1	0.35	0.6
LCMDS33	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.35	0.6
		Low	0.05	0.4	0.8	0.1	0.35	0.6
LCMDS18	HSIO	Mid (default)	0.6	1.25	1.65	0.1	0.35	0.6
		Low	0.05	0.4	0.8	0.1	0.35	0.6

DC Characteristics

.....continued

I/O Standard	Bank Type	VICM_RANGE Libero Setting	V _{ICM} ^{1,3} Min (V)	V _{ICM} ^{1,3} Typ (V)	V _{ICM} ^{1,3} Max (V)	V _{ID} ² Min (V)	V _{ID} Typ (V)	V _{ID} Max (V)
LCMDS25	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.35	0.6
		Low	0.05	0.4	0.8	0.1	0.35	0.6
RSDS33	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.2	0.6
		Low	0.05	0.4	0.8	0.1	0.2	0.6
RSDS25	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.2	0.6
		Low	0.05	0.4	0.8	0.1	0.2	0.6
RSDS18 ⁵	HSIO	Mid (default)	0.6	1.25	1.65	0.1	0.2	0.6
		Low	0.05	0.4	0.8	0.1	0.2	0.6
MINILVDS33	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.3	0.6
		Low	0.05	0.4	0.8	0.1	0.3	0.6
MINILVDS25	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.3	0.6
		Low	0.05	0.4	0.8	0.1	0.3	0.6
MINILVDS18 ⁵	HSIO	Mid (default)	0.6	1.25	1.65	0.1	0.3	0.6
		Low	0.05	0.4	0.8	0.1	0.3	0.6
SUBLVDS33	GPIO	Mid (default)	0.6	0.9	2.35	0.1	0.15	0.3
		Low	0.05	0.4	0.8	0.1	0.15	0.3
SUBLVDS25	GPIO	Mid (default)	0.6	0.9	2.35	0.1	0.15	0.3
		Low	0.05	0.4	0.8	0.1	0.15	0.3
SUBLVDS18 ⁵	HSIO	Mid (default)	0.6	0.9	1.65	0.1	0.15	0.3
		Low	0.05	0.4	0.8	0.1	0.15	0.3
PPDS33	GPIO	Mid (default)	0.6	0.8	2.35	0.1	0.2	0.6
		Low	0.05	0.4	0.8	0.1	0.2	0.6
PPDS25	GPIO	Mid (default)	0.6	0.8	2.35	0.1	0.2	0.6
		Low	0.05	0.4	0.8	0.1	0.2	0.6
PPDS18 ⁵	HSIO	Mid (default)	0.6	0.8	1.65	0.1	0.2	0.6
		Low	0.05	0.4	0.8	0.1	0.2	0.6
SLVS33 ⁶	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.2	0.3
		Low	0.05	0.2	0.8	0.1	0.2	0.3
SLVS25 ⁶	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.2	0.3
		Low	0.05	0.2	0.8	0.1	0.2	0.3

.....continued

I/O Standard	Bank Type	VICM_RANGE Libero Setting	V _{ICM} ^{1,3} Min (V)	V _{ICM} ^{1,3} Typ (V)	V _{ICM} ^{1,3} Max (V)	V _{ID} ² Min (V)	V _{ID} Typ (V)	V _{ID} Max (V)
SLVS18 ⁵	HSIO	Mid (default)	0.6	1.00	1.65	0.1	0.2	0.3
		Low	0.05	0.4	0.8	0.1	0.2	0.3
HCSL33 ⁶	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.55	1.1
		Low	0.05	0.35	0.8	0.1	0.55	1.1
HCSL25 ⁶	GPIO	Mid (default)	0.6	1.25	2.35	0.1	0.55	1.1
		Low	0.05	0.35	0.8	0.1	0.55	1.1
HCSL18 ⁵	HSIO	Mid (default)	0.6	1.0	1.65	0.1	0.55	1.1
		Low	0.05	0.4	0.8	0.1	0.55	1.1
BUSLVDSE25	GPIO	Mid (default)	0.6	1.25	2.35	0.05	0.1	V _{DDIn}
		Low	0.05	0.4	0.8	0.05	0.1	V _{DDIn}
MLVDSE25	GPIO	Mid (default)	0.6	1.25	2.35	0.05	0.35	2.4
		Low	0.05	0.4	0.8	0.05	0.35	2.4
LVPECL33	GPIO	Mid (default)	0.6	1.65	2.35	0.05	0.8	2.4
		Low	0.05	0.4	0.8	0.05	0.8	2.4
LVPECLE33	GPIO	Mid (default)	0.6	1.65	2.35	0.05	0.8	2.4
		Low	0.05	0.4	0.8	0.05	0.8	2.4
MIPI25	GPIO	Mid (default)	0.6	1.25	2.35	0.05	0.2	0.3
		Low	0.05	0.2	0.8	0.05	0.2	0.3

1. V_{ICM} is the input common mode.
2. V_{ID} is the input differential voltage.
3. V_{ICM} rules are as follows:
 - 3.1. GPIO V_{ICM} must be less than V_{DDI} – 0.4 V;
 - 3.2. HSIO V_{ICM} must be less than V_{DDI} – 0.24 V;
 - 3.3. V_{ICM} + V_{ID}/2 must be <V_{DDI} + 0.4 V;
 - 3.4. V_{ICM} – V_{ID}/2 must be >VSS – 0.3 V;
 - 3.5. Any differential input with V_{ICM} ≤ 0.6 V requires the low common mode setting in Libero (VICM_RANGE=LOW).
4. VDDI = 1.8 V, VDDAUX = 2.5 V.
5. HSIO receiver only.
6. GPIO receiver only.
7. LVDS25 (GPIO) and LVDS18 (HSIO) configurations should be used in conjunction with I/O CDR when implementing SGMII receivers.

Table 4-18. Differential DC Output Levels

I/O Standard	Bank Type	V _{OCM} ¹ Min (V)	V _{OCM} Typ (V)	V _{OCM} Max (V)	V _{OD} ² Min (V)	V _{OD} ² Typ (V)	V _{OD} ² Max (V)
LVDS33	GPIO	1.125	1.2	1.375	0.25	0.35	0.45
LVDS25 ⁴	GPIO	1.125	1.2	1.375	0.25	0.35	0.45
LCMDS33	GPIO	0.45	0.6	0.7	0.25	0.35	0.45
LCMDS25	GPIO	0.45	0.6	0.7	0.25	0.35	0.45
RSDS33	GPIO	1.125	1.2	1.375	0.17	0.2	0.23
RSDS25	GPIO	1.125	1.2	1.375	0.17	0.2	0.23
MINILVDS33	GPIO	1.125	1.2	2.375	0.3	0.4	0.6
MINILVDS25	GPIO	1.125	1.2	2.375	0.3	0.4	0.6
SUBLVDS33	GPIO	0.8	0.9	1.0	0.1	0.15	0.3
SUBLVDS25	GPIO	0.8	0.9	1.0	0.1	0.15	0.3
PPDS33	GPIO	0.05	0.8	1.4	0.17	0.2	0.23
PPDS25	GPIO	0.05	0.8	1.4	0.17	0.2	0.23
SLVSE15 ³	GPIO, HSIO	0.1	0.2	0.3	0.12	0.135	0.15
BUSLVDSE25 ³	GPIO	1.15	1.25	1.31	0.24	0.262	0.272
MLVDSE25 ³	GPIO	1.15	1.25	1.31	0.396	0.442	0.453
LVPECLE33 ³	GPIO	1.51	1.65	1.74	0.664	0.722	0.755
MIPIE25 ³	GPIO	0.15	0.2	0.25	0.14	0.2	0.27

1. V_{OCM} is the output common mode voltage.
2. V_{OD} is the output differential voltage.
3. Emulated output only, using external resistors.
4. LVDS25 configuration should be used when implementing SGMII transmitters.

4.3.3 Complementary Differential DC Input and Output Levels

The following tables list the complementary differential DC I/O levels.

Table 4-19. Complementary Differential DC Input Levels

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{ICM} ^{1,3} Min (V)	V _{ICM} ^{1,3} Typ (V)	V _{ICM} ^{1,3} Max (V)	V _{ID} ² Min (V)	V _{ID} ² Max (V)
SSTL25I	2.375	2.5	2.625	1.164	1.250	1.339	0.1	V _{DDAUX} (GPIO)
SSTL25II	2.375	2.5	2.625	1.164	1.250	1.339	0.1	V _{DDAUX} (GPIO)
SSTL18I	1.71	1.8	1.89	0.838	0.900	0.964	0.1	V _{DDAUX} (GPIO) V _{DDI} (HSIO)
SSTL18II	1.71	1.8	1.89	0.838	0.900	0.964	0.1	V _{DDAUX} (GPIO) V _{DDI} (HSIO)
SSTL15I	1.425	1.5	1.575	0.698	0.750	0.803	0.1	V _{DDAUX} (GPIO) V _{DDI} (HSIO)

.....continued

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{ICM} ^{1,3} Min (V)	V _{ICM} ^{1,3} Typ (V)	V _{ICM} ^{1,3} Max (V)	V _{ID} ² Min (V)	V _{ID} ² Max (V)
SSTL15II	1.425	1.5	1.575	0.698	0.750	0.803	0.1	V _{DDAUX} (GPIO) V _{DDI} (HSIO)
SSTL135I	1.283	1.35	1.418	0.629	0.675	0.723	0.1	V _{DDI} (HSIO)
SSTL135II	1.283	1.35	1.418	0.629	0.675	0.723	0.1	V _{DDI} (HSIO)
HSTL15I	1.425	1.5	1.575	0.698	0.750	0.803	0.1	V _{DDAUX} (GPIO) V _{DDI} (HSIO)
HSTL15II	1.425	1.5	1.575	0.698	0.750	0.803	0.1	V _{DDAUX} (GPIO) V _{DDI} (HSIO)
HSTL135I	1.283	1.35	1.418	0.629	0.675	0.723	0.1	V _{DDI} (HSIO)
HSTL135II	1.283	1.35	1.418	0.629	0.675	0.723	0.1	V _{DDI} (HSIO)
HSTL12I	1.14	1.2	1.26	0.559	0.600	0.643	0.1	V _{DDI} (HSIO)
HSTL12II	1.14	1.2	1.26	0.559	0.600	0.643	0.1	V _{DDI} (HSIO)
HSUL18I	1.71	1.8	1.89	0.838	0.900	0.964	0.1	V _{DDI} (HSIO)
HSUL18II	1.71	1.8	1.89	0.838	0.900	0.964	0.1	V _{DDI} (HSIO)
HSUL12I	1.14	1.2	1.26	0.559	0.600	0.643	0.1	V _{DDI} (HSIO)
POD12I	1.14	1.2	1.26	0.787	0.840	0.895	0.1	V _{DDI} (HSIO)
POD12II	1.14	1.2	1.26	0.787	0.840	0.895	0.1	V _{DDI} (HSIO)

1. V_{ICM} is the input common mode voltage.
2. V_{ID} is the input differential voltage.
3. V_{ICM} rules are as follows:
 - 3.1. V_{ICM} must be less than V_{DDI} – 0.4 V;
 - 3.2. V_{ICM} + V_{ID}/2 must be <V_{DDI} + 0.4 V;
 - 3.3. V_{ICM} – V_{ID}/2 must be >VSS – 0.3 V.

Table 4-20. Complementary Differential DC Output Levels

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{OL} Min (V)	V _{OL} Max (V)	V _{OH} ^{1,3} Min (V)	I _{OL} ² Min (mA)	I _{OH} ² Min (mA)
SSTL25I	2.375	2.5	2.625		V _{TT} – 0.608	V _{TT} + 0.608	8.1	8.1
SSTL25II	2.375	2.5	2.625		V _{TT} – 0.810	V _{TT} + 0.810	16.2	16.2
SSTL18I	1.71	1.8	1.89		V _{TT} – 0.603	V _{TT} + 0.603	6.7	6.7
SSTL18II	1.71	1.8	1.89		V _{TT} – 0.603	V _{TT} + 0.603	13.4	13.4
SSTL15I ⁴	1.425	1.5	1.575		0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /40	(V _{DDI} – V _{OH})/40
SSTL15II ⁴	1.425	1.5	1.575		0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /34	(V _{DDI} – V _{OH})/34
SSTL135I ⁴	1.283	1.35	1.418		0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /40	(V _{DDI} – V _{OH})/40
SSTL135II ⁴	1.283	1.35	1.418		0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /34	(V _{DDI} – V _{OH})/34

.....continued

I/O Standard	V _{DDI} Min (V)	V _{DDI} Typ (V)	V _{DDI} Max (V)	V _{OL} Min (V)	V _{OL} Max (V)	V _{OH} ^{1,3} Min (V)	I _{OL} ² Min (mA)	I _{OH} ² Min (mA)
HSTL15I	1.425	1.5	1.575		0.4	V _{DDI} – 0.4	8	8
HSTL15II	1.425	1.5	1.575		0.4	V _{DDI} – 0.4	16	16
HSTL135I ⁴	1.283	1.35	1.418		0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /50	(V _{DDI} – V _{OH})/50
HSTL135II ⁴	1.283	1.35	1.418		0.2 × V _{DDI}	0.8 × V _{DDI}	V _{OL} /25	(V _{DDI} – V _{OH})/25
HSTL12I ⁴	1.14	1.2	1.26		0.1 × V _{DDI}	0.9 × V _{DDI}	V _{OL} /50	(V _{DDI} – V _{OH})/50
HSTL12II ⁴	1.14	1.2	1.26		0.1 × V _{DDI}	0.9 × V _{DDI}	V _{OL} /25	(V _{DDI} – V _{OH})/25
HSUL18I ⁴	1.71	1.8	1.89		0.1 × V _{DDI}	0.9 × V _{DDI}	V _{OL} /55	(V _{DDI} – V _{OH})/55
HSUL18II ⁴	1.71	1.8	1.89		0.1 × V _{DDI}	0.9 × V _{DDI}	V _{OL} /25	(V _{DDI} – V _{OH})/25
HSUL12I ⁴	1.14	1.2	1.26		0.1 × V _{DDI}	0.9 × V _{DDI}	V _{OL} /40	(V _{DDI} – V _{OH})/40
POD12I ^{3,4}	1.14	1.2	1.26		0.5 × V _{DDI}		V _{OL} /48	(V _{DDI} – V _{OH})/48
POD12II ^{3,4}	1.14	1.2	1.26		0.5 × V _{DDI}		V _{OL} /34	(V _{DDI} – V _{OH})/34

1. V_{OH} is the single-ended high-output voltage.
2. The total DC sink/source current of all I/Os within a lane is limited as follows:
 - 2.1. HSIO lane: 120 mA per 12 I/O buffers.
 - 2.2. GPIO lane: 160 mA per 12 I/O buffers.
3. V_{OH_MAX} is based on external pull-up termination (pseudo-open drain).
4. I_{OL}/I_{OH} units for impedance standards are in amps (not mA).

4.3.4 HSIO On-Die Termination

The following tables list the on-die termination calibration accuracy specifications for the HSIO bank.

Table 4-21. Single-Ended (Internal Parallel) Thevenin Termination

Min (%)	Typ	Max (%)	Unit	Condition
–40	50	20	Ω	V _{DDI} = 1.8 V/1.5 V/1.35 V/1.2 V
–40	75	20	Ω	V _{DDI} = 1.8 V
–40	150	20	Ω	V _{DDI} = 1.8 V
–20	20	20	Ω	V _{DDI} = 1.5 V/1.35 V
–20	30	20	Ω	V _{DDI} = 1.5 V/1.35 V
–20	40	20	Ω	V _{DDI} = 1.5 V/1.35 V
–20	60	20	Ω	V _{DDI} = 1.5 V/1.35 V
–20	120	20	Ω	V _{DDI} = 1.5 V/1.35 V
–20	60	20	Ω	V _{DDI} = 1.2 V
–20	120	20	Ω	V _{DDI} = 1.2 V

Note: Thevenin impedance is calculated based on independent P and N as measured at 50% of V_{DDI} . For 50 Ω /75 Ω /150 Ω cases, the nearest supported values of 40 Ω /60 Ω /120 Ω are used.

Table 4-22. Single-Ended (Internal Parallel) Termination to VDDI

Min (%)	Typ	Max (%)	Unit	Condition
-20	34	20	Ω	$V_{DDI} = 1.2 \text{ V}$
-20	40	20	Ω	$V_{DDI} = 1.2 \text{ V}$
-20	48	20	Ω	$V_{DDI} = 1.2 \text{ V}$
-20	60	20	Ω	$V_{DDI} = 1.2 \text{ V}$
-20	80	20	Ω	$V_{DDI} = 1.2 \text{ V}$
-20	120	20	Ω	$V_{DDI} = 1.2 \text{ V}$
-20	240	20	Ω	$V_{DDI} = 1.2 \text{ V}$

Note: Measured at 80% of V_{DDI} .

Table 4-23. Single-Ended (Internal Parallel) Termination to VSS

Min (%)	Typ	Max (%)	Unit	Condition
-20	120	20	Ω	$V_{DDI} = 1.8 \text{ V}/1.5 \text{ V}$
-20	240	20	Ω	$V_{DDI} = 1.8 \text{ V}/1.5 \text{ V}$
-20	120	20	Ω	$V_{DDI} = 1.2 \text{ V}$
-20	240	20	Ω	$V_{DDI} = 1.2 \text{ V}$

Note: Measured at 50% of V_{DDI} .

4.3.5 GPIO On-Die Termination

The following table lists the on-die termination calibration accuracy specifications for the GPIO bank.

Table 4-24. On-Die Termination Calibration Accuracy Specifications for GPIO Bank

Parameter	Description	Min (%)	Typ	Max (%)	Unit	Condition
Differential termination ¹	Internal differential termination	-20	100	20	Ω	$V_{ICM} < 0.8 \text{ V}^6$
		-20	100	40	Ω	$0.6 \text{ V} < V_{ICM} < 1.65 \text{ V}^6$
		-20	100	80	Ω	$1.4 \text{ V} < V_{ICM}^6$

.....continued

Parameter	Description	Min (%)	Typ	Max (%)	Unit	Condition
Single-ended thevenin termination ^{2, 3}	Internal parallel thevenin termination	-40	50	20	Ω	$V_{DDI} = 1.8 \text{ V}/1.5 \text{ V}$
		-40	75	20	Ω	$V_{DDI} = 1.8 \text{ V}$
		-40	150	20	Ω	$V_{DDI} = 1.8 \text{ V}$
		-20	20	20	Ω	$V_{DDI} = 1.5 \text{ V}$
		-20	30	20	Ω	$V_{DDI} = 1.5 \text{ V}$
		-20	40	20	Ω	$V_{DDI} = 1.5 \text{ V}$
		-20	60	20	Ω	$V_{DDI} = 1.5 \text{ V}$
		-20	120	20	Ω	$V_{DDI} = 1.5 \text{ V}$
Single-ended termination to V_{SS} ^{4, 5}	Internal parallel termination to V_{SS}	-20	120	20	Ω	$V_{DDI} = 2.5 \text{ V}/1.8 \text{ V}/1.5 \text{ V}/1.2 \text{ V}$
		-20	240	20	Ω	$V_{DDI} = 2.5 \text{ V}/1.8 \text{ V}/1.5 \text{ V}/1.2 \text{ V}$

1. Measured across P to N with 400 mV bias.
2. Thevenin impedance is calculated based on independent P and N as measured at 50% of V_{DDI} .
3. For 50 Ω /75 Ω /150 Ω cases, the nearest supported values of 40 Ω /60 Ω /120 Ω are used.
4. Measured at 50% of V_{DDI} .
5. Supported terminations vary with the I/O type regardless of V_{DDI} nominal voltage. Refer to Libero for available combinations and default settings.
6. When V_{ICM} complies with more than one range, use the maximum percentage tolerance of the two ranges.

4.3.6 I/O Hysteresis

The following table lists the I/O input hysteresis characteristics for HSIO and GPIO over recommended operating conditions.

Table 4-25. Input Hysteresis Characteristics over Recommended Operating Conditions

Bank Type	IO Standard	Hysteresis (min)	Units
GPIO	LVC MOS33	180	mV
GPIO	LVC MOS25	135	mV
HSIO	LVC MOS18	50	mV
HSIO	LVC MOS15	50	mV

5. AC Switching Characteristics

This section contains the AC switching characteristics of the PolarFire FPGA device.

5.1 I/O Standards Specifications

This section describes I/O delay measurement methodology, buffer speed, switching characteristics, digital latency, gearing training calibration, and maximum physical interface (PHY) rate for memory interface IP.

5.1.1 Input Delay Measurement Methodology Maximum PHY Rate for Memory Interface IP

The following table provides information about the methodology for input delay measurement.

Table 5-1. Input Delay Measurement Methodology

Standard	Description	V_L ¹	V_H ¹	V_{ID} ²	V_{ICM} ²	V_{MEAS} ^{3, 4}	V_{REF} ^{1, 5}	Unit
PCI	PCI 3.3 V	0	VDDI			VDDI/2		V
LVTTTL	LVTTTL 3.3 V	0	VDDI			VDDI/2		V
LVC MOS33	LVC MOS 3.3 V	0	VDDI			VDDI/2		V
LVC MOS25	LVC MOS 2.5 V	0	VDDI			VDDI/2		V
LVC MOS18	LVC MOS 1.8 V	0	VDDI			VDDI/2		V
LVC MOS15	LVC MOS 1.5 V	0	VDDI			VDDI/2		V
LVC MOS12	LVC MOS 1.2 V	0	VDDI			VDDI/2		V
SSTL25I	SSTL 2.5 V Class I	$V_{REF} - 0.5$	$V_{REF} + 0.5$			V_{REF}	1.25	V
SSTL25II	SSTL 2.5 V Class II	$V_{REF} - 0.5$	$V_{REF} + 0.5$			V_{REF}	1.25	V
SSTL18I	SSTL 1.8 V Class I	$V_{REF} - 0.5$	$V_{REF} + 0.5$			V_{REF}	0.90	V
SSTL18II	SSTL 1.8 V Class II	$V_{REF} - 0.5$	$V_{REF} + 0.5$			V_{REF}	0.90	V
SSTL15I	SSTL 1.5 V Class I	$V_{REF} - .175$	$V_{REF} + .175$			V_{REF}	0.75	V
SSTL15II	SSTL 1.5 V Class II	$V_{REF} - .175$	$V_{REF} + .175$			V_{REF}	0.75	V
SSTL135I	SSTL 1.35 V Class I	$V_{REF} - .16$	$V_{REF} + .16$			V_{REF}	0.675	V
SSTL135II	SSTL 1.35 V Class II	$V_{REF} - .16$	$V_{REF} + .16$			V_{REF}	0.675	V
HSTL15I	HSTL 1.5 V Class I	$V_{REF} - .5$	$V_{REF} + .5$			V_{REF}	0.75	V
HSTL15II	HSTL 1.5 V Class II	$V_{REF} - .5$	$V_{REF} + .5$			V_{REF}	0.75	V
HSTL135I	HSTL 1.35 V Class I	$V_{REF} - .45$	$V_{REF} + .45$			V_{REF}	0.675	V
HSTL135II	HSTL 1.35 V Class II	$V_{REF} - .45$	$V_{REF} + .45$			V_{REF}	0.675	V
HSTL12I	HSTL 1.2 V Class I	$V_{REF} - .4$	$V_{REF} + .4$			V_{REF}	0.60	V
HSTL12II	HSTL 1.2 V Class II	$V_{REF} - .4$	$V_{REF} + .4$			V_{REF}	0.60	V
HSUL18I	HSUL 1.8 V Class I	$V_{REF} - .54$	$V_{REF} + .54$			V_{REF}	0.90	V
HSUL18II	HSUL 1.8 V Class II	$V_{REF} - .54$	$V_{REF} + 0.54$			V_{REF}	0.90	V

AC Switching Characteristics

.....continued

Standard	Description	V_L^1	V_H^1	V_{ID}^2	V_{ICM}^2	$V_{MEAS}^{3,4}$	$V_{REF}^{1,5}$	Unit
HSUL12I	HSUL 1.2 V	$V_{REF} - .22$	$V_{REF} + .22$			V_{REF}	0.60	V
POD12I	Pseudo open drain (POD) logic 1.2 V Class I	$V_{REF} - .15$	$V_{REF} + .15$			V_{REF}	0.84	V
POD12II	POD 1.2 V Class II	$V_{REF} - .15$	$V_{REF} + .15$			V_{REF}	0.84	V
LVDS33	Low-voltage differential signaling (LVDS) 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
LVDS25	LVDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
LVDS18	LVDS 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
LCMDS33	Low-common mode differential signaling (LCMDS) 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
LCMDS25	LCMDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
LCMDS18	LCMDS 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
RSDS33	RSDS 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
RSDS25	RSDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
RSDS18	RSDS 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
MINILVDS33	Mini-LVDS 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
MINILVDS25	Mini-LVDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
MINILVDS18	Mini-LVDS 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
SUBLVDS33	Sub-LVDS 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.900	0		V
SUBLVDS25	Sub-LVDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.900	0		V
SUBLVDS18	Sub-LVDS 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.900	0		V
PPDS33	Point-to-point differential signaling 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.800	0		V
PPDS25	PPDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.800	0		V
PPDS18	PPDS 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.800	0		V
SLVS33	Scalable low-voltage signaling 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.200	0		V
SLVS25	SLVS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.200	0		V
SLVS18	SLVS 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.200	0		V
HCSL33	High-speed current steering logic (HCSL) 3.3 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.350	0		V
HCSL25	HCSL 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.350	0		V
HCSL18	HCSL 1.8 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.350	0		V

AC Switching Characteristics

.....continued

Standard	Description	V_L^1	V_H^1	V_{ID}^2	V_{ICM}^2	$V_{MEAS}^{3,4}$	$V_{REF}^{1,5}$	Unit
BLVDSE25 ⁶	Bus LVDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
MLVDSE25 ⁶	Multipoint LVDS 2.5 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
LVPECL33	Low-voltage positive emitter coupled logic	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.650	0		V
LVPECLE33 ⁶	Low-voltage positive emitter coupled logic	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.650	0		V
SSTL25I	Differential SSTL 2.5 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
SSTL25II	Differential SSTL 2.5 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	1.250	0		V
SSTL18I	Differential SSTL 1.8 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.900	0		V
SSTL18II	Differential SSTL 1.8 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.900	0		V
SSTL15I	Differential SSTL 1.5 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.750	0		V
SSTL15II	Differential SSTL 1.5 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.750	0		V
SSTL135I	Differential SSTL 1.35 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.675	0		V
SSTL135II	Differential SSTL 1.35 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.675	0		V
HSTL15I	Differential HSTL 1.5 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.750	0		V
HSTL15II	Differential HSTL 1.5 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.750	0		V
HSTL135I	Differential HSTL 1.35 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.675	0		V
HSTL135II	Differential HSTL 1.35 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.675	0		V
HSTL12I	Differential HSTL 1.2 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.600	0		V
HSTL12II	Differential HSTL 1.2 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.600	0		V
HSUL18I	Differential HSUL 1.8 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.900	0		V
HSUL18II	Differential HSUL 1.8 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.900	0		V
HSUL12I	Differential HSUL 1.2 V	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.600	0		V
POD12I	Differential POD 1.2 V Class I	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.840	0		V
POD12II	Differential POD 1.2 V Class II	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.840	0		V

.....continued

Standard	Description	V_L ¹	V_H ¹	V_{ID} ²	V_{ICM} ²	V_{MEAS} ^{3, 4}	V_{REF} ^{1, 5}	Unit
MIPI25	Mobile Industry Processor Interface	$V_{ICM} - .125$	$V_{ICM} + .125$	0.250	0.200	0		V

1. Measurements are made at typical, minimum, and maximum V_{REF} values. Reported delays reflect worst-case of these measurements. V_{REF} values listed are typical. Input waveform switches between V_{IL} and V_{IH} . All rise and fall rates must be 1 V/ns for non-mixed mode input buffers as one-third the minimum period for mixed-mode input buffers.
2. Differential receiver standards all use 250 mV V_{ID} for timing. V_{ICM} is different between different standards.
3. Input voltage level from which measurement starts.
4. The value given is the differential input voltage.
5. This is an input voltage reference that bears no relation to the V_{REF}/V_{MEAS} parameters found in IBIS models or shown in the figure Output Delay Measurement—Single-Ended Test Setup.
6. Emulated bidirectional interface.

5.1.2 Output Delay Measurement Methodology

The following section provides information about the methodology for output delay measurement.

Table 5-2. Output Delay Measurement Methodology

Standard	Description	R_{REF} (Ω)	C_{REF} (pF)	V_{MEAS} (V)	V_{REF} (V)
PCI	PCIE 3.3 V	25	10	1.65	
LVTTL	LVTTL 3.3 V	1M	0	1.65	
LVC MOS33	LVC MOS 3.3 V	1M	0	1.65	
LVC MOS25	LVC MOS 2.5 V	1M	0	1.25	
LVC MOS18	LVC MOS 1.8 V	1M	0	0.90	
LVC MOS15	LVC MOS 1.5 V	1M	0	0.75	
LVC MOS12	LVC MOS 1.2 V	1M	0	0.60	
SSTL25I	Stub-series terminated logic 2.5 V Class I	50	0	V_{REF}	1.25
SSTL25II	SSTL 2.5 V Class II	50	0	V_{REF}	1.25
SSTL18I	SSTL 1.8 V Class I	50	0	V_{REF}	0.9
SSTL18II	SSTL 1.8 V Class II	50	0	V_{REF}	0.9
SSTL15I	SSTL 1.5 V Class I	50	0	V_{REF}	0.75
SSTL15II	SSTL 1.5 V Class II	50	0	V_{REF}	0.75
SSTL135I	SSTL 1.35 V Class I	50	0	V_{REF}	0.675
SSTL135II	SSTL 1.35 V Class II	50	0	V_{REF}	0.675
HSTL15I	High-speed transceiver logic (HSTL) 1.5 V Class I	50	0	V_{REF}	0.75
HSTL15II	HSTL 1.5 V Class II	50	0	V_{REF}	0.75
HSTL135I	HSTL 1.35 V Class I	50	0	V_{REF}	0.675

AC Switching Characteristics

.....continued

Standard	Description	R _{REF} (Ω)	C _{REF} (pF)	V _{MEAS} (V)	V _{REF} (V)
HSTL135II	HSTL 1.35 V Class II	50	0	V _{REF}	0.675
HSTL12I	HSTL 1.2 V Class I	50	0	V _{REF}	0.6
HSTL12II	HSTL 1.2 V Class II	50	0	V _{REF}	0.6
HSUL18I	High-speed unterminated logic 1.8 V Class I	50	0	V _{REF}	0.9
HSUL18II	HSUL 1.8 V Class II	50	0	V _{REF}	0.9
HSUL12I	HSUL 1.2 V Class I	50	0	V _{REF}	0.6
POD12I	Pseudo open drain (POD) logic 1.2 V Class I	50	0	V _{REF}	0.84
POD12II	POD 1.2 V Class II	50	0	V _{REF}	0.84
LVDS33	LVDS 3.3 V	100	0	0 ¹	0
LVDS25	LVDS 2.5 V	100	0	0 ¹	0
LCMDS33	Low-common mode differential signaling (LCMDS) 3.3 V	100	0	0 ¹	0
LCMDS25	LCMDS 2.5 V	100	0	0	0
RSDS33	Reduced swing differential signaling 3.3 V	100	0	0 ¹	0
RSDS25	RSDS 2.5 V	100	0	0 ¹	0
MINILVDS33	Mini-LVDS 3.3 V	100	0	0 ¹	0
MINILVDS25	Mini-LVDS 2.5 V	100	0	0 ¹	0
SUBLVDS33	Sub-LVDS 3.3 V	100	0	0 ¹	0
SUBLVDS25	Sub-LVDS 2.5 V	100	0	0 ¹	0
PPDS33	Point-to-point differential signaling 3.3 V	100	0	0 ¹	0
PPDS25	PPDS 2.5 V	100	0	0 ¹	0
SLVS33	Scalable low-voltage signaling 3.3 V	100	0	0 ¹	0
SLVS25	SLVS 2.5 V	100	0	0 ¹	0
SLVSE15	SLVS 1.5 V	100	0	0 ¹	0
HCSL33	High-speed current steering logic 3.3 V	100	0	0 ¹	0
HCSL25	HCSL 2.5 V	100	0	0 ¹	0
BUSLVDSE25	Bus LVDS	100	0	0 ¹	0
MLVDSE25	Multipoint LVDS 2.5 V	100	0	0 ¹	0
LVPECLE33	Low-voltage positive emitter-coupled logic	100	0	0 ¹	0
MIPIE25	Mobile industry processor interface 2.5 V	100	0	0 ¹	0
SSTL25I	Differential SSTL 2.5 V Class I	50	0	0 ¹	0

AC Switching Characteristics

.....continued

Standard	Description	R _{REF} (Ω)	C _{REF} (pF)	V _{MEAS} (V)	V _{REF} (V)
SSTL25II	Differential SSTL 2.5 V Class II	50	0	0 ¹	0
SSTL18I	Differential SSTL 1.8 V Class I	50	0	0 ¹	0
SSTL18II	Differential SSTL 1.8 V Class II	50	0	0 ¹	0
SSTL15I	Differential SSTL 1.5 V Class I	50	0	0 ¹	0
SSTL15II	Differential SSTL 1.5 V Class II	50	0	0 ¹	0
SSTL135I	Differential SSTL 1.35 V Class I	50	0	0 ¹	0
SSTL135II	Differential SSTL 1.35 V Class II	50	0	0 ¹	0
HSTL15I	Differential HSTL 1.5 V Class I	50	0	0 ¹	0
HSTL15II	Differential HSTL 1.5 V Class II	50	0	0 ¹	0
HSTL135I	Differential HSTL 1.35 V Class I	50	0	0 ¹	0
HSTL135II	Differential HSTL 1.35 V Class II	50	0	0 ¹	0
HSTL12I	Differential HSTL 1.2 V Class I	50	0	0 ¹	0
HSTL12II	Differential HSTL 1.2 V Class II	50	0	0 ¹	0
HSUL18I	Differential HSUL 1.8 V Class I	50	0	0 ¹	0
HSUL18II	Differential HSUL 1.8 V Class II	50	0	0 ¹	0
HSUL12I	Differential HSUL 1.2 V Class I	50	0	0 ¹	0
POD12I	Differential POD 1.2 V Class II	50	0	0 ¹	0
POD12II	Differential POD 1.2 V Class II	50	0	0 ¹	0

1. The value given is the differential output voltage.

Figure 5-1. Output Delay Measurement—Single-Ended Test Setup

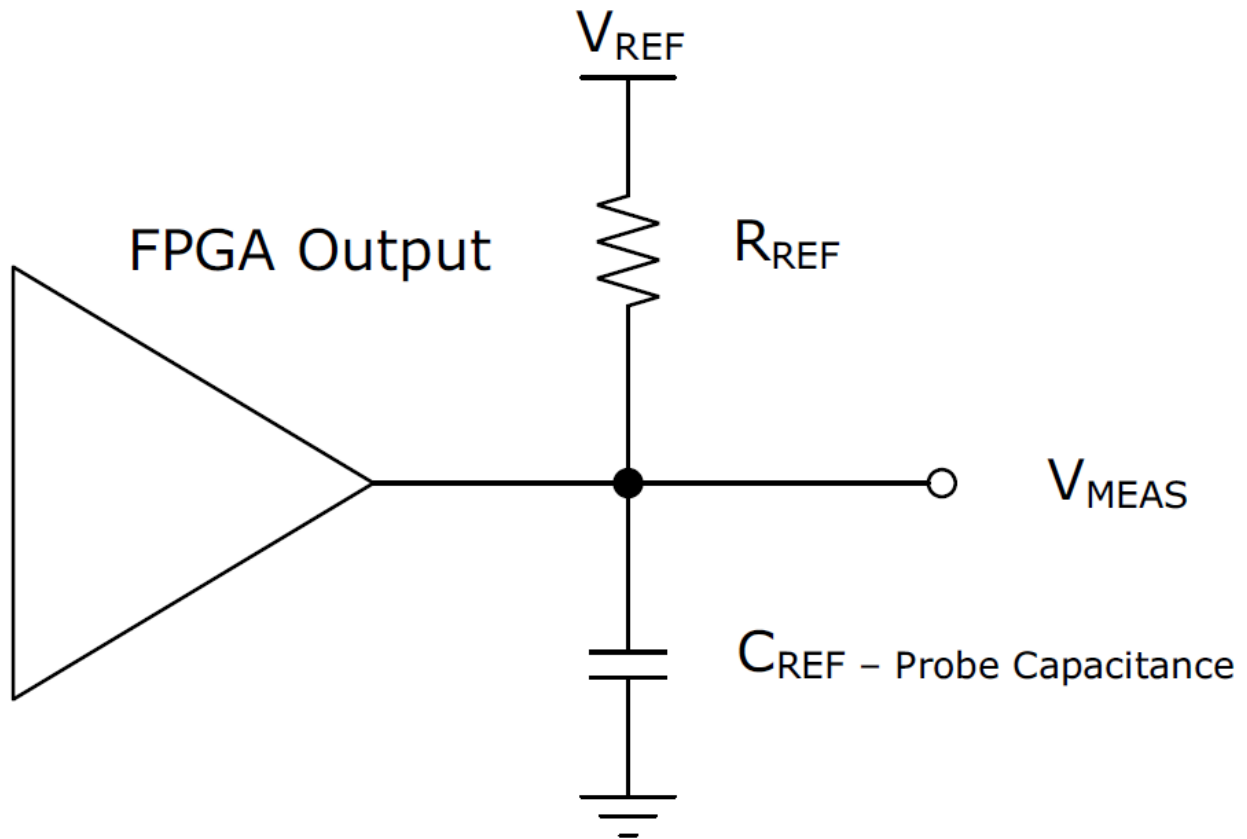
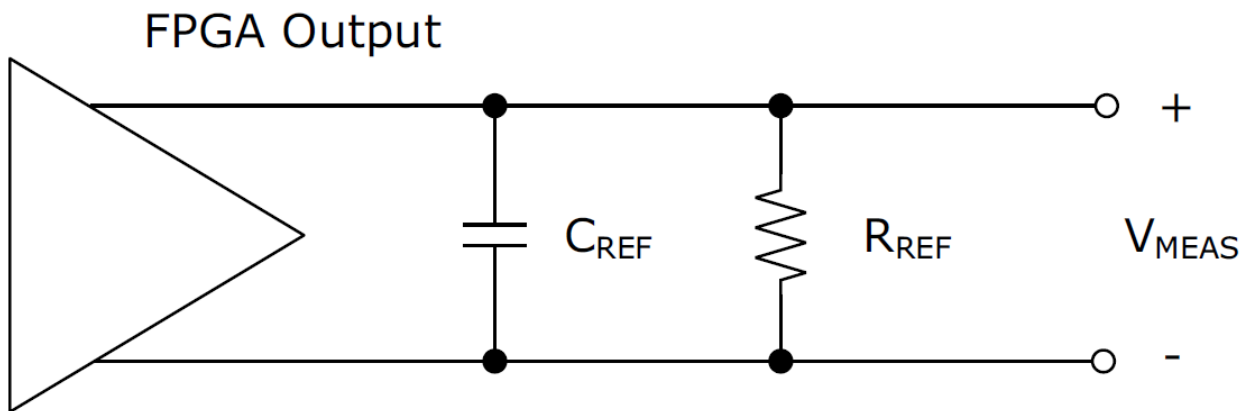


Figure 5-2. Output Delay Measurement—Differential Test Setup



5.1.3 Input Buffer Speed

The following tables describe input buffer speed.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-3. HSIO Maximum Input Buffer Speed

Standard	STD	-1	Unit
LVDS18	1250	1250	Mbps
LCMDS18	1250	1250	Mbps
HCSL18	800	800	Mbps
RSDS18	800	800	Mbps
MINILVDS18	800	800	Mbps
SUBLVDS18	800	800	Mbps
PPDS18	800	800	Mbps
SLVS18	800	800	Mbps
SSTL18I	800	1066	Mbps
SSTL18II	800	1066	Mbps
SSTL15I	1066	1333	Mbps
SSTL15II	1066	1333	Mbps
SSTL135I	1066	1333	Mbps
SSTL135II	1066	1333	Mbps
HSTL15I	900	1100	Mbps
HSTL15II	900	1100	Mbps
HSTL135I	1066	1066	Mbps
HSTL135II	1066	1066	Mbps
HSUL18I	400	400	Mbps
HSUL18II	400	400	Mbps
HSUL12I	1066	1333	Mbps
HSTL12I	1066	1266	Mbps
HSTL12II	1066	1266	Mbps
POD12I	1333	1600	Mbps
POD12II	1333	1600	Mbps
LVC MOS18 (12 mA)	500	500	Mbps
LVC MOS15 (10 mA)	500	500	Mbps
LVC MOS12 (8 mA)	300	300	Mbps

Notes:

- Performance is achieved with $V_{ID} \geq 200$ mV.
- LVDS18 configuration should be used in conjunction with I/O CDR when implementing SGMII receivers.

AC Switching Characteristics

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-4. GPIO Maximum Input Buffer Speed

Standard	STD	–1	Unit
LVDS25/LVDS33/LCMDS25/LCMDS33	1250	1600	Mbps
RSDS25/RSDS33	800	800	Mbps
MINILVDS25/MINILVDS33	800	800	Mbps
SUBLVDS25/SUBLVDS33	800	800	Mbps
PPDS25/PPDS33	800	800	Mbps
SLVS25/SLVS33	800	800	Mbps
SLVSE15	800	800	Mbps
HCSL25/HCSL33	800	800	Mbps
BUSLVDSE25	800	800	Mbps
MLVDSE25	800	800	Mbps
LVPECL33	800	800	Mbps
SSTL25I	800	800	Mbps
SSTL25II	800	800	Mbps
SSTL18I	800	800	Mbps
SSTL18II	800	800	Mbps
SSTL15I	800	1066	Mbps
SSTL15II	800	1066	Mbps
HSTL15I	800	900	Mbps
HSTL15II	800	900	Mbps
HSUL18I	400	400	Mbps
HSUL18II	400	400	Mbps
PCI	500	500	Mbps
LVTTTL	500	500	Mbps
LVC MOS33	500	500	Mbps
LVC MOS25	500	500	Mbps
LVC MOS18	500	500	Mbps
LVC MOS15	500	500	Mbps
LVC MOS12	300	300	Mbps

.....continued			
Standard	STD	–1	Unit
MIPI25 ³	1000	1500	Mbps

1. All SSTLD/HSTLD/HSULD/LVSTLD/POD type receivers use the LVDS differential receiver.
2. Performance is achieved with $V_{ID} \geq 200$ mV.
3. $V_{ID} \geq 200$ mV, $V_{ICM} \geq 100$ mV, $T_j = 0.4$ UI.
4. LVDS25 configuration should be used in conjunction with I/O CDR when implementing SGMII receivers.

5.1.4 Output Buffer Speed

The following tables describe output buffer speed.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-5. HSIO Maximum Output Buffer Speed

Standard	STD	–1	Unit
SSTL18I	800	1066	Mbps
SSTL18II	800	1066	Mbps
SSTL18I (differential)	800	1066	Mbps
SSTL18II (differential)	800	1066	Mbps
SSTL15I	1066	1333	Mbps
SSTL15II	1066	1333	Mbps
SSTL15I (differential)	1066	1333	Mbps
SSTL15II (differential)	1066	1333	Mbps
SSTL135I	1066	1333	Mbps
SSTL135II	1066	1333	Mbps
SSTL135I (differential)	1066	1333	Mbps
SSTL135II (differential)	1066	1333	Mbps
HSTL15I	900	1100	Mbps
HSTL15II	900	1100	Mbps
HSTL15I (differential)	900	1100	Mbps
HSTL15II (differential)	900	1100	Mbps
HSTL135I	1066	1066	Mbps
HSTL135II	1066	1066	Mbps
HSTL135I (differential)	1066	1066	Mbps
HSTL135II (differential)	1066	1066	Mbps

AC Switching Characteristics

.....continued

Standard	STD	–1	Unit
HSUL18I	400	400	Mbps
HSUL18II	400	400	Mbps
HSUL18I (differential)	400	400	Mbps
HSUL18II (differential)	400	400	Mbps
HSUL12I	1066	1333	Mbps
HSUL12I (differential)	1066	1333	Mbps
HSTL12I	1066	1266	Mbps
HSTL12II	1066	1266	Mbps
HSTL12I (differential)	1066	1266	Mbps
HSTL12II (differential)	1066	1266	Mbps
POD12I	1333	1600	Mbps
POD12II	1333	1600	Mbps
LVC MOS18 (12 mA)	500	500	Mbps
LVC MOS15 (10 mA)	500	500	Mbps
LVC MOS12 (8 mA)	250	300	Mbps

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-6. GPIO Maximum Output Buffer Speed

Standard	STD	–1	Unit
LVDS25/LCMDS25	1250	1250	Mbps
LVDS33/LCMDS33	1250	1600	Mbps
RSDS25	800	800	Mbps
MINILVDS25	800	800	Mbps
SUBLVDS25	800	800	Mbps
PPDS25	800	800	Mbps
SLVSE15	500	500	Mbps
BUSLVDSE25	500	500	Mbps
MLVDSE25	500	500	Mbps
LVPECLE33	500	500	Mbps
SSTL25I	800	800	Mbps

AC Switching Characteristics

.....continued

Standard	STD	-1	Unit
SSTL25II	800	800	Mbps
SSTL25I (differential)	800	800	Mbps
SSTL25II (differential)	800	800	Mbps
SSTL18I	800	800	Mbps
SSTL18II	800	800	Mbps
SSTL18I (differential)	800	800	Mbps
SSTL18II (differential)	800	800	Mbps
SSTL15I	800	1066	Mbps
SSTL15II	800	1066	Mbps
SSTL15I (differential)	800	1066	Mbps
SSTL15II (differential)	800	1066	Mbps
HSTL15I	900	900	Mbps
HSTL15II	900	900	Mbps
HSTL15I (differential)	900	900	Mbps
HSTL15II (differential)	900	900	Mbps
HSUL18I	400	400	Mbps
HSUL18II	400	400	Mbps
HSUL18I (differential)	400	400	Mbps
HSUL18II (differential)	400	400	Mbps
PCI	500	500	Mbps
LVTTL (20 mA)	500	500	Mbps
LVC MOS33 (20 mA)	500	500	Mbps
LVC MOS25 (16 mA)	500	500	Mbps
LVC MOS18 (12 mA)	500	500	Mbps
LVC MOS15 (10 mA)	500	500	Mbps
LVC MOS12 (8 mA)	250	300	Mbps
MIPIE25	1000	1000	Mbps

Note: LVDS25 configuration should be used when implementing SGMII transmitters.

5.1.5 Maximum PHY Rate for Memory Interface IP

The following tables describe the maximum PHY rate for memory interface IP.

AC Switching Characteristics

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-7. Maximum PHY Rate for Memory Interfaces IP for HSIO Banks

Memory Standard	Gearing Ratio	V _{DDAUX}	V _{DDI}	STD (Mbps) Min	STD (Mbps) Max	–1 (Mbps) Min	–1 (Mbps) Max	Fabric Clock STD Min (MHz)	Fabric Clock STD Max (MHz)	Fabric Clock –1 Min (MHz)	Fabric Clock –1 Max (MHz)
DDR4	8:1	1.8 V	1.2 V	800	1333	800	1600	100	167	100	200
DDR3	8:1	1.8 V	1.5 V	800	1067	800	1333	100	133	100	167
DDR3L ¹	8:1	1.8 V	1.35 V	800	1067	800	1333	100	133	100	167
LPDDR3	8:1	1.8 V	1.2 V	800	800	800	1333	100	133	100	167
QDRII+	8:1	1.8 V	1.5 V	500	900	500	1100	62.5	112.5	62.5	137.5
RLDRAM3 ¹	8:1	1.8 V	1.35 V	—	1067	—	1067	—	133	—	133
RLDRAM3 ¹	4:1	1.8 V	1.35 V	—	667	—	800	—	167	—	200
RLDRAM3 ¹	2:1	1.8 V	1.35 V	—	333	—	400	—	167	—	200
RLDRAMII ¹	8:1	1.8 V	1.8 V	—	800	—	1067	—	100	—	133
RLDRAMII ¹	4:1	1.8 V	1.8 V	—	667	—	800	—	167	—	200
RLDRAMII ¹	2:1	1.8 V	1.8 V	—	333	—	400	—	167	—	200

1. Simulation data only. Microchip does not provide a soft controller for RLDRAMII, RLDRAM3, or DDR3L.
2. Simulation data only. RLDRAMII is currently not supported with a soft IP controller.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-8. Maximum PHY Rate for Memory Interfaces IP for GPIO Banks

Memory Standard	Gearing Ratio	V _{DDAUX}	V _{DDI}	STD (Mbps) Min	STD (Mbps) Max	–1 (Mbps) Min	–1 (Mbps) Max	Fabric Clock STD Min (MHz)	Fabric Clock STD Max (MHz)	Fabric Clock –1 Min (MHz)	Fabric Clock –1 Max (MHz)
DDR3	8:1	2.5 V	1.5 V	800	800	800	1067	100	100	100	133
QDRII+	8:1	2.5 V	1.5 V	500	900	500	900	62.5	112.5	62.5	112.5
RLDRAMII ¹	4:1	2.5 V	1.8 V	—	800	—	800	—	200	—	200
RLDRAMII ¹	2:1	2.5 V	1.8 V	—	400	—	400	—	200	—	200

- Simulation data only. RLDRAMII is currently not supported with a soft IP controller.

5.1.6 User I/O Switching Characteristics

The following section describes user I/O switching characteristics. For more information about user I/O timing, see the PolarFire I/O Timing Spreadsheet (to be released). The following interface names are described in UG0686: PolarFire FPGA User I/O User Guide.

5.1.6.1 I/O Digital

The following tables describe I/O digital.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-9. I/O Digital Receive Single-Data Rate Switching Characteristics¹

Parameter	Interface Name	Topology	I/O Type	STD (MHz)	–1 (MHz)	STD (Mbps)	–1 (Mbps)	Clock-to-Data Condition
Input F _{MAX}	RX_SDR_G_A	Rx SDR	HSIO, GPIO	500	500	500	500	From a global clock source, aligned
Input F _{MAX}	RX_SDR_R_A	Rx SDR	HSIO, GPIO	250	250	250	250	From a regional clock source, aligned
Input F _{MAX}	RX_SDR_G_C	Rx SDR	HSIO, GPIO	500	500	500	500	From a global clock source, centered
Input F _{MAX}	RX_SDR_R_C	Rx SDR	HSIO, GPIO	250	250	250	250	From a regional clock source, centered

- Unless otherwise noted, all data rates listed are achieved with static IOD tap settings.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-10. I/O Digital Receive Double Data Rate Switching Characteristics⁴

Parameter	Interface Name	Topology	I/O Type	STD (MHz)	–1 (MHz)	STD (Mbps)	–1 (Mbps)	Clock-to-Data Condition
Input F _{MAX}	RX_DDR_G_A	Rx DDR	HSIO	335	345	670	690	From a global clock source, aligned
			GPIO	310	325	620	650	
Input F _{MAX}	RX_DDR_R_A	Rx DDR	HSIO	250	250	500	500	From a regional clock source, aligned
			GPIO	250	250	500	500	
Input F _{MAX}	RX_DDR_G_C	Rx DDR	HSIO	335	345	670	690	From a global clock source, centered
			GPIO	310	325	620	650	

AC Switching Characteristics

.....continued

Parameter	Interface Name	Topology	I/O Type	STD (MHz)	-1 (MHz)	STD (Mbps)	-1 (Mbps)	Clock-to-Data Condition
Input F _{MAX}	RX_DDR_R_C	Rx DDR	HSIO	250	250	500	500	From a regional clock source, centered
			GPIO	250	250	500	500	
Input F _{MAX} 2:1	RX_DDRX_B_G_A	Rx DDR digital mode	HSIO	350	350	700	700	From a HS_IO_CLK clock source, aligned, global fabric clock
			GPIO	300	310	600	620	
Input F _{MAX} 4:1	RX_DDRX_B_G_A	Rx DDR digital mode	HSIO	350	350	700	700	From a HS_IO_CLK clock source, aligned, global fabric clock
			GPIO	300	310	600	620	
Input F _{MAX} 3.5:1	RX_DDRX_B_G_FA	Rx DDR digital mode for fractional	HSIO	350	350	700	700	From a HS_IO_CLK clock source, aligned, global fabric clock, fractional input
			GPIO	320	320	640	640	
Input F _{MAX} 2:1	RX_DDRX_B_G_C	Rx DDR digital mode	HSIO	350	350	700	700	From a HS_IO_CLK clock source, centered, global fabric clock
			GPIO	300	310	600	620	
Input F _{MAX} 4:1 Input F _{MAX} 5:1	RX_DDRX_B_G_C	Rx DDR digital mode	HSIO	350	350	700	700	From a HS_IO_CLK clock source, centered, global fabric clock
			GPIO	300	310	600	620	
Input F _{MAX} 4:1	RX_DDRX_B_G_DYN_MIPI ³	Rx DDR digital mode for MIPI	GPIO	500 ¹	750 ¹	1000 ¹	1500 ¹	From a HS_IO_CLK clock source, centered, global fabric clock
Input F _{MAX} 2:1	RX_DDRX_B_R_A	Rx DDR digital mode	HSIO	220	270	440	540	From a HS_IO_CLK clock source, aligned, regional fabric clock
			GPIO	205	250	410	500	

AC Switching Characteristics

.....continued

Parameter	Interface Name	Topology	I/O Type	STD (MHz)	–1 (MHz)	STD (Mbps)	–1 (Mbps)	Clock-to-Data Condition
Input F_{MAX} 4:1 Input F_{MAX} 5:1	RX_DDRX_B_R_A	Rx DDR digital mode	HSIO	220	270	440	540	From a HS_IO_CLK clock source, aligned, regional fabric clock
			GPIO	205	250	410	500	
Input F_{MAX} 2:1	RX_DDRX_B_R_C	Rx DDR digital mode	HSIO	220	270	440	540	From a HS_IO_CLK clock source, centered, regional fabric clock
			GPIO	205	250	410	500	
Input F_{MAX} 4:1 Input F_{MAX} 5:1	RX_DDRX_B_R_C	Rx DDR digital mode	HSIO	220	270	440	540	From a HS_IO_CLK clock source, centered, regional fabric clock
			GPIO	205	250	410	500	

1. $V_{ID} \geq 200$ mV, $V_{ICM} \geq 100$ mV, $T_J = 0.4$ UI.
2. A centered clock-to-data interface can be created with a negedge launch of the data.
3. Data rates listed are achieved using dynamic training.
4. Unless otherwise noted, all data rates listed are achieved with static IOD tap settings.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-11. I/O Digital Transmit Single Data Rate Switching Characteristics²

Parameter	Interface Name	Topology	I/O Type	STD (MHz)	–1 (MHz)	STD (Mbps)	–1 (Mbps)	Forwarded Clock-to-Data Skew
Output F_{MAX}	TX_SDR_G_A	Tx SDR	HSIO, GPIO	500	500	500	500	From a global clock source, aligned ¹
	TX_SDR_G_C	Tx SDR	HSIO, GPIO	500	500	500	500	From a global clock source, centered ¹

1. A centered clock-to-data interface can be created with a negedge launch of the data.
2. Unless otherwise noted, all data rates listed are achieved with static IOD tap settings.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-12. I/O Digital Transmit Double Data Rate Switching Characteristics

Parameter	Interface Name	Topology	I/O Type	STD (MHz)	-1 (MHz)	STD (Mbps)	-1 (Mbps)	Forwarded Clock-to-Data Skew
Output F_{MAX}	TX_DDR_G_A	Tx DDR	HSIO, GPIO	500	500	1000	1000	From a global clock source, aligned
	TX_DDR_G_C	Tx DDR	HSIO, GPIO	500	500	1000	1000	From a global clock source, centered
Output F_{MAX} 2:1	TX_DDRX_B_A	Tx DDR digital mode	HSIO	400	500	800	1000	From a HS_IO_CLK clock source, aligned
Output F_{MAX} 4:1 Output F_{MAX} 5:1	TX_DDRX_B_A	Tx DDR digital mode	HSIO	667	800	1333	1600	From a HS_IO_CLK clock source, aligned
Output F_{MAX} 2:1	TX_DDRX_B_C	Tx DDR digital mode	HSIO	400	500	800	1000	From a HS_IO_CLK clock source, centered with PLL
Output F_{MAX} 4:1 Output F_{MAX} 5:1	TX_DDRX_B_C	Tx DDR digital mode	HSIO	667	800	1333	1600	From a HS_IO_CLK clock source, centered with PLL
Output F_{MAX} 2:1	TX_DDRX_B_A	Tx DDR digital mode	GPIO	400	500	800	1000	From a HS_IO_CLK clock source, aligned
Output F_{MAX} 4:1 Output F_{MAX} 5:1	TX_DDRX_B_A	Tx DDR digital mode	GPIO	625	800	1250	1600	From a HS_IO_CLK clock source, aligned
Output F_{MAX} 2:1	TX_DDRX_B_C	Tx DDR digital mode	GPIO	400	500	800	1000	From a HS_IO_CLK clock source, centered with PLL
Output F_{MAX} 4:1 Output F_{MAX} 5:1	TX_DDRX_B_C	Tx DDR digital mode	GPIO	625	800	1250	1600	From a HS_IO_CLK clock source, centered with PLL

AC Switching Characteristics

.....continued

Parameter	Interface Name	Topology	I/O Type	STD (MHz)	-1 (MHz)	STD (Mbps)	-1 (Mbps)	Forwarded Clock-to-Data Skew
Output F_{MAX} 4:1	TX_DDRX_B_C_MIP1	Tx DDR digital mode for MIP1	GPIO	500	500	1000	1000	From a HS_IO_CLK clock source, centered with PLL

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-13. Programmable Delay

Parameter	STD Min	STD Typ	STD Max	-1 Min	-1 Typ	-1 Max	Unit
In delay, out delay, DLL delay step sizes	12.7	30	35	12.7	25	29.5	ps

Note: Refer to Libero timing reports for configuration specific intrinsic and incremental delays.

Figure 5-3. LVDS Jitter Tolerance Plot

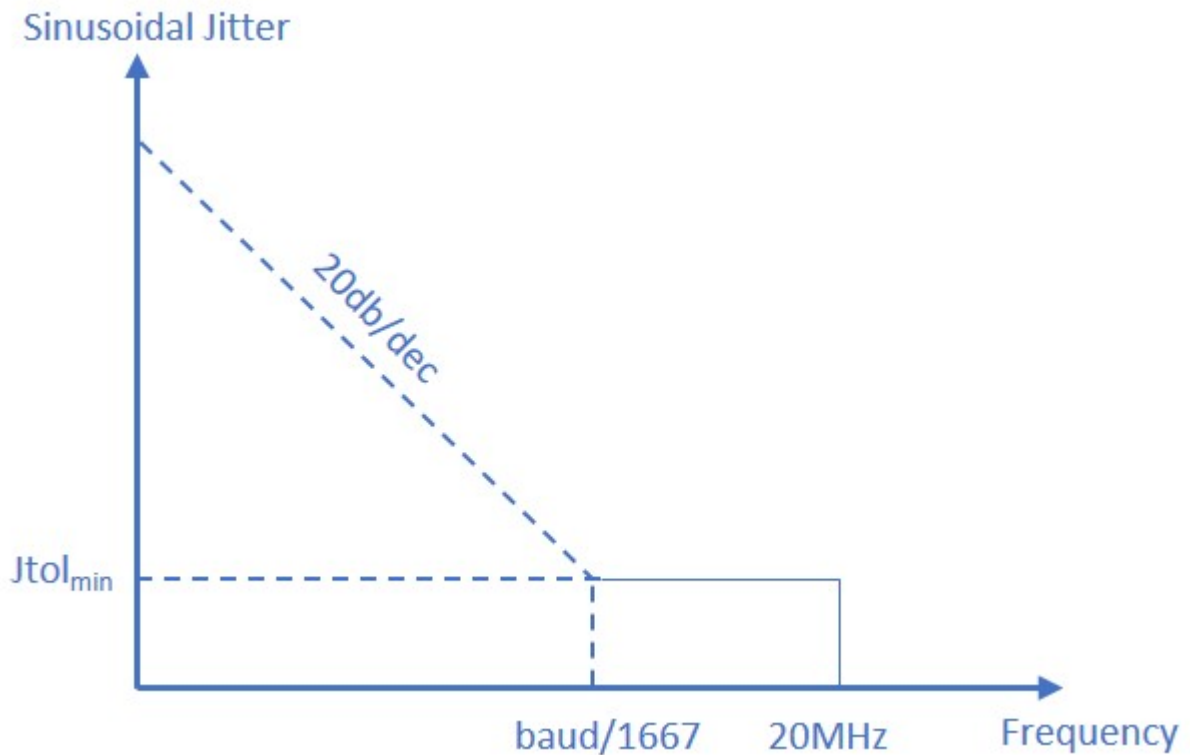


Table 5-14. I/O CDR Switching Characteristics

Buffer Type	I/O Configuration	Min Data Rate (Mbps)	Max Data Rate (Mbps)	Max Tx to Rx Frequency Offset (ppm)	Jt _{ol_min} (UI)
HSIO ^{1,2}	LVDS18	266	1250	±200	0.08
HSIO ^{1,2}	LVDS18	266	1250	±100	0.1
GPIO ^{1,3}	LVDS25	266	1250	±100	0.1

1. Jitter tolerance of applied sinusoidal jitter from 1 KHz to 120 MHz, as shown in figure LVDS Jitter Tolerance Plot. It is measured in addition to a stressed eye of T_j = 0.24 UI with V_{ICM} of 1.25 V and V_{IDmin} of 250 mV, with the CDR operating at a rate of 1250 Mbps plus or minus the ppm offset listed.
2. HSIO LVDS uses an external 100 Ω differential termination resistor. For more information, see LVDS specification in table Differential DC Input Levels.
3. GPIO LVDS uses an internal 100 Ω differential termination resistor. For more information, see LVDS specification in table Differential DC Input Levels.

5.2 Clocking Specifications

This section describes the PLL and DLL clocking and oscillator specifications.

5.2.1 Clocking

The following table describes clocking specifications.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-15. Global and Regional Clock Characteristics (–55 °C to 125 °C)

Parameter	Symbol	V _{DD} = 1.0 V STD	V _{DD} = 1.0 V –1	V _{DD} = 1.05 V STD	V _{DD} = 1.05 V –1	Unit	Condition
Global clock F _{MAX}	F _{MAXG}	500	500	500	500	MHz	
Regional clock F _{MAX}	F _{MAXR}	375	375	375	375	MHz	Transceiver interfaces only
	F _{MAXR}	250	250	250	250	MHz	All other interfaces
Global clock duty cycle distortion	T _{DCDG}	190	190	190	190	ps	At 500 MHz
Regional clock duty cycle distortion	T _{DCDR}	120	120	120	120	ps	At 250 MHz

The following table describes clocking specifications from –40 °C to 100 °C.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-16. High-Speed I/O Clock Characteristics (–55 °C to 125 °C)

Parameter	Symbol	V _{DD} = 1.0 V STD	V _{DD} = 1.0 V –1	V _{DD} = 1.05 V STD	V _{DD} = 1.05 V –1	Unit	Condition
High-speed I/O clock F _{MAX}	F _{MAXB}	1000	1250	1000	1250	MHz	HSIO and GPIO
High-speed I/O clock skew ¹	F _{SKEWB}	30	20	30	20	ps	HSIO without bridging
	F _{SKEWB}	See table HSIO Clock Skew with Bridging.				ps	HSIO with bridging
	F _{SKEWB}	45	35	45	35	ps	GPIO without bridging
	F _{SKEWB}	75	60	75	60	ps	GPIO with bridging
High-speed I/O clock duty cycle distortion ²	T _{DCB}	90	90	90	90	ps	HSIO without bridging
	T _{DCB}	115	115	115	115	ps	HSIO with bridging
	T _{DCB}	90	90	90	90	ps	GPIO without bridging
	T _{DCB}	115	115	115	115	ps	GPIO with bridging

1. F_{SKEWB} is the worst-case clock-tree skew observable between sequential I/O elements. Clock-tree skew is significantly smaller at I/O registers close to each other because they are fed by the same or adjacent clock-tree branches. Use the Microsemi Timing Analyzer tool to evaluate clock skew specific to the design.
2. Parameters listed in this table correspond to the worst-case duty cycle distortion observable at the I/O flip flops. IBIS should be used to calculate any additional duty cycle distortion that might be caused by asymmetrical rise/fall times for any I/O standard.

The following table describes high-speed I/O clock skew (F_{SKEWB}) with bridging from –40 °C to 100 °C.

Note: F_{SKEWB} is the worst-case clock-tree skew observable between sequential I/O elements. Clock-tree skew is significantly smaller at I/O registers close to each other and fed by the same or adjacent clock-tree branches. Use the Microsemi Timing Analyzer tool to evaluate clock skew specific to the design.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-17. HSIO Clock Skew with Bridging (–55 °C to 125 °C)

Device	Total I/O Banks	Bridging Source	V _{DD} = 1.0 V STD	V _{DD} = 1.0 V –1	V _{DD} = 1.05 V STD	V _{DD} = 1.05 V –1	Unit
MPF100T	2	NNW ¹	120	80	120	80	ps
	2	NNE ²	110	70	110	70	ps
MPF200T	2	NNW ¹	120	80	120	80	ps
	2	NNE ²	110	70	110	70	ps

AC Switching Characteristics

.....continued

Device	Total I/O Banks	Bridging Source	V _{DD} = 1.0 V STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V STD	V _{DD} = 1.05 V –1	Unit
MPF300T	3	NNW ¹	120	80	120	80	ps
	3	NNE ²	280	200	280	200	ps
MPF500T	3	NNW ¹	125	85	125	85	ps
	3	NNE ²	300	220	300	220	ps

1. NNW source designates bridging that originates from the North West Corner or PIOs inside I/O bank 0 (the most western I/O bank at the north edge).
2. NNE source designates bridging that originates from the North East Corner or PIOs inside I/O bank 1 (the most eastern I/O bank at the north edge).

5.2.2 PLL

The following table describes PLL.

Table 5-18. PLL Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Input clock frequency (integer mode)	F _{INI}	1		1250	MHz	
Input clock frequency (fractional mode)	F _{INF}	10		1250	MHz	
Minimum reference or feedback pulse width ¹	F _{INPULSE}	200			ps	
Frequency at the Frequency Phase Detector (PFD) (integer mode)	F _{PHDETI}	1		312	MHz	
Frequency at the PFD (fractional mode)	F _{PHDETF}	10		225	MHz	
Allowable input duty cycle	F _{INDUTY}	25		75	%	
Maximum input period clock jitter (reference and feedback clocks) ²	F _{MAXINJ}		120	1000	ps	
PLL VCO frequency	F _{VCO}	800		5000	MHz	
Loop bandwidth (Int) ³	F _{BW}	F _{PHDET} /55	F _{PHDET} /44	F _{PHDET} /30	MHz	

AC Switching Characteristics

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Loop bandwidth (FRAC) ³	F _{BW}	F _{PHDET} /91	F _{PHDET} /77	F _{PHDET} /56	MHz	
Static phase offset of the PLL outputs ⁴	T _{SPO}			Max (±60 ps, ±0.5 degrees)	ps	
PLL output period jitter ^{10, 11}	T _{OUTJITTER}			±0.0125*output_period	ps	1.5 MHz ≤ F _{out} < 15 MHz
				135	ps	F _{out} ≥ 15 MHz
				±67.5	ps	
PLL output duty cycle precision	T _{OUTDUTY}	48		54	%	
PLL lock time ⁵	T _{LOCK}			Max (6.0 μs, 625 PFD cycles)	μs	
PLL unlock time ⁶	T _{UNLOCK}	2		8	PFD cycles	
PLL output frequency	F _{OUT}	0.050		1250	MHz	
Minimum power-down pulse width	T _{MPDPW}	1			μs	
Maximum delay in the feedback path ⁷	F _{MAXDFB}			1.5	PFD cycles	
Spread spectrum modulation spread ⁸	Mod_Spread	0.1		3.1	%	
Spread spectrum modulation frequency ⁹	Mod_Freq	F _{PHDET} /(128x63)	32	F _{PHDET} /(128)	KHz	

1. Minimum time for high or low pulse width.
2. Maximum jitter the PLL can tolerate without losing lock.
3. Default bandwidth setting of BW_PROP_CTRL = "01" for Integer and Fraction modes leads to the typical estimated bandwidth. This bandwidth can be lowered by setting BW_PROP_CTRL = "00" and can be increased if BW_PROP_CTRL = "10" and will be at the highest value if BW_PROP_CTRL = "11".
4. Maximum (±3-Sigma) phase error between any two outputs with nominally aligned phases.
5. Input clock cycle is REFDIV/F_{REF}. For example, F_{REF} = 25 MHz, REFDIV = 1, lock time = 10.0 (assumes LOCKCOUNTSEL setting = 4'd8 (256 cycles)).
6. Unlock occurs if two cycles slip within LOCKCOUNT/4 PFD cycles.
7. Maximum propagation delay of external feedback path in Deskew mode.
8. Programmable capability for depth of down spread or center spread modulation.
9. Programmable modulation rate based on the modulation divider setting (1 to 63).
10. Period jitter is measured at the output of the device using HSUL12 output buffers and includes the jitter effects of the reference clock source, PLL, clock routing networks, and output buffer. PLL is configured with internal feedback enabled and in integer mode. FPGA fabric is active during testing (75% utilization).

11. Jitter characteristics for protocol-specific industry standards are met due to improved input clock path and/or optimized VCO rates used. Characterization reports for specific protocols are available by contacting technical support.

Note: In order to meet all datasheet specifications, the PLL must be programmed such that the PLL Loop Bandwidth $< (0.0017 * \text{VCO Frequency}) - 0.4863 \text{ MHz}$. The Libero PLL configuration tool will enforce this rule when creating PLL configurations.

5.2.3 DLL

The following table provides information about DLL.

Table 5-19. DLL Electrical Characteristics

Parameter ¹	Symbol	Min	Typ	Max	Unit
Input reference clock frequency	F _{INF}	133		800	MHz
Input feedback clock frequency	F _{INFDBF}	133		800	MHz
Primary output clock frequency	F _{OUTPF}	133		800	MHz
Secondary output clock frequency ²	F _{OUTSF}	33.3		800	MHz
Input clock cycle-to-cycle jitter	F _{INJ}			200	ps
Output clock cycle-to-cycle jitter (with clean input clock)	T _{OUTJITTERCC}			Max (250 ps, 15% of clock period)	ps
Output clock period jitter (with clean input clock)	T _{OUTJITTERP}			Max (300 ps, 20% of clock period)	ps
Output clock-to-clock skew between two outputs with the same phase settings	T _{SKEW}			±150	ps
DLL lock time	T _{LOCK}	16		16K	Reference clock cycles
Minimum reset pulse width	T _{MRPW}	3			ns
Minimum input pulse width ³	T _{MIPW}	20			ns
Minimum input clock pulse width high	T _{MPWH}	400			ps
Minimum input clock pulse width low	T _{MPWL}	400			ps
Delay step size	T _{DEL}	12.7	30	35	ps
Maximum delay block delay ⁴	T _{DELMAX}	1.8		4.8	ns
Output clock duty cycle (with 50% duty cycle input) ⁵	T _{DUTY}	40		60	%
Output clock duty cycle (with 50% duty cycle input) ⁶	T _{DUTY50}	45		55	%

1. For all DLL modes.
2. Secondary output clock divided by four option.
3. On load, direction, move, hold, and update input signals.
4. 128 delay taps in one delay block.
5. Without duty cycle correction enabled.
6. With duty cycle correction enabled.

5.2.4 RC Oscillators

The following tables describe internal RC clock resources for user designs. They also describe system design with RF front-end information about emitters generated on-chip to support programming operations.

Table 5-20. 2 MHz RC Oscillator Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Operating frequency	RC _{2FREQ}		2		MHz
Accuracy	RC _{2FACC}	–4		4	%
Duty cycle	RC _{2DC}	46		54	%
Peak-to-peak output period jitter	RC _{2PJIT}		5	10	ns
Peak-to-peak output cycle-to-cycle jitter	RC _{2CJIT}		5	10	ns
Operating current (V _{DD25})	RC _{2IVPPA}			60	μA
Operating current (V _{DD})	RC _{2IVDD}			2.6	μA

Table 5-21. 160 MHz RC Oscillator Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Operating frequency	RC _{SCFREQ}		160		MHz
Accuracy	RC _{SCFACC}	–4		4	%
Duty cycle	RC _{SCDC}	47		52	%
Peak-to-peak output period jitter	RC _{SCPJIT}			600	ps
Peak-to-peak output cycle-to-cycle jitter	RC _{SCCJIT}			172	ps
Operating current (V _{DD25})	RC _{SCVPPA}			599	μA
Operating current (V _{DD18})	RC _{SCVPP}			0.1	μA
Operating current (V _{DD})	RC _{SCVDD}			60.7	μA

5.3 Fabric Specifications

The following section describes specifications for the fabric.

5.3.1 Math Blocks

The following table lists the maximum operating frequency (F_{MAX}) of the math block in the extended commercial temperature range (0 °C to 100 °C).

Table 5-22. Math Block Performance Extended Commercial Range (0 °C to 100 °C)

Modes	V _{DD} = 1.0 V – STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V – STD	V _{DD} = 1.05 V – 1	Unit
18 × 18 multiplication	370	470	440	500	MHz
18 × 18 multiplication summed with 48-bit input	370	470	440	500	MHz

AC Switching Characteristics

.....continued

Modes	V _{DD} = 1.0 V – STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V – STD	V _{DD} = 1.05 V – 1	Unit
18 × 19 multiplier pre-adder ROM mode	365	465	435	500	MHz
Two 9 × 9 multiplication	370	470	440	500	MHz
9 × 9 dot product (DOTP)	370	470	440	500	MHz
Complex 18 × 19 multiplication	360	455	430	500	MHz

The following table lists the maximum operating frequency (F_{MAX}) of the math block in the industrial temperature range (–40 °C to 100 °C).

Table 5-23. Math Block Performance Industrial Range (–40 °C to 100 °C)

Modes	V _{DD} = 1.0 V – STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V – STD	V _{DD} = 1.05 V – 1	Unit
18 × 18 multiplication	365	465	435	500	MHz
18 × 18 multiplication summed with 48-bit input	365	465	435	500	MHz
18 × 19 multiplier pre-adder ROM mode	355	460	430	500	MHz
Two 9 × 9 multiplication	365	465	435	500	MHz
9 × 9 DOTP	365	465	435	500	MHz
Complex 18 × 19 multiplication	350	450	425	500	MHz

The following table lists the maximum operating frequency (F_{MAX}) of the math block in the Automotive T2 temperature range (–40 °C to 125 °C).

Table 5-24. Math Block Performance Automotive T2 Range (–40 °C to 125 °C)

Modes	V _{DD} = 1.0 V – STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V – STD	V _{DD} = 1.05 V – 1	Unit
18 × 18 multiplication	365	465	435	500	MHz
18 × 18 multiplication summed with 48-bit input	365	465	435	500	MHz
18 × 19 multiplier pre-adder ROM mode	355	460	430	500	MHz
Two 9 × 9 multiplication	365	465	435	500	MHz
9 × 9 DOTP	365	465	435	500	MHz
Complex 18 × 19 multiplication	350	450	425	500	MHz

The following table lists the maximum operating frequency (F_{MAX}) of the math block in the Military temperature range (–55 °C to 125 °C).

Table 5-25. Math Block Performance Military Range (–55 °C to 125 °C)

Modes	V _{DD} = 1.0 V – STD	V _{DD} = 1.05 V – STD	Unit
18 × 18 multiplication	360	435	MHz

.....continued			
Modes	V _{DD} = 1.0 V – STD	V _{DD} = 1.05 V – STD	Unit
18 × 18 multiplication summed with 48-bit input	360	435	MHz
18 × 19 multiplier pre-adder ROM mode	355	430	MHz
Two 9 × 9 multiplication	360	435	MHz
9 × 9 DOTP	360	435	MHz
Complex 18 × 19 multiplication	345	425	MHz

5.3.2 SRAM Blocks

The following table lists the maximum operating frequency (F_{MAX}) of the LSRAM block for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-26. LSRAM Performance Industrial Temperature Range (–55 °C to 125 °C)

V _{DD} = 1.0 V – STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V – STD	V _{DD} = 1.05 V – 1	Unit	Condition
343	428	343	428	MHz	Two-port, all supported widths, pipelined, simple-write, and write-feed-through
309	428	309	428	MHz	Two-port, all supported widths, non-pipelined, simple-write, and write-feed-through
343	428	343	428	MHz	Dual-port, all supported widths, pipelined, simple-write, and write-feed-through
309	428	309	428	MHz	Dual-port, all supported widths, non-pipelined, simple-write, and write-feed-through
343	428	343	428	MHz	Two-port pipelined ECC mode, pipelined, simple-write, and write-feed-through
279	295	279	295	MHz	Two-port non-pipelined ECC mode, pipelined, simple-write, and write-feed-through
343	428	343	428	MHz	Two-port pipelined ECC mode, non-pipelined, simple-write, and write-feed-through
196	285	240	285	MHz	Two-port non-pipelined ECC mode, non-pipelined, simple-write, and write-feed-through
240	285	240	285	MHz	Two-port, all supported widths, pipelined, and read-before-write
240	285	240	285	MHz	Two-port, all supported widths, non-pipelined, and read-before-write
240	285	240	285	MHz	Dual-port, all supported widths, pipelined, and read-before-write
240	285	240	285	MHz	Dual-port, all supported widths, non-pipelined, and read-before-write

.....continued					
$V_{DD} = 1.0\text{ V}$ – STD	$V_{DD} = 1.0\text{ V}$ – 1	$V_{DD} = 1.05\text{ V}$ – STD	$V_{DD} = 1.05\text{ V}$ – 1	Unit	Condition
240	285	240	285	MHz	Two-port pipelined ECC mode, pipelined, and read-before-write
198	240	198	240	MHz	Two-port non-pipelined ECC mode, pipelined, and read-before-write
240	285	240	285	MHz	Two-port pipelined ECC mode, non-pipelined, and read-before-write
193	240	193	240	MHz	Two-port non-pipelined ECC mode, non-pipelined, and read-before-write

The following table lists the maximum operating frequency (F_{MAX}) of the μ SRAM block for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-27. μ SRAM Performance

Parameter	Symbol	$V_{DD} = 1.0\text{ V}$ – STD	$V_{DD} = 1.0\text{ V}$ – 1	$V_{DD} = 1.05\text{ V}$ – STD	$V_{DD} = 1.05\text{ V}$ – 1	Unit	Condition
Operating frequency	F_{MAX}	400	415	450	480	MHz	Write-port
Read access time	T_{ac}		2		2	ns	Read-port

The following table lists the maximum operating frequency (F_{MAX}) of the μ PROM block for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-28. μ PROM Performance

Parameter	Symbol	$V_{DD} = 1.0\text{ V}$ – STD	$V_{DD} = 1.0\text{ V}$ – 1	$V_{DD} = 1.05\text{ V}$ – STD	$V_{DD} = 1.05\text{ V}$ – 1	Unit
Read access time	T_{ac}	10	10	10	10	ns

5.4 Transceiver Switching Characteristics

This section describes transceiver switching characteristics.

5.4.1 Transceiver Performance

The following table describes transceiver performance.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-29. PolarFire Transceiver and TXPLL Performance

Parameter	Symbol	STD Min	STD Typ	STD Max	–1 Min	–1 Typ	–1 Max	Unit
Tx data rate ^{1,2}	F _{TXRate}	0.25		10.3125	0.25		12.7	Gbps
Tx OOB (serializer bypass) data rate	F _{TXRateOOB}	DC		1.5	DC		1.5	Gbps
Rx data rate when AC coupled ²	F _{RxRateAC}	0.25		10.3125	0.25		12.7	Gbps
Rx data rate when DC coupled	F _{RxRateDC}	0.25		3.2	0.25		3.2	Gbps
Rx OOB (deserializer bypass) data rate	F _{TXRateOOB}	DC		1.25	DC		1.25	Gbps
TXPLL output frequency ³	F _{TXPLL}	1.6		5.1563	1.6		6.35	GHz
Rx CDR mode	F _{RXCDR}	0.25		10.3125	0.25		10.3125	Gbps
Rx DFE and CDR auto-calibration modes ²	F _{RXAUTOCAL}	3.0		10.3125	3.0		12.7	Gbps
Rx Eye Monitor mode ²	F _{RXEyemon}	3.0		10.3125	3.0		12.7	Gbps
EQ far-end loopback data rate	F _{EQFELPB}	0.25		1.25	0.25		1.25	Gbps
EQ near-end loopback data rate	F _{EQNELPB}	0.25		10.3125	0.25		10.3125	Gbps
CDR far-end parallel loopback data rate ⁶	F _{CDRFELPB}	0.00625 ⁵		312.5			312.5	MHz
PCS reset minimum pulse width	MPW _{PCS_RESET}	16			16			[Tx Rx]_CLK Cycles ⁴
PMA reset minimum pulse width	MPW _{PMA_RESET}	16			16			[Tx Rx]_CLK Cycles ⁴

1. The reference clock is required to be a minimum of 75 MHz for data rates of 10 Gbps and above.
2. For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.
3. The Tx PLL rate is between 0.5x to 5.5x the Tx data rate. The Tx data rate depends on per XCVR lane Tx post-divider settings.
4. Minimum pulse width should reference TX_CLK when Tx only or both Tx and Rx are used. Reference RX_CLK if only Rx is used.
5. In 40-bit wide parallel mode.
6. The CDR far-end parallel loopback is clocked by the recovered clock of the CDR. The bandwidth of this loopback is equivalent to the clock multiplied by the data width.

5.4.2 Transceiver Reference Clock Performance

The following table describes performance of the transceiver reference clock.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-30. PolarFire Transceiver Reference Clock AC Requirements

Parameter	Symbol	STD Min	STD Typ	STD Max	-1 Min	-1 Typ	-1 Max	Unit
Reference clock input rate ^{1, 2}	F _{TXREFCLK}	20		400	20		400	MHz
Reference clock input rate ^{1, 2, 3}	F _{XCVRREFCLKMAX CASCADE}	20		156.3	20		156.3	MHz
Reference clock rate at the Tx PLL PFD ⁴	F _{TXREFCLKPFD}	20		156.3	20		175	MHz
Reference clock rate recommended at the PFD for Tx rates 10 Gbps and above ⁴	F _{TXREFCLKPFD10G}	75		156.3	75		175	MHz
Tx reference clock phase noise requirements to meet jitter specifications (156 MHz clock at reference clock input) ⁵	F _{TXREFPN}			-110			-110	dBc/Hz
Phase noise at 10 KHz	F _{TXREFPN}			-110			-110	dBc/Hz
Phase noise at 100 KHz	F _{TXREFPN}			-115			-115	dBc/Hz
Phase noise at 1 MHz	F _{TXREFPN}			-135			-135	dBc/Hz
Reference clock input rise time (10%–90%)	T _{REFRISE}		200	500		200	500	ps
Reference clock input fall time (90%–10%)	T _{REFFALL}		200	500		200	500	ps
Reference clock rate at RX CDR	F _{RXREFCLKCDR}	20		156.3	20		156.3	MHz

.....continued

Parameter	Symbol	STD Min	STD Typ	STD Max	–1 Min	–1 Typ	–1 Max	Unit
Reference clock duty cycle	T _{REFDUTY}	40		60	40		60	%
Spread spectrum modulation spread ⁶	Mod_Spread	0.1		3.1	0.1		3.1	%
Spread spectrum modulation frequency ⁷	Mod_Freq	TxREF CLKPFD/ (128)	32	TxREF CLKPFD/ (128*63)	TxREF CLKPFD/ (128)	32	TxREF CLKPFD/ (128*63)	KHz

1. See the maximum reference clock rate allowed per input buffer standard.
2. The minimum value applies to this clock when used as an XCVR reference clock. It does not apply when used as a non-XCVR input buffer (DC input allowed).
3. Cascaded reference clock.
4. After reference clock input divider.
5. To calculate the F_{TXREFPN} phase noise requirement at frequencies other than 156 MHz use the following formula: F_{TXREFPN} at f(MHz) = F_{TXREFPN} at 156 MHz + 20*log(f/156)
6. Programmable capability for depth of down-spread or center-spread modulation.
7. Programmable modulation rate based on the modulation divider setting (1 to 63).

5.4.3 Transceiver Reference Clock I/O Standards

The following differential I/O standards are supported as transceiver reference clocks.

- LVDS25/33
- HCLS25 (for PCIe)
- RSDS25/33
- MINILVDS25/33
- SUBLVDS25/33
- PPDS25/33
- SLVS25/33
- BUSLVDS25
- MLVDS25
- LVPECL33
- MIPI25

For DC input levels, see table Differential DC Input and Output Levels.

Note: The transceiver reference clock differential receiver supports V_{ICM} common mode.

Note: The amount of jitter from the input receiver increases at common modes of less 0.2 V or greater than V_{DD}SREF–0.4 V. Therefore, for improved SerDes operation, it is recommended that the V_{CM} of the signal into the SerDes reference clock input be at a minimum of 0.2 V and below V_{DD}SREF–0.4 V.

The following single-ended I/O standards are supported as transceiver reference clocks.

- LVTTTL
- LVCMOS33
- LVCMOS25
- LVCMOS18

- SSTL25/II
- SSTL18/II
- HSUL18/II

For DC input levels, see table DC Input and Output Levels.

Note: Generally, Hysteresis = Off is recommended. In extremely high noise systems with degraded reference clock input, Hysteresis = On may improve results.

5.4.4 Transmitter Performance

The following tables describe performance of the transmitter.

Table 5-31. Transceiver Reference Clock Input Termination

Parameter	Symbol	Min	Typ	Max	Unit
Single-ended termination	RefTerm		50		Ω
Single-ended termination	RefTerm		75		Ω
Single-ended termination	RefTerm		150		Ω
Differential termination	RefDiffTerm		115 ¹		Ω
Power-up termination			>50K		Ω

1. Measured at VCM= 1.2 V and VID= 350 mV.

Note: All pull-ups are disabled at power-up to allow hot plug capability.

The following tables describe the PolarFire Transceiver User Interface Clocks

Note: Until specified, all modes are non-deterministic. For more information, see [UG0677: PolarFire FPGA Transceiver User Guide](#).

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-32. Transceiver TX_CLK Range (Nondeterministic PCS Mode with Global or Regional Fabric Clocks)

Mode	STD Min	STD Max	–1 Min	–1 Max	Unit
8-bit, max data rate = 1.6 Gbps		200		200	MHz
10-bit, max data rate = 1.6 Gbps		160		160	MHz
16-bit, max data rate = 4.8 Gbps		300		300	MHz
20-bit, max data rate = 6.0 Gbps		300		300	MHz
32-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		325		325	MHz
40-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		260		320	MHz
64-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		165		200	MHz
80-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		130		160	MHz
Fabric pipe mode 32-bit, max data rate = 6.0 Gbps		150		150	MHz

AC Switching Characteristics

- For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-33. Transceiver RX_CLK Range (Non-Deterministic PCS Mode with Global or Regional Fabric Clocks)

Mode	STD Min	STD Max	–1 Min	–1 Max	Unit
8-bit, max data rate = 1.6 Gbps		200		200	MHz
10-bit, max data rate = 1.6 Gbps		160		160	MHz
16-bit, max data rate = 4.8 Gbps		300		300	MHz
20-bit, max data rate = 6.0 Gbps		300		300	MHz
32-bit, max data rate = 10.3125 Gbps		325		325	MHz
40-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		260		320	MHz
64-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		165		200	MHz
80-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		130		160	MHz
Fabric pipe mode 32-bit, max data rate = 6.0 Gbps		150		150	MHz

- For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

Table 5-34. Transceiver TX_CLK Range (Deterministic PCS Mode with Regional Fabric Clocks)

Mode	STD Min	STD Max	–1 Min	–1 Max	Unit
8-bit, max data rate = 1.6 Gbps		200		200	MHz
10-bit, max data rate = 1.6 Gbps		160		160	MHz
16-bit, max data rate = 3.6 Gbps (–STD) / 4.25 Gbps (–1)		225		266	MHz
20-bit, max data rate = 4.5 Gbps (–STD) / 5.32 Gbps (–1)		225		266	MHz
32-bit, max data rate = 7.2 Gbps (–STD) / 8.5 Gbps (–1)		225		266	MHz
40-bit, max data rate = 9.0 Gbps (–STD) / 10.6 Gbps (–1) ¹		225		266	MHz
64-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		165		200	MHz
80-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		130		160	MHz

- For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.

–STD speed grade is offered for Extended Commercial (E), Industrial (I), Military (M), and Automotive (T2) temperature grades.

–1 speed grade is offered for Extended Commercial (E), Industrial (I), and Automotive (T2) temperature grades only.

AC Switching Characteristics

Table 5-35. Transceiver RX_CLK Range (Deterministic PCS Mode with Regional Fabric Clocks)

Mode	STD Min	STD Max	-1 Min	-1 Max	Unit
8-bit, max data rate = 1.6 Gbps		200		200	MHz
10-bit, max data rate = 1.6 Gbps		160		160	MHz
16-bit, max data rate = 3.6 Gbps (–STD) / 4.25 Gbps (–1)		225		266	MHz
20-bit, max data rate = 4.5 Gbps (–STD) / 5.32 Gbps (–1)		225		266	MHz
32-bit, max data rate = 7.2 Gbps (–STD) / 8.5 Gbps (–1)		225		266	MHz
40-bit, max data rate = 9.0 Gbps (–STD) / 10.6 Gbps (–1) ¹		225		266	MHz
64-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		165		200	MHz
80-bit, max data rate = 10.3125 Gbps (–STD) / 12.7 Gbps (–1) ¹		130		160	MHz

- For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.

Table 5-36. PolarFire Transceiver Transmitter Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Differential termination	V _{OTERM}	68	85	102	Ω	85 Ω setting
	V _{OTERM}	80	100	120	Ω	100 Ω setting
	V _{OTERM}	120	150	180	Ω	150 Ω setting
Common mode voltage ¹	V _{OCM}	0.44 × V _{DDA}	0.525 × V _{DDA}	0.59 × V _{DDA}	V	DC coupled 50% setting
	V _{OCM}	0.52 × V _{DDA}	0.6 × V _{DDA}	0.66 × V _{DDA}	V	DC coupled 60% setting
	V _{OCM}	0.61 × V _{DDA}	0.7 × V _{DDA}	0.75 × V _{DDA}	V	DC coupled 70% setting
	V _{OCM}	0.63 × V _{DDA}	0.8 × V _{DDA}	0.83 × V _{DDA}	V	DC coupled 80% setting
Rise time ² Fall time ²	T _{TxRF}	40		61	ps	20% to 80%
		39		58	ps	80% to 20%
Differential peak-to-peak amplitude	V _{ODPP}	1080	1140	1320	mV	1000 mV setting
	V _{ODPP}	1010	1060	1220	mV	800 mV setting
	V _{ODPP}	550	580	670	mV	500 mV setting
	V _{ODPP}	465	490	560	mV	400 mV setting
	V _{ODPP}	350	370	425	mV	300 mV setting
	V _{ODPP}	250	260	300	mV	200 mV setting
	V _{ODPP}	150	160	185	mV	100 mV setting

AC Switching Characteristics

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Transmit lane P to N skew ³	T _{OSKEW}		8	15	ps	
Lane to lane transmit skew ⁴	T _{LLSKEW}			75	ps	Single PLL, 2–4 bonded lanes, 8–40-bit fabric width ¹⁰
				8	UI	Single PLL, 2–4 bonded lanes, 64–80-bit fabric width ¹¹
				8 + Refclk skew	UI	Multiple PLL, 2–4 bonded lanes, 8–40-bit fabric width ^{11, 12}
				32 + Refclk skew	UI	Multiple PLL, 2–4 bonded lanes, 64–80-bit fabric width ^{11, 12}
Electrical idle transition entry time ⁷	TTxEITrEntry			20	ns	
Electrical idle transition exit time ⁷	TTxEITrExit			19	ns	
Electrical idle amplitude	VTxEIpp			7	mV	
TXPLL lock time	T _{TXLock}			1600	PFD cycles	
Digital PLL lock time ⁸	T _{DPLLLock}			75,000	REFCLK UIs	Frequency lock
				150,000	REFCLK UIs	Phase lock
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J			0.22	UI	Data rate ≥10.3125 Gbps to 12.7 Gbps ⁹ (Tx V _{CO} rate 5.16 GHz to 6.35 GHz) TXPLL in integer mode
	T _{DJ}			0.1	UI	
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J			0.28	UI	Data rate ≥10.3125 to 12.7 Gbps ⁹ (Tx V _{CO} rate 5.16 GHz to 6.35 GHz) TXPLL in fractional mode
	T _{DJ}			0.1	UI	
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J			0.22	UI	Data rate ≥8.5 Gbps to 10.3125 Gbps (Tx V _{CO} rate 4.25 GHz to 5.16 GHz) TXPLL in integer mode
	T _{DJ}			0.09	UI	
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J			0.28	UI	Data rate ≥8.5 Gbps to 10.3125 Gbps (Tx V _{CO} rate 4.25 GHz to 5.16 GHz) TXPLL in fractional mode
	T _{DJ}			0.09	UI	

AC Switching Characteristics

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.21 0.09	UI UI	Data rate ≥5.0 Gbps to 8.5 Gbps (Tx V _{CO} rate 2.5 GHz to 4.25 GHz) TXPLL in integer mode
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.25 0.09	UI UI	Data rate ≥5.0 Gbps to 8.5 Gbps (Tx V _{CO} rate 2.5 GHz to 4.25 GHz) TXPLL in fractional mode
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.17 0.03	UI UI	Data rate ≥1.6 Gbps to 5.0 Gbps (Tx V _{CO} rate 1.6 GHz to 2.5 GHz) TXPLL in integer mode
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.2 0.03	UI UI	Data rate ≥1.6 Gbps to 5.0 Gbps (Tx V _{CO} rate 1.6 GHz to 2.5 GHz) TXPLL in fractional mode
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.08 0.02	UI UI	Data rate ≥ 800 Mbps to 1.6 Gbps (Tx V _{CO} rate 1.6 GHz) TXPLL in integer mode
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.11 0.02	UI UI	Data rate ≥ 800 Mbps to 1.6 Gbps (Tx V _{CO} rate 1.6 GHz) TXPLL in fractional mode
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.05 0.01	UI UI	Data rate = 250 Mbps to 800 Mbps (Tx V _{CO} rate 1.48 GHz to 1.6 GHz) TXPLL in integer mode
Total jitter ^{5, 6, 13} Deterministic jitter ^{5, 6}	T _J T _{DJ}			0.06 0.01	UI UI	Data rate = 250 Mbps to 800 Mbps (Tx V _{CO} rate 1.48 GHz to 1.6 GHz) TXPLL in fractional mode

1. Increased DC common mode settings above 50% reduce allowed V_{OD} output swing capabilities.
2. Adjustable through transmit emphasis.
3. With estimated package differences.
4. Single PLL applies to all four lanes in the same quad location with the same TxPLL. Multiple PLL applies to N lanes using multiple TxPLLs from different quad locations.
5. Improved jitter characteristics for a specific industry standard are possible in many cases due to improved reference clock or higher V_{CO} rate used.
6. Tx jitter is specified with all transmitters on the device enabled, a 10⁻¹²-bit error rate (BER) and Tx data pattern of PRBS7.
7. From the PMA mode, the TX_ELEC_IDLE port to the XVCR TXP/N pins.
8. FTxRefClk = 75 MHz with typical settings.

9. For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.
10. Transmit alignment in this case will automatically align upon the TX PLL obtaining lock. For details on transmit alignment, see UG0677: PolarFire FPGA Transceiver User Guide.
11. In order to obtain the required alignment for these configurations, an FPGA fabric TX alignment circuit must be implemented. For details on transmit alignment, see [UG0677: PolarFire FPGA Transceiver User Guide](#).
12. Refclk skew is the amount of skew between the reference clocks of the two PLL.
13. Jitter decomposition can be found in the protocol characterization reports.

5.4.5 Receiver Performance

The following table describes performance of the receiver.

Table 5-37. PolarFire Transceiver Receiver Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Input voltage range	V_{IN}	0		$V_{DDA} + 0.3$	V	
Differential peak-to-peak amplitude	V_{IDPP}	140		1250	mV	
Differential termination	V_{ITERM}	68	85	102	Ω	85 Ω setting
		80	100	120	Ω	100 Ω setting
		120	150	180	Ω	150 Ω setting
Common mode voltage	V_{ICMDC}^1	$0.7 \times V_{DDA}$		$0.9 \times V_{DDA}$	V	DC coupled
Exit electrical idle detection time	T_{EIDET}		50	100	ns	
Run length of consecutive identical digits (CID)	C_{ID}			200	UI	
CDR PPM tolerance ²	C_{DRPPM}			1.17	%UI	
CDR lock-to-data time ¹³	T_{LTD}	$512 * CDR_{REFDIV}$		$1024 * CDR_{REFDIV}$	CDR_{REFCLK} cycles	Disabled: Enhanced Receiver Management ¹⁴
		$(1900/T_{CDRREF} + (512 + (1020 * (W_{XCVRFABRX}/CDR_{FBDIV}))) * CDR_{REFDIV})$		$(5200/T_{CDRREF} + (1024 + (6380 * (W_{XCVRFABRX}/CDR_{FBDIV}))) * CDR_{REFDIV})$		Enabled: Enhanced Receiver Management ¹⁴

AC Switching Characteristics

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Condition
CDR lock-to-ref time ¹³	T _{LTF}	$(1000/T_{CDRREF}) + (1024 * CDR_{REFDIV})$		$(13000/T_{CDRREF}) + (1536 * CDR_{REFDIV})$	CDR _{REFCLK} cycles	
High-gain lock time	T _{HGLT}	10.8			ns	For Burst mode receiver (BMR)
High-gain state time ¹²	T _{HGSTATE}			3264	ns	For Burst mode receiver (BMR)
Loss-of-signal detect (peak detect range setting= high) ^{9,10}	V _{DETHIGH}	145		295	mV	Setting= 3
		155		340	mV	Setting= 4
		180		365	mV	Setting= 5
		195		375	mV	Setting= 6
		210		385	mV	Setting= 7
Loss-of-signal detect (peak detect range setting= low) ^{9,10}	V _{DETLOW}	65		175	mV	Setting= PCIe ^{3, 7}
		95		190	mV	Setting= SATA ^{4, 8}
		75		170	mV	Setting= 1
		95		185	mV	Setting= 2
		100		190	mV	Setting= 3
		140		210	mV	Setting= 4
		155		240	mV	Setting= 5
		165		245	mV	Setting= 6
		170		250	mV	Setting= 7

AC Switching Characteristics

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Sinusoidal jitter tolerance	$T_{\text{SJ TOL}}$	0.34			UI	>8.5 Gbps – 12.7 Gbps ^{5, 11}
		0.43			UI	>8.0–8.5 Gbps ⁵
		0.45			UI	>3.2–8.0 Gbps ⁵
		0.45			UI	>1.6 to 3.2 Gbps ⁵
		0.42			UI	>0.8 to 1.6 Gbps ⁵
		0.41			UI	250 to 800 Mbps ⁵
Total jitter tolerance with stressed eye	$T_{\text{TJ TOL SE}}$	0.65			UI	3.125 Gbps ⁵
		0.65			UI	6.25 Gbps ⁶
		0.7			UI	10.3125 Gbps ⁶
		0.7			UI	12.7 Gbps ^{6, 11}
Sinusoidal jitter tolerance with stressed eye	$T_{\text{SJ TOL SE}}$	0.1			UI	3.125 Gbps ⁵
		0.05			UI	6.25 Gbps ⁶
		0.05			UI	10.3125 Gbps ⁶
		0.05			UI	12.7 Gbps ^{6, 11}
CTLE DC gain (all stages, max settings)		0.1		10	dB	
CTLE AC gain (all stages, max settings)		0.05		16	dB	
DFE AC gain (per 5 stages, max settings)		0.05		7.5	dB	
Auto adaptive calibration time (CTLE)	T_{CTLE}	12		45	ms	
Auto adaptive calibration time (CTLE+DFE)	$T_{\text{CTLE+DFE}}$		1.4		s	

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Enhanced receiver management control clock input (CTRL_CLK)	F _{ERMCTRLCLK}	38.4	40	41.6	MHz	

1. Valid at 3.2 Gbps and below.
2. Data vs Rx reference clock frequency.
3. Achieves compliance with PCIe electrical idle detection.
4. Achieves compliance with SATA OOB specification.
5. Rx jitter values based on bit error ratio (BER) of 10–12, AC-coupled input with 400 mV V_{ID}, all stages of Rx CTLE enabled, DFE disabled, 80 MHz sinusoidal jitter injected to Rx data.
6. Rx jitter values based on bit error ratio (BER) of 10–12, AC-coupled input with 400 mV V_{ID}, all stages of Rx CTLE enabled, DFE enabled, 80 MHz sinusoidal jitter injected to Rx data.
7. For PCIe: Low Threshold Setting= 0, High Threshold Setting= 2.
8. For SATA: Low Threshold Setting= 2, High Threshold Setting= 3.
9. Loss of signal is valid for data rates of 1 Gbps to 5 Gbps for PRBS7 (8B/10B) or PRBS31 (64b/6xb) data formats. It is also valid for detection of SATA out-of-band signals at data rates up to 6 Gbps. If the default settings for the low threshold (0x0) and high threshold (0x2) using the low range option for the peak detector are used, then the Rx V_{Amplitude} pk-pk (outside of data eye) at the receiver input package pins must be a minimum of 300 mV for short reach (6.5 dB insertion loss at 5 GHz) applications, 350 mV for medium reach (17.0 dB insertion loss at 5 GHz) applications, and 450 mV for long reach (25.0 dB insertion loss at 5 GHz) applications—generally the settings are less limiting than what is required for good BER operation of the SerDes. Note that if the option to force CDR Lock2Ref upon Rx Idle is set (default at data rates of 5 Gbps and below), this minimum V_{Amplitude} pk-pk must be enforced for proper CDR operation.
10. Detect values measured at 1.5 Gbps with PRBS7 data pattern.
11. For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.
12. T_{HGSTATE} is based on the condition where the CDR was in lock (to reference or data) for at least 5.2 μs before moving to the high-gain state. At this point, if the receive data is outside the ppm tolerance of the CDR, the CDR will unlock after the time specified by the parameter.
13. The following definitions apply:
 - 13.1. T_{CDRREF} is the transceiver CDR reference clock period in nanoseconds.
 - 13.2. W_{XCVRFABRX} is the parallel interface width of the transceiver receive fabric interface.
 - 13.3. CDR_{FBDIV} is the feedback divider of the transceiver.
 - 13.4. CDR_{CDRREFDIV} is the reference divider of the transceiver CDR.
14. For details on the Enhanced Receiver Management feature, refer to UG0677: PolarFire FPGA Transceiver User Guide.

5.4.6 Transceiver and Receiver Return Loss Characteristics

This section describes transmitter and receiver return loss characteristics compliant with OIF-CEI-03.1.

Figure 5-4. Differential Return Loss

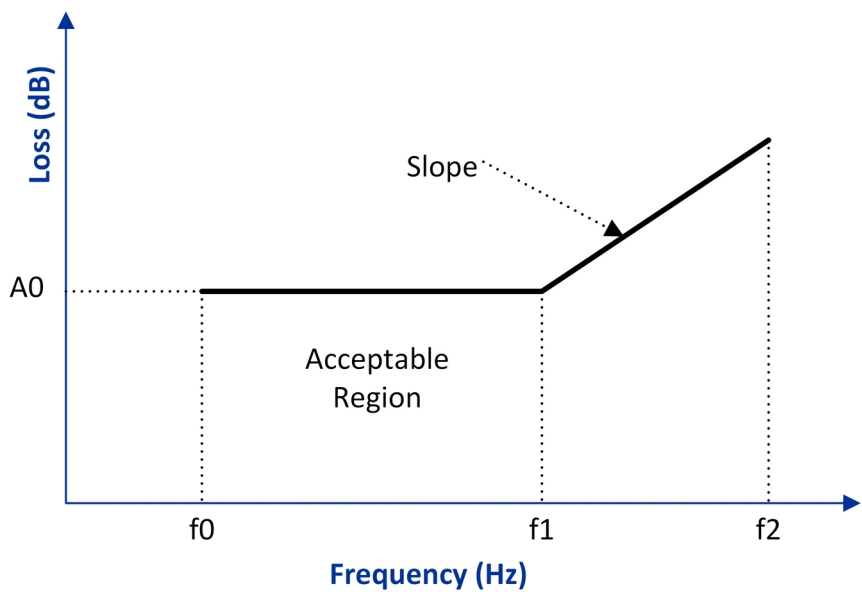


Table 5-38. Differential Return Loss

Parameter	Value	Unit
A0	−8	dB
f0	100	MHz
f1	$(3/4) * T_Baud$	Hz
f2	T_Baud	Hz
Slope	16.6	dB/dec

Figure 5-5. Common Mode Return Loss

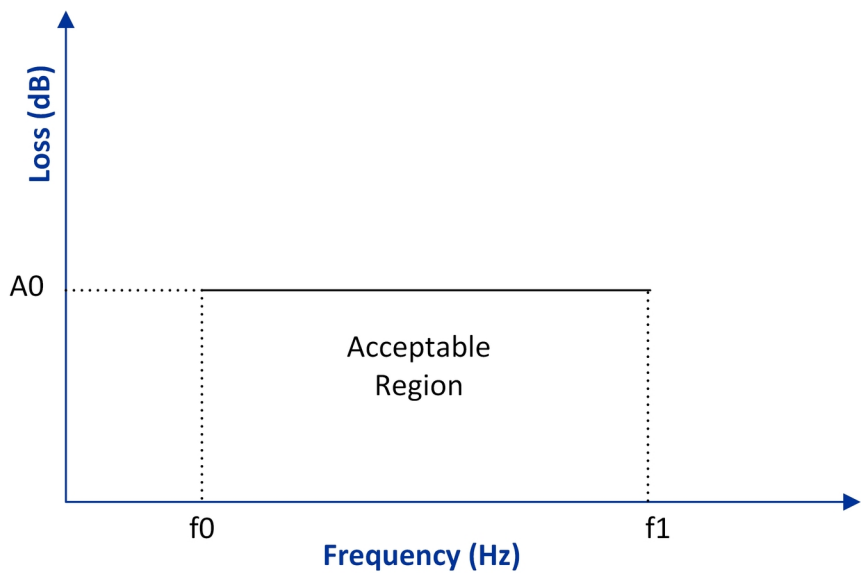


Table 5-39. Common Mode Return Loss

Parameter	Value	Unit
A0	−6	dB
f0	100	MHz
f1	$(3/4) * T_{\text{Baud}}$	Hz

5.5 Transceiver Protocol Characteristics

The following section describes transceiver protocol characteristics.

5.5.1 PCI Express

The following tables describe the PCI express.

Table 5-40. PCI Express Gen1

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	2.5 Gbps		0.25	UI
Receiver jitter tolerance	2.5 Gbps	0.4		UI

Note: With add-in card, as specified in PCI Express CEM Rev 2.0.

Table 5-41. PCI Express Gen2

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	5.0 Gbps		0.35	UI
Receiver jitter tolerance	5.0 Gbps	0.4		UI

Note: With add-in card as specified in PCI Express CEM Rev 2.0.

5.5.2 Interlaken

The following table describes Interlaken.

Table 5-42. Interlaken

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	6.375 Gbps		0.3	UI
	10.3125 Gbps		0.3	UI
	12.7 Gbps ^{1, 2}		0.3	UI
Receiver jitter tolerance	6.375 Gbps	0.6		UI
	10.3125 Gbps	0.65		UI
	12.7 Gbps ^{1, 2}	0.65		UI

1. For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.
2. Supported on –1 speed grade only.

5.5.3 10GbE (10GBASE-R and 10GBASE-KR)

The following table describes 10GbE (10GBASE-R).

Table 5-43. 10GbE (10GBASE-R)

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	10.3125 Gbps		0.28	UI
Receiver jitter tolerance	10.3125 Gbps	0.7		UI

The following table describes 10GbE (10GBASE-KR).

Table 5-44. 10GbE (10GBASE-KR)

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	10.3125 Gbps		0.28	UI
Receiver jitter tolerance (SJ)	10.3125 Gbps	0.115		UI
Receiver jitter tolerance (RJ)	10.3125 Gbps	0.13		UI
Receiver jitter tolerance (DCD)	10.3125 Gbps	0.035		UI

The following table describes 10GbE (XAUI).

Table 5-45. 10GbE (XAUI)

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter (near end)	3.125 Gbps		0.35	UI
Total transmit jitter (far end)			0.55	UI
Receiver jitter tolerance	3.125 Gbps	0.65		UI

The following table describes 10GbE (RXAUI).

Table 5-46. 10GbE (RXAUI)

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter (near-end)	6.25 Gbps		0.35	UI
Total transmit jitter (far-end)	6.25 Gbps		0.55	UI
Receiver jitter tolerance	6.25 Gbps	0.65		UI

5.5.4 1GbE (1000BASE-X)

The following table describes 1GbE (1000BASE-X).

Table 5-47. 1GbE (1000BASE-X)

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	1.25 Gbps		0.24	UI

.....continued

Parameter	Data Rate	Min	Max	Unit
Receiver jitter tolerance	1.25 Gbps	0.749		UI

5.5.5 SGMII and QSGMII

The following table describes SGMII.

Table 5-48. SGMII

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	1.25 Gbps		0.24	UI
Receiver jitter tolerance	1.25 Gbps	0.749		UI

The following table describes QSGMII.

Table 5-49. QSGMII

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	5.0 Gbps		0.3	UI
Receiver jitter tolerance	5.0 Gbps	0.65		UI

5.5.6 CPRI

The following table describes CPRI.

Table 5-50. CPRI

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	0.6144 Gbps		0.35	UI
	1.2288 Gbps		0.35	UI
	2.4576 Gbps		0.35	UI
	3.0720 Gbps		0.35	UI
	4.9152 Gbps		0.3	UI
	6.1440 Gbps		0.3	UI
	8.11008 Gbps		0.335	UI
	9.8304 Gbps		0.335	UI

.....continued

Parameter	Data Rate	Min	Max	Unit
Receive jitter tolerance	0.6144 Gbps	0.75		UI
	1.2288 Gbps	0.75		UI
	2.4576 Gbps	0.75		UI
	3.0720 Gbps	0.75		UI
	4.9152 Gbps	0.7		UI
	6.1440 Gbps	0.7		UI
	8.11008 Gbps	0.7		UI
	9.8304 Gbps	0.7		UI

5.5.7 JESD204B

The following table describes JESD204B.

Table 5-51. JESD204B

Parameter	Data Rate	Min	Max	Unit
Total transmit jitter	3.125 Gbps		0.35	UI
	6.25 Gbps		0.3	UI
	12.5 Gbps ^{1, 2}		0.3	UI
Receive jitter tolerance	3.125 Gbps	0.56		UI
	6.25 Gbps	0.6		UI
	12.5 Gbps ^{1, 2}	0.7		UI

1. For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.
2. Supported on –1 speed grade only.

5.5.8 Display Port

The following table describes Display Port.

Table 5-52. Display Port

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	1.62 Gbps	Test point: TP2		0.27	UI
	2.7 Gbps	Test point: TP2		0.42	UI
	5.4 Gbps	Test point: TP3_EQ		0.62 ¹	UI
	8.1 Gbps	Test point: TP3_CTLE		0.47	UI

.....continued

Parameter	Data Rate	Condition	Min	Max	Unit
Total receive jitter tolerance	1.62 Gbps	SJ at 20 MHz	0.747		UI
	2.7 Gbps	SJ at 100 MHz	0.491		UI
	5.4 Gbps	SJ at 10 MHz	0.636		UI
		SJ at 100 MHz	0.62		UI
	8.1 Gbps	SJ at 15 MHz	0.62		UI

1. Total transmit jitter includes 0.04 UI from cable crosstalk effect.

5.5.9 Serial RapidIO

The following table describes Serial RapidIO.

Table 5-53. Serial RapidIO

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	1.25 Gbps			0.35	UI
	2.5 Gbps			0.35	UI
	3.125 Gbps			0.35	UI
	5.0 Gbps			0.3	UI
	6.25 Gbps			0.3	UI
	10.3125 Gbps			0.28	UI
Receive jitter tolerance	1.25 Gbps		0.65		UI
	2.5 Gbps		0.65		UI
	3.125 Gbps		0.65		UI
	5.0 Gbps	Short reach	0.6		UI
		Long reach	0.95		UI
	6.25 Gbps	Short reach	0.6		UI
		Long reach	0.95		UI
	10.3125 Gbps	Short reach	0.62		UI

5.5.10 SDI

The following table describes SDI.

Table 5-54. SDI

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	270 Mbps	Timing jitter (10 Hz–27 MHz)		0.2	UI
		Alignment jitter (1 KHz–27 MHz)		0.2	UI
	1.485 Gbps	Timing jitter (10 Hz–148.5 MHz)		1.0	UI
		Alignment jitter (100 KHz–148.5 MHz)		0.2	UI
	2.97 Gbps	Timing jitter (10 Hz–297 MHz)		2.0	UI
		Alignment jitter (100 KHz–297 MHz)		0.3	UI
	5.94 Gbps	Timing Jitter (10 Hz - 594 MHz)		2.0	UI
		Alignment Jitter (100 KHz - 594 MHz)		0.3	UI
	11.88 Gbps	Timing Jitter (10 Hz - 1188 MHz)		2.0	UI
		Alignment Jitter (100 KHz - 1188 MHz)		0.3	UI
Receive jitter tolerance	270 Mbps	Alignment jitter	0.2		UI
	1.485 Gbps	Alignment jitter	0.2		UI
	2.97 Gbps	Alignment jitter	0.3		UI
	5.94 Gbps	Alignment jitter	0.3		UI
	11.88 Gbps	Alignment jitter	0.3		UI

5.5.11 OTN

The following table describes OTN.

Table 5-55. OTN

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	2.66 Gbps	3 dB BW: 5 KHz to 20 MHz		0.3	UI
		3 dB BW: 1 MHz to 20 MHz		0.1	UI
	10.70 Gbps ²	3 dB BW: 20 KHz to 80 MHz		0.3	UI
		3 dB BW: 4 MHz to 80 MHz		0.1	UI
	11.09 Gbps ¹	3 dB BW: 20 KHz to 80 MHz		0.3	UI
		3 dB BW: 4 MHz to 80 MHz		0.1	UI
Receive jitter tolerance	2.66 Mbps	SJ at 5 KHz	1.5		UI
		SJ at 20 MHz	0.15		UI
	10.70 Gbps ²	SJ at 20 KHz	1.5		UI
		SJ at 80 MHz	0.15		UI
	11.09 Gbps ^{1, 2}	SJ at 20 KHz	1.5		UI
		SJ at 80 MHz	0.15		UI

1. For data rates greater than 10.3125 Gbps, VDDA must be set to 1.05 V mode. See supply tolerance in the section Recommended Operating Conditions.
2. Supported on –1 speed grade only.

5.5.12 Fiber Channel

The following table describes Fiber Channel.

Table 5-56. Fiber Channel

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	1.0625 Gbps			0.23	UI
	2.125 Gbps			0.33	UI
	4.25 Gbps			0.52	UI
	8.5 Gbps			0.31	UI
Receive jitter tolerance	1.0625 Gbps	0.68			UI
	2.125 Gbps	0.62			UI
	4.24 Gbps	0.62			UI
	8.5 Gbps	0.71			UI

5.5.13 HiGig and HiGig+

The following table describes HiGig and HiGig+.

Table 5-57. HiGig and HiGig+

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	3.75 Gbps	Near-end		0.35	UI
	3.75 Gbps	Far-end		0.55	UI
Receive jitter tolerance	3.75 Gbps		0.65		UI

5.5.14 HiGig II

The following table describes HiGig II.

Table 5-58. HiGig II

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	6.875 Gbps	Near-end		0.35	UI
	6.875 Gbps	Far-end		0.55	UI
Receive jitter tolerance	6.875 Gbps		0.65		UI

5.5.15 Firewire IEEE 1394

The following table describes Firewire.

Table 5-59. FireWire IEEE 1394

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	196.608 Mbps	S200 Near-end ¹		200	ps
	393.22 Mbps	S400 Near-end ²		516	ps
	786.43 Mbps	S800 Near-end ^{2, 3}		200	ps
Receive jitter tolerance	196.608 Mbps	S200 ¹	500		ps
	393.22 Mbps	S400 ²	1025		ps
	786.43 Mbps	S800 ²	375		ps

1. DS mode.
2. Beta mode.
3. PolarFire complies with 1394 S800 electrical requirements with the exception of TX eye requirement. Refer to the FireWire characterization report on the PolarFire documentation page for more details.

5.5.16 SLVS-EC

The following table describes SLVS-EC.

Table 5-60. SLVS-EC

Parameter	Data Rate	Condition	Min	Max	Unit
Total transmit jitter	2.376 Gbps			0.4	ps

.....continued					
Parameter	Data Rate	Condition	Min	Max	Unit
Receive jitter tolerance	2.376 Gbps	0.15 SJ at 2 MHz	0.5		ps
	5.0 Gbps	0.15 SJ at 4 MHz	0.5		ps

5.6 Non-Volatile Characteristics

The following section describes non-volatile characteristics.

5.6.1 FPGA Programming Cycle and Retention

The following table describes FPGA programming cycle and retention.

Retention characteristics for Military-grade devices and Automotive-grade devices at the absolute maximum junction temperature of 125 °C can be profiled using the PolarFire Retention Calculator, which can be obtained through technical support at soc.microsemi.com/Portal/Default.aspx.

Table 5-61. FPGA Programming Cycles vs Retention Characteristics

Programming T _J	Programming Cycles, Max	Retention Years	Retention Years at T _J
0 °C to 85 °C	1000	20	85 °C
0 °C to 100 °C	500	20	100 °C
–20 °C to 100 °C	500	20	100 °C
–40 °C to 100 °C	500	20	100 °C
–40 °C to 85 °C	1000	16	100 °C
–40 °C to 55 °C	2000	12	100 °C
–40 °C to 100 °C	500	20	100 °C
–40 °C to 100 °C	500	10	110 °C
–40 °C to 100 °C	500	Note 2	125 °C

Notes:

- Power supplied to the device must be valid during programming operations such as programming and verify . Programming recovery mode is available only for in-application programming mode and requires an external SPI flash.
- Contact technical support at soc.microsemi.com/Portal/Default.aspx.

5.6.2 FPGA Programming Time

The following tables describe FPGA programming time. For allowable programming junction temperature (T_J), see previous table [FPGA Programming Cycles vs Retention Characteristics](#).

Table 5-62. Master SPI Programming Time (IAP)

Parameter	Symbol	Devices	Typ	Max	Unit
Programming time	T_{PROG}	MPF100T, TL, TS, TLS	17	25	s
		MPF200T, TL, TS, TLS	17	25	s
		MPF300T, TL, TS, TLS	26	32	s
		MPF500T, TL, TS, TLS	31	37	s

Table 5-63. Slave SPI Programming Time

Parameter	Symbol	Devices	Typ	Max	Unit
Programming time	T_{PROG}	MPF100T, TL, TS, TLS ¹	27	33	s
		MPF200T, TL, TS, TLS ¹	41	50	s
		MPF300T, TL, TS, TLS ¹	50	60	s
		MPF500T, TL, TS, TLS ¹	90	108	s

1. SmartFusion2 as SPI Master with MSS running at 100 MHz, MSS_SPI_0 port running at 6.67 MHz. Bitstream stored in DDR. DirectC version 4.1.
2. Programmer: FlashPro5 with TCK 10 MHz. PC Configuration: Intel i7 at 3.6 GHz, 32 GB RAM, Windows 10.

Table 5-64. JTAG Programming Time

Parameter	Symbol	Devices	Typ	Max	Unit
Programming time	T_{PROG}	MPF100T, TL, TS, TLS ¹	35	42	s
		MPF200T, TL, TS, TLS ¹	56	68	s
		MPF300T, TL, TS, TLS ¹	95	114	s
		MPF500T, TL, TS, TLS ¹	122	147	s

1. Programmer: FlashPro5 with TCK 10 MHz. PC Configuration: Intel i7 at 3.6 GHz, 32 GB RAM, Windows 10.

5.6.3 FPGA Bitstream Sizes

The following table describes FPGA bitstream sizes.

Table 5-65. Initialization Client Sizes

Device	Plaintext	Ciphertext
MPF100T, TL, TS, TLS	1580 KB	1630 KB
MPF200T, TL, TS, TLS	2916 KB	3006 KB
MPF300T, TL, TS, TLS	4265 KB	4403 KB
MPF500T, TL, TS, TLS	6835 KB	7045 KB

Note: Worst case initializing all fabric LSRAM, USRAM, and UPROM.

Table 5-66. Bitstream Sizes

File	Devices	FPGA	Security	SNVM (all pages)	FPGA+ SNVM	FPGA+ Sec	SNVM+ Sec	FPGA+ SNVM+ Sec
SPI	MPF100T, TL, TS, TLS	3.4 MB	3.5 KB	59.7 KB	3.5 MB	3.5 MB	62.2 KB	3.5 MB
DAT	MPF100T, TL, TS, TLS	3.4 MB	7.6 KB	61.2 KB	3.5 MB	3.4 MB	66.3 KB	3.5 MB
SPI	MPF200T, TL, TS, TLS	5.9 MB	3.5 KB	59.7 KB	5.9 MB	5.9 MB	62.2 KB	6.0 MB
DAT	MPF200T, TL, TS, TLS	5.9 MB	7.6 KB	61.2 KB	6.0 MB	5.9 MB	66.3 KB	6.0 MB
SPI	MPF300T, TL, TS, TLS	9.3 MB	3.5 KB	59.7 KB	9.6 MB	9.5 MB	62.2 KB	9.6 MB
DAT	MPF300T, TL, TS, TLS	9.3 MB	7.6 KB	61.2 KB	9.6 MB	9.5 MB	66.3 KB	9.6 MB
SPI	MPF500T, TL, TS, TLS	14.3 MB	3.5 KB	59.7 KB	14.4 MB	14.3 MB	62.2 KB	14.4 MB
DAT	MPF500T, TL, TS, TLS	14.3 MB	7.6 KB	61.2 KB	14.4 MB	14.3 MB	66.3 KB	14.4 MB

5.6.4 Digest Cycles

Digests verify the integrity of the programmed non-volatile data. Digests are a cryptographic hash of various data areas. Any digest that reports back an error raises the digest tamper flag. Digests are operational only from –40 °C to 100 °C.

Table 5-67. Maximum Number of Digest Cycles

Retention Since Programmed (N = Number Digests During that Time) ¹									
Storage and Operating T _J	N ≤ 300	N = 500	N = 1000	N = 1500	N = 2000	N = 4000	N = 6000	Unit	Retention
–40 to 100	20 × LF	17 × LF	12 × LF	10 × LF	8 × LF	4 × LF	2 × LF	°C	Years
0 to 100	20 × LF	17 × LF	12 × LF	10 × LF	8 × LF	4 × LF	2 × LF	°C	Years
–40 to 85	20 × LF	20 × LF	20 × LF	20 × LF	16 × LF	8 × LF	4 × LF	°C	Years
–40 to 55	20 × LF	20 × LF	20 × LF	20 × LF	20 × LF	20 × LF	20 × LF	°C	Years
–40 to 110	10 × LF	8.5 × LF	6 × LF	5 × LF	4 × LF	2 × LF	1 × LF	°C	Years
–40 to 125	Note 2								

.....continued

Retention Since Programmed (N = Number Digests During that Time) ¹									
Storage and Operating T _J	N ≤ 300	N = 500	N = 1000	N = 1500	N = 2000	N = 4000	N = 6000	Unit	Retention
–55 to 110	10 × LF	8.5 × LF	6 × LF	5 × LF	4 × LF	2 × LF	1 × LF	°C	Years
–55 to 125	Note 2								

1. LF = Lifetime factor as defined by the number of programming cycles the device has seen under the conditions listed in the following table.
2. Contact technical support at soc.microsemi.com/Portal/Default.aspx

Table 5-68. FPGA Programming Cycles Lifetime Factor

Programming T _J	Programming Cycles	LF
–40 °C to 100 °C	500	1
–40 °C to 85 °C	1000	0.8
–40 °C to 55 °C	2000	0.6

Notes:

- The maximum number of accumulated device digest cycles is 100K. The maximum number of digests is 10K cycles between programming non-volatile data (Fabric sNVM, User keys, User Locks, and so on).
- Digests are operational only over the –40 °C to 100 °C temperature range.
- After a program cycle, an additional N digests cycles are allowed with the resultant retention characteristics for the total operating and storage temperature shown.
- Retention is specified for total device storage and operating temperature.
- All temperatures are junction temperatures (T_J).
- Example 1—500 digests cycles are performed between programming cycles. N = 500. The operating conditions are –40 °C to 85 °C T_J. 501 programming cycles have occurred. The retention under these operating conditions is 20 × LF = 20 × .8 = 16 years.
- Example 2—one programming cycle has occurred, N = 1500 digest cycles have occurred. Temperature range is –40 °C to 100 °C. The resultant retention is 10 × LF or 10 years over the industrial temperature range.

5.6.5 Digest Time

The following table describes digest time.

Table 5-69. Digest Times

Parameter	Devices	Typ	Max	Unit
Setup time	All	2		μs
Fabric digest run time	MPF100T, TL, TS, TLS	880	910	ms
	MPF200T, TL, TS, TLS	1005	1072	ms
	MPF300T, TL, TS, TLS	1503.9	1582	ms
	MPF500T, TL, TS, TLS	2085	2150	ms

.....continued

Parameter	Devices	Typ	Max	Unit
UFS CC digest run time	MPF100T, TL, TS, TLS	33.5	35	μs
	MPF200T, TL, TS, TLS	33.5	35	μs
	MPF300T, TL, TS, TLS	33.5	35	μs
	MPF500T, TL, TS, TLS	33.5	35	μs
sNVM digest run time ¹	MPF100T, TL, TS, TLS	4.5	5	ms
	MPF200T, TL, TS, TLS	4.5	5	ms
	MPF300T, TL, TS, TLS	4.5	5	ms
	MPF500T, TL, TS, TLS	4.5	5	ms
UFS UL digest run time	MPF100T, TL, TS, TLS	47	49	μs
	MPF200T, TL, TS, TLS	47	49	μs
	MPF300T, TL, TS, TLS	47	49	μs
	MPF500T, TL, TS, TLS	47	49	μs
User key digest run time ²	MPF100T, TL, TS, TLS	526	544	μs
	MPF200T, TL, TS, TLS	526	544	μs
	MPF300T, TL, TS, TLS	526	544	μs
	MPF500T, TL, TS, TLS	526	544	μs
UFS UPERM digest run time	MPF100T, TL, TS, TLS	33.2	35	μs
	MPF200T, TL, TS, TLS	33.2	35	μs
	MPF300T, TL, TS, TLS	33.2	35	μs
	MPF500T, TL, TS, TLS	33.2	35	μs
Factory digest run time	MPF100T, TL, TS, TLS	494	511	μs
	MPF200T, TL, TS, TLS	494	511	μs
	MPF300T, TL, TS, TLS	494	511	μs
	MPF500T, TL, TS, TLS	494	511	μs

1. The entire sNVM is used as ROM.
2. Valid for user key 0 through 6.

Note: These times do not include the power-up to functional timing overhead when using digest checks on power-up.

5.6.6 Zeroization Time

This section describes zeroization time. A zeroization operation counts as one programming cycle.

Table 5-70. Zeroization Times for MPF100T, TL, TS, and TLS Devices

Parameter	Typ	Max	Unit	Conditions
Time to enter zeroization	8	9	ms	Zip flag set
Time to destroy the fabric data ¹	248	253	ms	Data erased
Time to destroy data in non-volatile memory (like new) ^{1, 2}	507	522	ms	One iteration of scrubbing
Time to destroy data in non-volatile memory (non-recoverable) ^{1, 3}	520	536	ms	One iteration of scrubbing
Time to scrub the fabric data ¹	0.8	0.9	s	Full scrubbing
Time to scrub the pNVM data (like new) ^{1, 2}	1.5	1.6	s	Full scrubbing
Time to scrub the fabric data pNVM data (non-recoverable) ^{1, 3}	1.7	1.8	s	Full scrubbing
Time to verify ⁵	1.1	1.2	s	
Total time to zeroize (like new) ^{1, 2}	2.8	2.9	s	
Total time to zeroize (non-recoverable) ^{1, 3}	3.1	3.2	s	

1. Total completion time after entering zeroization.
2. Like new mode—zeroizes user design security setting and sNVM content.
3. Non-recoverable mode—zeroizes user design security setting, sNVM and factory keys, and factory data required for programming.
4. Time to verify after scrubbing completes.

Table 5-71. Zeroization Times for MPF200T, TL, TS, and TLS Devices

Parameter	Typ	Max	Unit	Conditions
Time to enter zeroization	8	9	ms	Zip flag set
Time to destroy the fabric data ¹	250	255	ms	Data erased
Time to destroy data in non-volatile memory (like new) ^{1, 2}	507	522	ms	One iteration of scrubbing
Time to destroy data in non-volatile memory (non-recoverable) ^{1, 3}	520	536	ms	One iteration of scrubbing
Time to scrub the fabric data ¹	0.9	1.0	s	Full scrubbing
Time to scrub the pNVM data (like new) ^{1, 2}	1.5	1.6	s	Full scrubbing
Time to scrub the fabric data PNVM data (non-recoverable) ^{1, 3}	1.7	1.8	s	Full scrubbing
Time to verify ⁵	1.4	1.5	s	
Total time to zeroize (like new) ^{1, 2}	2.9	3.0	s	
Total time to zeroize (non-recoverable) ^{1, 3}	3.1	3.2	s	

1. Total completion time after entering zeroization.
2. Like new mode—zeroizes user design security setting and sNVM content.
3. Non-recoverable mode—zeroizes user design security setting, sNVM and factory keys, and factory data required for programming.
4. Time to verify after scrubbing completes.

Table 5-72. Zeroization Times for MPF300T, TL, TS, and TLS Devices

Parameter	Typ	Max	Unit	Conditions
Time to enter zeroization	8	9	ms	Zip flag set
Time to destroy the fabric data ¹	390	420	ms	One iteration of scrubbing
Time to destroy data in non-volatile memory (like new) ^{1, 2}	507	522	ms	One iteration of scrubbing
Time to destroy data in non-volatile memory (non-recoverable) ^{1, 3}	520	536	ms	One iteration of scrubbing
Time to scrub the fabric data ¹	1.3	1.4	s	Full scrubbing
Time to scrub the pNVM data (like new) ^{1, 2}	1.5	1.6	s	Full scrubbing
Time to scrub the fabric data pNVM data (non-recoverable) ^{1, 3}	1.7	1.8	s	Full scrubbing
Time to verify ⁵	1.8	1.9	s	
Total time to zeroize (like new) ^{1, 2}	3.7	3.8	s	
Total time to zeroize (non-recoverable) ^{1, 3}	3.9	4	s	

1. Total completion time after entering zeroization.
2. Like new mode—zeroizes user design security setting and sNVM content.
3. Non-recoverable mode—zeroizes user design security setting, sNVM and factory keys, and factory data required for programming.
4. Time to verify after scrubbing completes.

Table 5-73. Zeroization Times for MPF500T, TL, TS, and TLS Devices

Parameter	Typ	Max	Unit	Conditions
Time to enter zeroization	8	9	ms	Zip flag set
Time to destroy the fabric data ¹	392	422	ms	One iteration of scrubbing
Time to destroy data in non-volatile memory (like new) ^{1, 2}	507	522	ms	One iteration of scrubbing
Time to destroy data in non-volatile memory (non-recoverable) ^{1, 3}	520	536	ms	One iteration of scrubbing
Time to scrub the fabric data ¹	1.4	1.5	s	Full scrubbing
Time to scrub the pNVM data (like new) ^{1, 2}	1.5	1.6	s	Full scrubbing
Time to scrub the fabric data pNVM data (non-recoverable) ^{1, 3}	1.7	1.8	s	Full scrubbing
Time to verify ⁵	1.9	2.0	s	
Total time to zeroize (like new) ^{1, 2}	3.8	3.9	s	
Total time to zeroize (non-recoverable) ^{1, 3}	4.0	4.1	s	

1. Total completion time after entering zeroization.
2. Like new mode—zeroizes user design security setting and sNVM content.
3. Non-recoverable mode—zeroizes user design security setting, sNVM and factory keys, and factory data required for programming.
4. Time to verify after scrubbing completes.

5.6.7 Verify Time

The following tables describe verify time.

Table 5-74. Standalone Fabric Verify Times

Parameter	Devices	Max	Unit
Standalone verification over JTAG	MPF100T, TL, TS, TLS ¹	33	s
	MPF200T, TL, TS, TLS ¹	53	s
	MPF300T, TL, TS, TLS ¹	90	s
	MPF500T, TL, TS, TLS ¹	114	s
Standalone verification over SPI	MPF100T, TL, TS, TLS ²	24	s
	MPF200T, TL, TS, TLS ²	37	s
	MPF300T, TL, TS, TLS ²	55	s
	MPF500T, TL, TS, TLS ²	89	s

1. Programmer: FlashPro5, TCK 10 MHz; PC configuration: Intel i7 at 3.6 GHz, 32 GB RAM, Windows 10.
2. SmartFusion2 with MSS running at 100 MHz, MSS_SPI_0 port running at 6.67 MHz. Bitstream stored in DDR. DirectC version 4.1.

Notes:

- Standalone verify is limited to 2,000 total device hours over the industrial –40 °C to 100 °C temperature.
- Use the digest system service, for verify device time more than 2,000 hours.
- Standalone verify checks the programming margin on both the P and N gates of the push-pull cell.
- Digest checks only the P side of the push-pull gate. However, the push-pull gates work in tandem. Digest check is recommended if users believe they will exceed the 2,000-hour verify time specification.

Table 5-75. Verify Time by Programming Hardware

Devices	IAP	FlashPro4	FlashPro5	BP	Silicon Sculptor	Units
MPF100T, TL, TS, TLS	6	42	33			s
MPF200T, TL, TS, TLS	9	67	53			s
MPF300T, TL, TS, TLS	14	95	90			s
MPF500T, TL, TS, TLS	15	169	114			s

Notes:

- FlashPro4 4 MHz TCK.
- FlashPro5 10 MHz TCK.
- PC configuration: Intel i7 at 3.6 GHz, 32 GB RAM, Windows 10.

Table 5-76. Verify System Services

Parameter	Symbol	ServiceID	Devices	Typ	Max	Unit
In application verify by index	T _{IAP_Ver_Index}	44H	MPF100T, TL, TS, TLS	5.9	6.2	s
			MPF200T, TL, TS, TLS	8.2	9	s
			MPF300T, TL, TS, TLS	12.4	13	s
			MPF500T, TL, TS, TLS	13.4	14	s
In application verify by SPI address	T _{IAP_Ver_Addr}	45H	MPF100T, TL, TS, TLS	5.9	6.2	s
			MPF200T, TL, TS, TLS	8.2	9	s
			MPF300T, TL, TS, TLS	12.4	13	s
			MPF500T, TL, TS, TLS	13.4	14	s

5.6.8 Authentication Time

The following tables describe authentication system service time.

Table 5-77. Authentication Services

Parameter	Symbol	ServiceID	Devices	Typ	Max	Unit
Bitstream Authentication	T _{BIT_AUTH}	22H	MPF100T, TL, TS, TLS	2.1	2.4	s
			MPF200T, TL, TS, TLS	3.3	3.7	s
			MPF300T, TL, TS, TLS	4.9	5.4	s
			MPF500T, TL, TS, TLS	7.6	7.8	s
IAP Image Authentication	T _{IAP_AUTH}	23H	MPF100T, TL, TS, TLS	2.1	2.4	s
			MPF200T, TL, TS, TLS	3.3	3.7	s
			MPF300T, TL, TS, TLS	4.9	5.4	s
			MPF500T, TL, TS, TLS	7.6	7.8	s

5.6.9 Secure NVM Performance

The following table describes secure NVM performance.

Table 5-78. sNVM Read/Write Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Plain text programming		7.0	7.2	7.9	ms	
Authenticated text programming		7.2	7.4	9.4	ms	
Authenticated and encrypted text programming		7.2	7.4	9.4	ms	
Authentication R/W 1st access from power-up overhead	T _{PUF_OVHD}	10	13	111	ms	From T _{FAB_READY}
Plain text read		8	8.5	9	μs	
Authenticated text read		113	114.5	119	μs	

.....continued

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Authenticated and decrypted text read		159	161	167	μs	

Notes:

- Page size= 256 bytes (non-authenticated), 236 bytes (authenticated).
- Only page reads and writes allowed.
- T_{PUF_OVHD} is an additional time that occurs on the first R/W, after cold or warm boot, to sNVM using authenticated or authenticated and encrypted text.

5.6.10 Secure NVM Programming Cycles

The following table describes secure NVM programming cycles.

Table 5-79. sNVM Programming Cycles vs. Retention Characteristics

Programming Temperature	Programming Cycles per Page, Max	Programming Cycles per Block, Max	Retention Years
–40 °C to 100 °C	10,000	100,000	20
–40 °C to 85 °C	10,000	100,000	20
–40 °C to 55 °C	10,000	100,000	20
–40 °C to 125 °C	10,000	100,000	Note 2
–55 °C to 125 °C	10,000	100,000	Note 2

Notes:

1. Page size = 256 bytes. Block size = 56 KBytes.
2. Contact technical support at soc.microsemi.com/Portal/Default.aspx

5.7 System Services

This section describes system switching and throughput characteristics.

5.7.1 System Services Throughput Characteristics

The following table describes system services throughput characteristics.

Table 5-80. System Services Throughput Characteristics

Parameter	Symbol	Service ID	Typ	Max	Unit	Conditions
Serial number	T_{Serial}	00H	65	67	μs	
User code	T_{User}	01H	0.8	1.2	μs	
Design information	T_{Design}	02H	2.5	3	μs	
Device certificate	T_{Cert}	03H	255	271	ms	
Read digests	T_{digest_read}	04H	201	215	μs	
Query security locks	T_{sec_Query}	05H	15	17	μs	
Read debug information	T_{Rd_debug}	06H	34	38	μs	

.....continued						
Parameter	Symbol	Service ID	Typ	Max	Unit	Conditions
Reserved		07H–0FH				
Secure NVM write plain text	T _{SNVM_Wr_Plain}	10H				Note 1
Secure NVM write authenticated plain text	T _{SNVM_Wr_Auth}	11H				Note 1
Secure NVM write authenticated cipher text	T _{SNVM_Wr_Cipher}	12H				Note 1
Reserved		13H–17H				
Secure NVM read	T _{SNVM_Rd}	18H				Note 1
Digital signature service raw	T _{SIG_RAW}	19H	174	187	ms	
Digital signature service DER	T _{SIG_DER}	1AH	174	187	ms	
Reserved		1BH–1FH				
PUF emulation	T _{Challenge}	20H	1.8	2.0	ms	
Nonce service	T _{Nonce}	21H	1.2	1.5	ms	
Bitstream authentication	T _{BIT_AUTH}	22H				Note 4
IAP Image authentication	T _{IAP_AUTH}	23H				Note 4
Reserved		26H–3FH				
In application programming by index	T _{IAP_Prg_Index}	42H				Note 2
In application programming by SPI address	T _{IAP_Prg_Addr}	43H				Note 2
In application verify by index	T _{IAP_Ver_Index}	44H				Note 5
In application verify by SPI address	T _{IAP_Ver_Addr}	45H				Note 5
Auto update	T _{AutoUpdate}	46H				Note 2
Digest check	T _{digest_chk}	47H				Note 3

1. See sNVM Read/Write Characteristics.
2. See SPI Master Programming Time.
3. See Digest Times.
4. See Authentication Services Time.
5. See Verify Services Time.
6. Throughputs described are measured from SS_REQ assertion to BUSY de-assertion.

5.8 Fabric Macros

This section describes switching characteristics of UJTAG, UJTAG_SEC, PF_SPI, system controller, and temper detectors and dynamic reconfiguration.

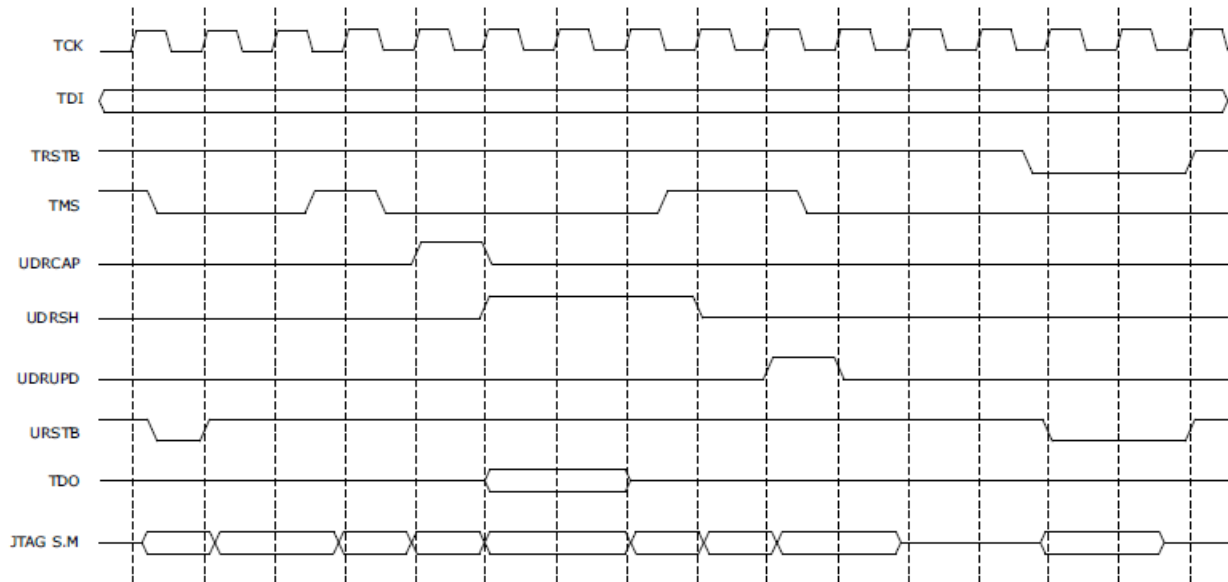
5.8.1 UJTAG Switching Characteristics

The following section describes characteristics of UJTAG switching.

Table 5-81. UJTAG Performance Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
TCK frequency	F _{TCK}			25	MHz	

Figure 5-6. UJTAG Timing Diagram



5.8.2 UJTAG_SEC Switching Characteristics

The following table describes characteristics of UJTAG_SEC switching.

Table 5-82. UJTAG Security Performance Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
TCK frequency	F _{TCK}				MHz	

5.8.3 PF_SPI Master Programming Switching Characteristics

The following section describes characteristics of PF_SPI master programming switching.

Table 5-83. SPI Master Programming Performance Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
SCK frequency	F _{SCK}			20	MHz	

5.8.4 Tamper Detectors

The following section describes tamper detectors.

Table 5-84. ADC Conversion Rate

Parameter	Description	Min	Typ ¹	Max	Unit
T _{CONV1}	Time from enable changing from zero to non-zero value to first conversion completes. Minimum value applies when POWEROFF = 0.	350		470	μs
T _{CONVN}	Time between subsequent channel conversions.		480		μs

AC Switching Characteristics

.....continued

Parameter	Description	Min	Typ ¹	Max	Unit
T _{SETUP}	Data channel and output to valid asserted. Data is held until next conversion completes, that is >480 µs.	0			ns
T _{VALID} ²	Width of the valid pulse.	1.5		2.5	µs
T _{RATE}	Time from start of first set of conversions to the start of the next set. Can be considered as the conversion rate. Is set by the conversion rate parameter.		Rate × 32		µs

1. Min, typ, and max refer to variation due to functional configuration and the raw TVS value. The actual internal correction time will vary based on the raw TVS value.
2. The pulse width varies depending on the time taken to complete the internal calibration multiplication, this can be up to 375 ns.

Note: Once the TVS block is active, the enable signal is sampled 25 ns before the falling edge of valid. The next enabled channel in the sequence 0-1-2-3 is started; that is, if channel 0 has just completed and only channels 0 and 3 are enabled, the next channel will be 3. When all the enabled channels in the sequence 0-1-2-3 are completed, the TVS waits for the conversion rate timer to expire. The enable signal may be changed at any time if it changes to 4'b0000 while valid is asserted (and 25 ns before valid is de-asserted), then no further conversions will be started.

Table 5-85. Temperature and Voltage Sensor Electrical Characteristics

Parameter	Min	Typ	Max	Unit	Condition
Temperature sensing range	–55		125	°C	
Temperature sensing accuracy	–10		10	°C	
Voltage sensing range	0.9		2.8	V	
Voltage sensing accuracy	–3.0		3.0	%	

Table 5-86. Tamper Macro Timing Characteristics—Flags and Clearing

Parameter	Symbol	Typ	Max	Unit
From event detection to flag generation	T _{JTAG_ACTIVE} ¹	28	35	ns
	T _{MESH_ERR} ¹	1.8	2.5	µs
	T _{CLK_GLITCH} ¹		50	ns
	T _{CLK_FREQ} ¹		4	µs
	T _{LOW_VDD} ^{1,3}	70	1000	µs
	T _{HIGH_VDD18} ^{1,3}	85	1000	µs
	T _{HIGH_VDD25} ^{1,3}	130	1000	µs
	T _{SECDEC} ¹		5	ns
	T _{DRI_ERR} ¹	14	18	µs
	T _{WDOG} ¹		5	ns
	T _{LOCK_ERR} ¹		5	ns

.....continued

Parameter	Symbol	Typ	Max	Unit
Time from system controller instruction execution to flag generation	$T_{INST_BUF_ACCESS}^{1,2}$	4	5	μs
	$T_{INST_DEBUG}^{1,2}$	3.3	4	μs
	$T_{INST_CHK_DIGEST}^{1,2}$	1.8	3	μs
	$T_{INST_EC_SETUP}^{1,2}$	1.8	2	μs
	$T_{INST_FACT_PRIV}^{1,2}$	3.8	5	μs
	$T_{INST_KEY_VAL}^{1,2}$	2.5	3.5	μs
	$T_{INST_MISC}^{1,2}$	1.5	2	μs
	$T_{INST_PASSCODE_MATCH}^{1,2}$	2.5	3	μs
	$T_{INST_PASSCODE_SETUP}^{1,2}$	4.2	5	μs
	$T_{INST_PROG}^{1,2}$	3.8	4.5	μs
	$T_{INST_PUB_INFO}^{1,2}$	4	4.5	μs
	$T_{INST_ZERO_RECO}^{1,2}$	2.5	3	μs
	$T_{INST_PASSCODE_FAIL}^{1,2}$	170	180	μs
	$T_{INST_KEY_VAL_FAIL}^{1,2}$	92	110	μs
	$T_{INST_UNUSED}^{1,2}$	4	5	μs
Time from sending the CLEAR to deassertion on FLAG	T_{CLEAR_FLAG}	17	23	ns

1. The timing does not impact the user design, but it is useful for security analysis.
2. System service requests from the fabric will interrupt the system controller delaying the generation of the flag.
3. Timing of these depends highly on supply ramp rate.

Table 5-87. Tamper Macro Response Timing Characteristics

Parameter	Symbol	Typ	Max	Unit
Time from triggering the response to all I/Os disabled	$T_{IO_DISABLE}$	45	63	ns
Time from negation of RESPONSE to all I/Os re-enabled	$T_{CLR_IO_DISABLE}$	34	51	ns
Time from triggering the response to security locked	$T_{LOCKDOWN}$		20	ns
Time from negation of RESPONSE to earlier security unlock condition	$T_{CLR_LOCKDOWN}$		20	ns
Time from triggering the response to device enters RESET	T_{tr_RESET}	11.7	14	μs
Time from triggering the response to start of zeroization	$T_{tr_ZEROLISE}$	7.4	8.2	ms

5.8.5 System Controller Suspend Switching Characteristics

The following table describes the characteristics of system controller suspend switching.

Table 5-88. System Controller Suspend Entry and Exit Characteristics

Parameter	Symbol	Definition	Typ	Max	Unit
Time from TRSTb falling edge to SUSPEND_EN signal assertion	$T_{\text{suspend_Tr}}$ ^{1, 2}	Suspend entry time from TRST_N assertion	42	44	ns
Time from TRSTb rising edge to ACTIVE signal assertion	$T_{\text{suspend_exit}}$	Suspend exit time from TRST_N negation	361	372	ns

1. ACTIVE indicates that the system controller is inactive or active regardless of the state of SUSPEND_EN.
2. ACTIVE signal must never be asserted with SUSPEND_EN is asserted.

5.8.6 Dynamic Reconfiguration Interface

The following table provides interface timing information for the DRI, which is an embedded APB slave interface within the FPGA fabric that does not use FPGA resources.

Table 5-89. Dynamic Reconfiguration Interface Timing Characteristics

Parameter	Symbol	Max	Unit
PCLK frequency	$F_{\text{PD_PCLK}}$	200	MHz

5.8.7 User Voltage Detector Characteristics

The following table provides the electrical characteristics of the VDD (1.0 V), VDD18, and VDD25 voltage detectors. For proper operation of the voltage detectors, Vdd must be set to 1.0 V.

Table 5-90. User Voltage Detector Electrical Characteristics

Parameter	Min	Typ	Max	Unit	Condition
V _{DD_HIGH_DET}	1.04		1.07	V	Temp= -40 °C to 100 °C; V _{DD18} = 1.8 V ±5%; V _{DD25} = 2.5 V ±5%
V _{DD18_HIGH_DET}	1.9		1.96	V	Temp= -40 °C to 100 °C; V _{DD} = 1.0 V ±3%; V _{DD25} = 2.5 V ±5%
V _{DD25_HIGH_DET}	2.66		2.74	V	Temp= -40 °C to 100 °C; V _{DD} = 1.0 V ±3%; V _{DD18} = 1.8 V ±5%
V _{DD_LOW_DET}	0.945		0.915	V	Temp= -40 °C to 100 °C; V _{DD18} = 1.8 V ±5%; V _{DD25} = 2.5 V ±5%
V _{DD18_LOW_DET}	1.62		1.57	V	Temp= -40 °C to 100 °C; V _{DD} = 1.0 V ±3%; V _{DD25} = 2.5 V ±5%
V _{DD25_LOW_DET}	2.31		2.21	V	Temp= -40 °C to 100 °C; V _{DD} = 1.0 V ±3%; V _{DD18} = 1.8 V ±5%

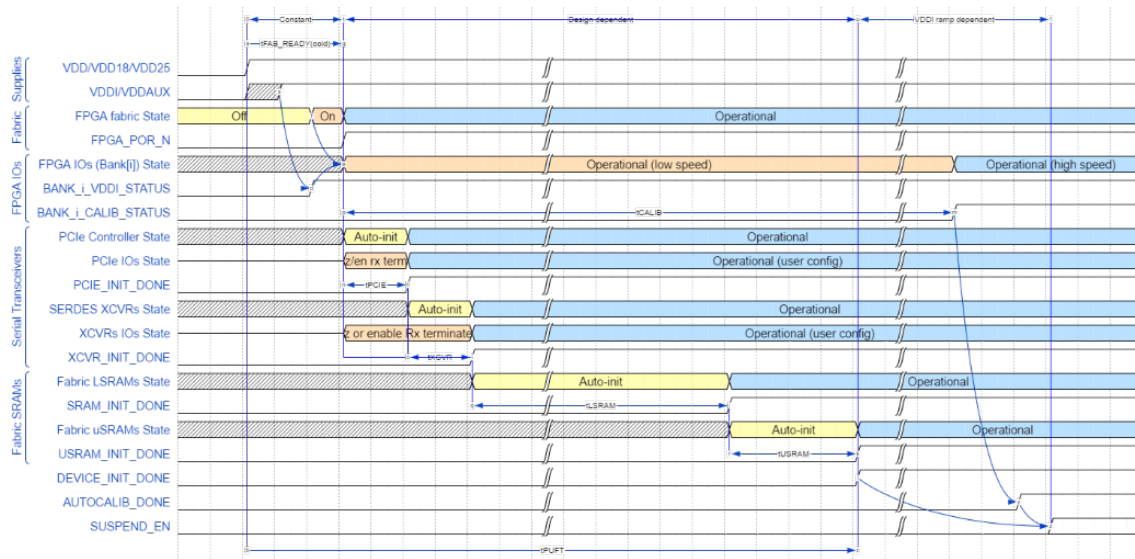
5.9 Power-Up to Functional Timing

Microsemi non-volatile FPGA technology offers the fastest boot-time of any mid-range FPGA in the market. The following tables describes both cold-boot (from power-on) and warm-boot (assertion of DEVRST_N pin or assertion of reset from the tamper macro) timing. The power-up diagrams assume all power supplies to the device are stable.

5.9.1 Power-On (Cold) Reset Initialization Sequence

The following cold reset timing diagram shows the initialization sequencing of the device.

Figure 5-7. Cold Reset Timing



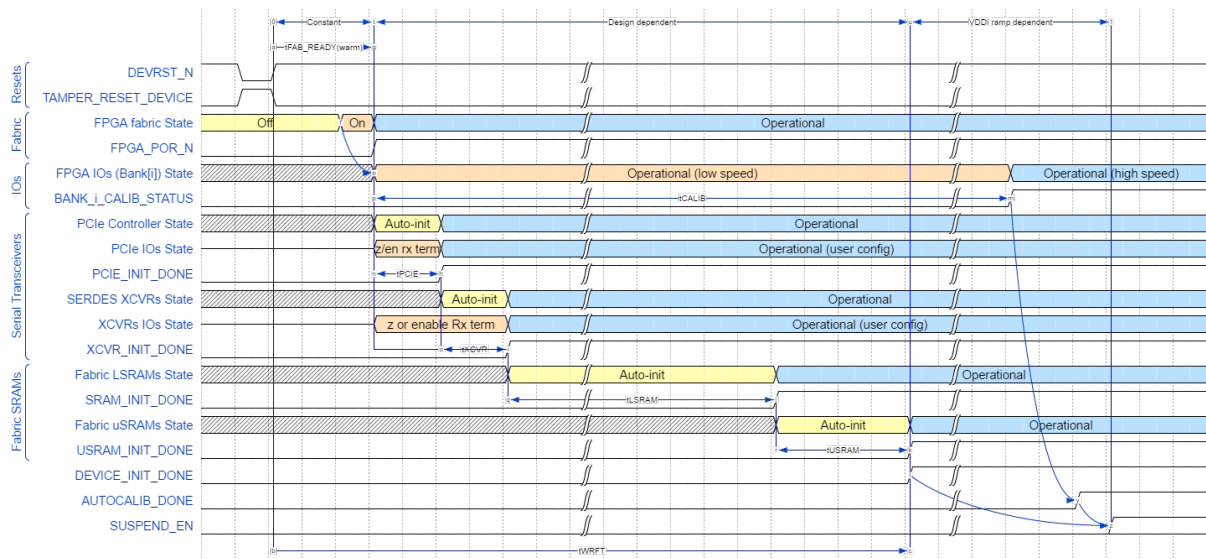
Notes:

- The previous diagram shows the case where VDDI/VDDAUX of I/O banks are powered either before or sufficiently soon after VDD/VDD18/VDD25 that the I/O bank enable time is measured from the assertion time of VDD/VDD18/VDD25 (that is, the PUFT specification). If VDDI/VDDAUX of I/O banks are powered sufficiently after VDD/VDD18/VDD25, then the I/O bank enable time is measured from the assertion of VDDI/VDDAUX and is not specified by the PUFT specification. In this case, I/O operation is indicated by the assertion of BANK_i_VDDI_STATUS, rather than being measured relative to FABRIC_POR_N negation.
- AUTOCALIB_DONE assertion indicates the completion of calibration for any I/O banks specified by the user for auto-calibration. AUTOCALIB_DONE asserts independently of DEVICE_INIT_DONE. It may assert before or after DEVICE_INIT_DONE and is determined by the following:
 - How long after VDD/VDD18/VDD25 that VDDI/VDDAUX are powered on. Note that if any of the user-specified I/O banks are not powered on within the auto-calibration timeout window, then AUTOCALIB_DONE doesn't assert until after this timeout.
 - The specified ramp times of VDDI of each I/O bank designated for auto-calibration.
 - How much auto-initialization is to be performed for the PCIe, SERDES transceivers, and fabric LSRAMs.
- If any of the I/O banks specified for auto-calibration do not have their VDDI/VDDAUX powered on within the auto-calibration timeout window, then it will be approximately auto-calibrated whenever VDDI/VDDAUX is subsequently powered on. To obtain an accurate calibration however, on such IO banks, it is necessary to initiate a re-calibration (using CALIB_START from fabric).
- AVM_ACTIVE only asserts if avionics mode is being used. It is asserted when the later of DEVICE_INIT_DONE or AUTOCALIB_DONE assert.

5.9.2 Warm Reset Initialization Sequence

The following warm reset timing diagram shows the initialization sequencing of the device when either DEVRST_N or TAMPER_RESET_DEVICE signals are asserted.

Figure 5-8. Warm Reset Timing



5.9.3 Power-On Reset Voltages

The following sections describe the power-on reset voltages.

5.9.3.1 Main Supplies

The start of power-up to functional time (T_{PUFT}) is defined as the point at which the latest of the main supplies (VDD, VDD18, VDD25) reach the reference voltage levels specified in the following table. This starts the process of releasing the reset of the device and powering on the FPGA fabric and I/Os.

Table 5-91. POR Ref Voltages

Supply	Power-On Reset Start Point (V)	Note
VDD	0.95	Applies to both 1.0 V and 1.05 V operation.
VDD18	1.71	
VDD25	2.25	

5.9.3.2 I/O-Related Supplies

For the I/Os to become functional (for low speed, sub-400 MHz operation), the (per-bank) I/O supplies (VDDI, VDDAUX) must reach the trip point voltage levels specified in the following table and the main supplies above must also be powered on.

Table 5-92. I/O-Related Supplies

Supply	I/O Power-Up Start Point (V)
VDDI	0.85
VDDAUX	1.6

There are no sequencing requirements for the power supplies. There are few sequences that can create temporary glitches on GPIO during initialization. Refer to [UG0726: PolarFire FPGA Board Design User Guide](#) for more details. In order for the device to start initialization, VDDI3 must be valid at the same time as the other main supplies (VDD, VDD18, VDD25). The other I/O supplies (VDDI, VDDAUX) have no effect on power-up of FPGA fabric (that is, the fabric still powers up even if the I/O supplies of I/O banks remain powered off, with the exception of VDDI3).

5.9.4 User Design Dependence of Power-Up Times

Some phases of the device initialization are user design dependent, as the device automatically initializes certain resources to user-specified configurations if those resources are used in the design. It is necessary to compute the overall power-up to functional time by referencing the following tables and adding the relevant phases, according to the design configuration. The following equation refers to timing parameters specified in the above timing diagrams. Please note T_{PCIE} , T_{XCVR} , T_{LSRAM} , and T_{USRAM} can be found in the PolarFire FPGA device power-up and resets user guide UG0725.

$$T_{PUFT} = T_{FAB_READY(cold)} + \max((T_{PCIE} + T_{XCVR} + T_{LSRAM} + T_{USRAM}), T_{CALIB})$$

$$T_{WRFT} = T_{FAB_READY(warm)} + \max((T_{PCIE} + T_{XCVR} + T_{LSRAM} + T_{USRAM}), T_{CALIB})$$

Note: T_{PCIE} , T_{XCVR} , T_{LSRAM} , T_{USRAM} , and T_{CALIB} are common to both cold and warm reset scenarios.

Auto-initialization of FPGA (if required) occurs in parallel with I/O calibration. The device may be considered fully functional only when the later of these two activities has finished, which may be either one, depending on the configuration, as may be calculated from the following tables. Note that I/O calibration may extend beyond T_{PUFT} (as I/O calibration process is independent of main device power-on and is instead dependent on I/O bank supply relative power-on time and ramp times). The previous timing diagram for power-on initialization shows the earliest that I/Os could be enabled, if the I/O power supplies are powered on before or at the same time as the main supplies.

5.9.5 Cold Reset to Fabric and I/Os (Low Speed) Functional

The following table specifies the minimum, typical, and maximum times from the power supplies reaching the above trip point levels until the FPGA fabric is operational and the FPGA I/Os are functional for low-speed (sub-400 MHz) operation.

Table 5-93. Cold Boot

Power-On (Cold) Reset to Fabric and I/O Operational	Min	Typ	Max	Unit
Time when input pins start working – $T_{IN_ACTIVE(cold)}$	0.92	4.38	7.84	ms
Time when weak pull-ups are enabled – $T_{PU_PD_ACTIVE(cold)}$	0.92	4.38	7.84	ms
Time when fabric is operational – $T_{FAB_READY(cold)}$	0.95	4.41	7.87	ms
Time when output pins start driving – $T_{OUT_ACTIVE(cold)}$	0.97	4.43	7.89	ms

5.9.6 Warm Reset to Fabric and I/Os (Low Speed) Functional

The following table specifies the minimum, typical, and maximum times from the negation of the warm reset event until the FPGA fabric is operational and the FPGA I/Os are functional for low-speed (sub-400 MHz) operation.

Table 5-94. Warm Boot

Warm Reset to Fabric and I/O Operational	Min	Typ	Max	Unit
Time when input pins start working – $T_{IN_ACTIVE(warm)}$	0.65	1.63	2.62	ms
Time when weak pull-ups/pull-downs are enabled – $T_{PU_PD_ACTIVE(warm)}$	0.65	1.63	2.62	ms
Time when fabric is operational – $T_{FAB_READY(warm)}$	0.68	1.66	2.65	ms
Time when output pins start driving – $T_{OUT_ACTIVE(warm)}$	0.70	1.68	2.67	ms

5.9.7 Miscellaneous Initialization Parameters

In the following table, T_{FAB_READY} refers to either $T_{FAB_READY(cold)}$ or $T_{FAB_READY(warm)}$ as specified in the previous tables, depending on whether the initialization is occurring as a result of a cold or warm reset, respectively.

Table 5-95. Cold and Warm Boot

Parameter	Symbol	Min	Typ	Max	Unit	Condition
The time from T_{FAB_READY} to ready to program through JTAG/SPI-Slave		0	0	0	ms	
The time from T_{FAB_READY} to auto-update start			$T_{PUF_OVHD}^1$	$T_{PUF_OVHD}^1$	ms	
The time from T_{FAB_READY} to programming recovery start			$T_{PUF_OVHD}^1$	$T_{PUF_OVHD}^1$	ms	
The time from T_{FAB_READY} to the tamper flags being available	T_{TAMPER_READY}	0	0	0	ms	
The time from T_{FAB_READY} to the Athena Crypto co-processor being available (for S devices only)	T_{CRYPTO_READY}	0	0	0	ms	

1. Programming depends on the PUF to power up. Refer to T_{PUF_OVHD} at section Secure NVM Performance.

5.9.8 I/O Calibration

The following tables specify the initial I/O calibration time for the fastest and slowest supported VDDI ramp times of 0.2 ms to 50 ms, respectively. This only applies to I/O banks specified by the user to be auto-calibrated.

Table 5-96. I/O Initial Calibration Time (TCALIB)

Ramp Time	Min (ms)	Max (ms)	Condition
0.2 ms	0.98	2.63	Applies to HSIO and GPIO banks
50 ms	41.62	62.19	Applies to HSIO and GPIO banks

Notes:

- The user may specify any VDDI ramp time in the range specified above. The nominal initial calibration time is given by the specified VDDI ramp time plus 2 ms.
- In order for IO calibration to start, VDDI and VDDAUX of the I/O bank must be higher than the trip point levels specified in I/O-Related Supplies.

Table 5-97. I/O Fast Recalibration Time (TRECALIB)

I/O Type	Min (ms)	Typ (ms)	Max (ms)	Condition
GPIO bank	0.04	0.14	0.24	GPIO configured for 3.3 V operation
HSIO bank	0.11	0.20	0.30	HSIO configured for 1.8 V operation

Note: In order to obtain fast re-calibration, the user must assert the relevant clock request signal from the FPGA fabric to the I/O bank controller.

5.10 Dedicated Pins

The following section describes the dedicated pins.

5.10.1 JTAG Switching Characteristics

The following table describes characteristics of JTAG switching.

Table 5-98. JTAG Electrical Characteristics

Symbol	Description	Min	Typ	Max	Unit	Condition
T _{DISU}	TDI input setup time	0.0			ns	
T _{DIHD}	TDI input hold time	2.0			ns	
T _{TMSSU}	TMS input setup time	1.5			ns	
T _{TMSHD}	TMS input hold time	1.5			ns	
F _{TCK}	TCK frequency			25	MHz	
T _{TCKDC}	TCK duty cycle	40		60	%	
T _{TDOCQ}	TDO clock to Q out			8.4	ns	C _{LOAD} = 40 pf
T _{RSTBCQ}	TRSTB clock to Q out			23.5	ns	C _{LOAD} = 40 pf
T _{RSTBPW}	TRSTB min pulse width	50			ns	
T _{RSTBREM}	TRSTB removal time	0.0			ns	
T _{RSTBREC}	TRSTB recovery time	12.0			ns	
CIN _{TDI}	TDI input pin capacitance			5.3	pf	
CIN _{TMS}	TMS input pin capacitance			5.3	pf	
CIN _{TCK}	TCK input pin capacitance			5.3	pf	
CIN _{TRSTB}	TRSTB input pin capacitance			5.3	pf	

5.10.2 SPI Switching Characteristics

The following tables describe characteristics of SPI switching.

Table 5-99. SPI Master Mode (PolarFire Master)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
SCK frequency	sp1			20	MHz	During Programming
				40	Mhz	During Initialization
SCK minimum pulse width high	sp2	SCK_period/2			ns	
SCK minimum pulse width low	sp3	SCK_period/2			ns	
Rise and fall time	sp4 sp5				ns	Refer to PolarFire IBIS models ³
SDO setup time	sp6m	(SCK_period/2) – 3.0			ns	
SDO hold time	sp7m	(SCK_period/2) – 2.0			ns	
SDI setup time	sp8m	10.0			ns	
SDI hold time	sp9m	–1.0			ns	

Notes:

1. Parameters are referenced to the active edge of SCK, which depends on the configured SPI protocol (for example, Motorola SPI mode uses rising edge as active edge if SPO= 0).
2. SDI is clocked into SPI on active edge and clocked out on inactive edge. Therefore, SDO delay parameters are dependent on SCK frequency (nominally SCK_period/2).
3. For specific rise/fall times, board design considerations, and detailed output buffer resistances, use the corresponding IBIS models located online at Microsemi SoC Products Group.

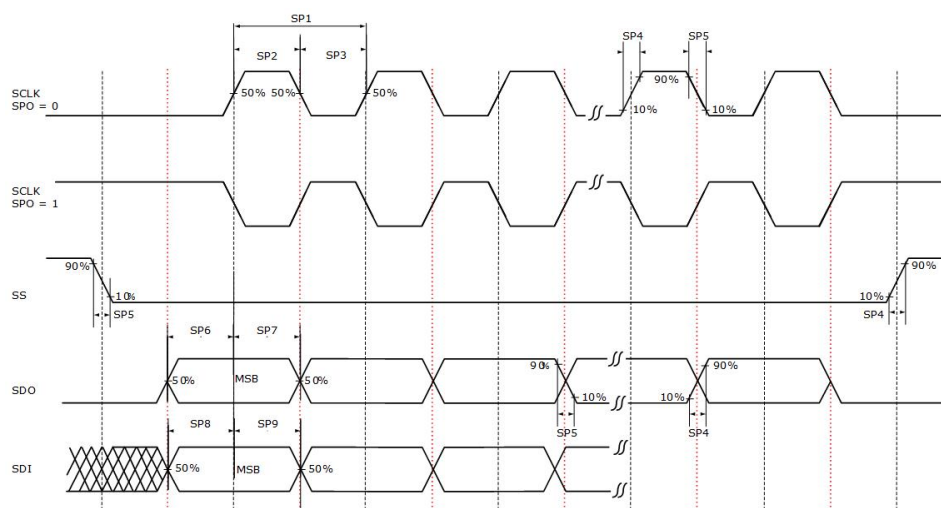
Table 5-100. SPI Slave Mode (PolarFire Slave)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
SCK frequency	sp1			80	MHz	
SCK minimum pulse width high	sp2	SCK_period/2			ns	
SCK minimum pulse width low	sp3	SCK_period/2			ns	
Rise and fall time	sp4 sp5				ns	Refer to PolarFire IBIS models ³
SDO setup time	sp6s	(SCK_period/2) – 8.0			ns	
SDO hold time	sp7s	SCK_period/2			ns	
SDI setup time	sp8s	4.0			ns	
SDI hold time	sp9s	2.0			ns	

Notes:

1. Parameters are referenced to the active edge of SCK, which depends on the configured SPI protocol (for example, Motorola SPI mode uses rising edge as active edge if SPO= 0).
2. SDI is clocked into SPI on active edge and clocked out on inactive edge. Therefore, SDO delay parameters are dependent on SCK frequency (nominally SCK_period/2).
3. For specific rise/fall times, board design considerations, and detailed output buffer resistances, use the corresponding IBIS models located online at Microsemi SoC Products Group.

Figure 5-9. SPI Timing for a Single Frame Transfer in Motorola Mode (SPH = 1)



5.10.3 SmartDebug Probe Switching Characteristics

The following table describes characteristics of SmartDebug probe switching.

Table 5-101. SmartDebug Probe Performance Characteristics

Parameter	Symbol	V _{DD} = 1.0 V STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V STD	V _{DD} = 1.05 V – 1	Unit
Maximum frequency of probe signal	F _{MAX}	100	100	100	100	MHz
Minimum delay of probe signal	T _{Min_delay}					ns
Maximum delay of probe signal	T _{Max_delay}					ns

5.10.4 DEVRST_N Switching Characteristics

The following table describes characteristics of DEVRST_N switching.

Table 5-102. DEVRST_N Electrical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Condition
DEVRST_N ramp time	DR _{RAMP}		10		μs	It must be a normal clean digital signal, with typical rise and fall times
DEVRST_N assert time	DR _{ASSERT}	1			μs	The minimum time for DEVRST_N assertion to be recognized
DEVRST_N de-assert time	DR _{DEASSERT}	2.75			ms	The minimum time DEVRST_N needs to be de-asserted before assertion

5.11 User Crypto

The following section describes user crypto.

5.11.1 TeraFire 5200B Switching Characteristics

The following table describes TeraFire 5200B switching characteristics.

Table 5-103. TeraFire F5200B Switching Characteristics

Parameter	Symbol	V _{DD} = 1.0 V STD	V _{DD} = 1.0 V – 1	V _{DD} = 1.05 V STD	V _{DD} = 1.05 V – 1	Unit	Condition
F _{MAX} with DLL	F _{MAX_DLL}	189	189	189	189	MHz	–40 °C to 100 °C
F _{MIN} with DLL	F _{MIN_DLL}	125	125	125	125	MHz	–40 °C to 100 °C
F _{MAX} with DLL in bypass mode	F _{MAX_DLL_BYPASS}	70	70	70	70	MHz	–40 °C to 100 °C
F _{MIN} with DLL in bypass mode	F _{MIN_DLL_BYPASS}	0	0	0	0	MHz	–40 °C to 100 °C

5.11.2 TeraFire 5200B Throughput Characteristics

The following tables for each algorithm describe the TeraFire 5200B throughput characteristics.

Note: Throughput cycle count collected with Athena TeraFire Core and RISC-V running at 70 MHz.

Table 5-104. AES

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay in CPU Clock-Cycles
AES-ECB-128 encrypt ¹	128	511	1011
	64K	48109	927
AES-ECB-128 decrypt ¹	128	557	1328
	64K	48385	1282
AES-ECB-256 encrypt ¹	128	527	1333
	64K	56301	1303
AES-ECB-256 decrypt ¹	128	589	1356
	64K	56673	1410
AES-CBC-256 encrypt ¹	128	588	1316
	64K	58691	1286
AES-CBC-256 decrypt ¹	128	617	1676
	64K	56853	1730
AES-GCM-128 encrypt ¹ , 128-bit tag, (full message encrypted/authenticated)	128	1921	1701
	64K	58022	1640
AES-GCM-256 encrypt ¹ , 128-bit tag, (full message encrypted/authenticated)	128	1969	1718
	64K	58054	1803

1. With DPA counter measures.

Table 5-105. GMAC

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
AES-GCM-256 ¹ , 128-bit tag, (message is only authenticated)	128	1859	1752
	64K	47659	1854

1. With DPA counter measures.

Table 5-106. HMAC

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
HMAC-SHA-256 ¹ , 256-bit key	512	7461	1616
	64K	86319	1350

.....continued

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
HMAC-SHA-384 ¹ , 384-bit key	1024	13017	1438
	64K	104055	1438

1. With DPA counter measures.

Table 5-107. CMAC

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
AES-CMAC-256 ¹ (message is only authenticated)	128	446	8434
	64K	45494	110209

1. With DPA counter measures.

Table 5-108. KEY TREE

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
128-bit nonce + 8-bit optype		102457	2173
256-bit nonce + 8-bit optype		103218	2359

Table 5-109. SHA

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
SHA-1 ¹	512	2370	816
	64K	75528	709
SHA-256 ¹	512	2500	656
	64K	82704	656
SHA-384 ¹	1024	4122	712
	64K	98174	656
SHA-512 ¹	1024	4122	652
	64K	98174	653

1. With DPA counter measures.

Table 5-110. ECC

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
ECDSA SigGen, P-384/SHA-384 ¹	1024	12525647	5072
	8K	12540387	5072
ECDSA SigGen, P-384/SHA-384	1024	5502896	5071
	8K	5513718	5071
ECDSA SigVer, P-384/SHA-384 ¹	1024	6243821	4683
	8K	6321110	4422
ECDSA SigVer, P-384/SHA-384	1024	6243821	4422
	8K	6321110	4422
Key Agreement (KAS), P-384		5039125	10318
Point Multiply, P-256 ¹		5177474	4434
Point Multiply, P-384 ¹		12055519	5086
Point Multiply, P-521 ¹		26889271	6470
Point Addition, P-384		3018067	5303
KeyGen (PKG), P-384		12052230	7909
Point Verification, P-384		5091	3354

1. With DPA counter measures.

Table 5-111. IFC (RSA)

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
Encrypt, RSA-2048, e=65537	2048	436972	8287
Encrypt, RSA-3072, e=65537	3072	962162	12063
Decrypt, RSA-2048 ¹ , CRT	2048	26847616	15261
Decrypt, RSA-3072 ¹ , CRT	3072	75168689	22488
Decrypt, RSA-4096, CRT	4096	88789629	23585
Decrypt, RSA-3072, CRT	3072	38202717	18838
SigGen, RSA-3072/SHA-384 ¹ , CRT, PKCS #1 V 1.1.5	1024	75156973	19562
	8K	75222026	18880
SigGen, RSA-3072/SHA-384, PKCS #1, V 1.5	1024	148092303	13622
	8K	148102319	13622

.....continued			
Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
SigVer, RSA-3072/SHA-384, e = 65537, PKCS #1 V 1.5	1024	970959	11769
	8K	981755	11769
SigVer, RSA-2048/SHA-256, e = 65537, PKCS #1 V 1.5	1024	443593	8490
	8K	452751	8443
SigGen, RSA-3072/SHA-384, ANSI X9.31	1024	147143879	13624
	8K	147153109	13417
SigVer, RSA-3072/SHA-384, e = 65537, ANSI X9.31	1024	972788	11268
	8K	983643	11215

1. With DPA counter measures.

Table 5-112. FFC (DH)

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
SigGen, DSA-3072/SHA-384 ¹	1024	27932434	13271
	8K	27946636	13166
SigGen, DSA-3072/SHA-384	1024	12086324	13028
	8K	12097138	12862
SigVer, DSA-3072/SHA-384	1024	24711796	14689
	8K	24418930	14689
SigVer, DSA-2048/SHA-256	1024	9673222	10717
	8K	9803028	10717
Key Agreement (KAS), DH-3072 (p=3072,security=256)		4920705	9519
Key Agreement (KAS), DH-3072 (p=3072,security=256) ¹		78871914	9495

1. With DPA counter measures.

Table 5-113. NRBG

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
Instantiate: strength, s=256, 384-bit nonce, 384-bit personalization string		18221	3076

AC Switching Characteristics

.....continued

Modes	Message Size (Bits)	Athena TeraFire Crypto Core Clock-Cycles	CAL Delay In CPU Clock-Cycles
Reseed: no additional input, s=256		13585	1056
Reseed: 384-bit additional input, s=256		15922	995
Generate: (no additional input), prediction resistance enabled, s=256	128	15262	1672
	8K	27169	7837
Generate: (no additional input), prediction resistance disabled, s=256	128	2138	781
	8K	14045	7837
Generate: (384-bit additional input), prediction resistance enabled, s=256	128	21299	1620
	8K	33206	8563
Generate: (384-bit additional input), prediction resistance disabled, s=256	128	11657	1507
	8K	23564	8563
Un-instantiate		761	502

6. Revision History

Revision	Date	Description
A	02/2021	- Updated document to Microchip template. - Updated document number from DS51700141 to DS00003831. - Added automotive and military temperature-grade specifications. - Increased MIPI TX speeds from 800 Mbps to 1000 Mbps for STD speed grade. - Removed digest junction temperature from the table Maximum Number of Digest Cycles as it has no effect on device retention. - Added SDI 6G and 12G rates.
1.8	11/2020	- Added footnote 3 to clarify mixed I/O receiver capability for Table 4-15. - Clarified GPIO V_{ICM} and HSIO V_{ICM} rules in footnote 3 in Table 4-17. - Added Table 4-25. - Added minimum DDR memory data rates to Table 5-7 and Table 5-8. - Corrected F_{MAX} values for QDR memories from 113 MHz to 112.5 MHz in Table 5-8. - Added note to indicate which IOD delay setting was used to achieve the specifications for the following tables: Table 5-9 Table 5-10 Table 5-11 Table 5-12 - Included a +/- maximum specification in addition to the absolute maximum specification for "PLL output period jitter" in Table 5-18. - Added footnote 11 to Table 5-18 to direct customers to contact technical support for protocol-specific jitter characteristics. - Updated values in Table 5-26. - Added transceiver loopback rates and two footnotes to Table 5-29. - Updated transceiver refclk inputs from 156 MHz to 156.3 MHz in Table 5-30. - Added min/max specifications to "Differential termination" in Table 5-36 and Table 5-37. - Made the following updates to Table 5-52: - Added 8.1 Gbps data rates. - Clarified total receive jitter tolerance for 5.4 Gbps data rate. - Added footnote to total transmit jitter for 5.4 Gbps data rate max. - Made the following updates to Table 5-59: - Added FireWire S200 specifications. - Lowered FireWire S400 Tx jitter from 557 ps to 516 ps. - Clarified FireWire S800 amplitude specification. - Added Table 5-60. - Deleted Table 103 SPI Macro Interface Timing Characteristics and replaced with 5.8.3 PF_SPI Master Programming Switching Characteristics. To determine timing of the user SPI macro from the fabric, please use SmartTime. - Updated the signal name AVM_ACTIVE to SUSPEND_EN in Figure 5-7 and Figure 5-8. - Clarified device behavior in description underneath Table 5-92.

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Revision	Date	Description
1.7	12/2019	- Updated table PolarFire FPGA Silicon Status. Libero 12.2 now contains production timing and power for all devices. - Corrected footnote 5 in the table PolarFire Transceiver Reference Clock AC Requirements. - Corrected footnote in the table sNVM Programming Cycles vs. Retention Characteristics. - Added timing parameters to the table Master SPI Programming Time (IAP) and table Slave SPI Programming Time. - Added 270 mbps rates to the section SDI. - Added FireWire section. - Added footnotes to the following tables: - Recommended Operating Conditions - I/O Digital Receive Double Data Rate Switching Characteristics - I/O Digital Transmit Single Data Rate Switching Characteristics - I/O Digital Transmit Double Data Rate Switching Characteristics - HSIO Maximum Input Buffer Speed - HSIO Maximum Output Buffer Speed - GPIO Maximum Output Buffer Speed - Programmable Delay - Added MIPI data rates to the following tables: - GPIO Maximum Input Buffer Speed - GPIO Maximum Output Buffer Speed - Updated MIPIE25 output DC specifications.
1.6	06/2019	- The parameter RX_DDRX_B_G_FA (for Video7 applications) was added. For more information, see table I/O Digital Receive Double-Data Rate Switching Characteristics. - I/O CDR switching characteristics were added. For more information, see table I/O CDR Switching Characteristics. - High-speed I/O clock skew with bridging was added. For more information, see table High-Speed I/O Clock Characteristics (–40 °C to 100 °C). - PCS and PMA minimum reset pulse widths were added. For more information, see table PolarFire Transceiver and TXPLL Performance. - Auto adaptive calibration was added to CDR lock times, Burst Mode Receiver (BMR) high-gain lock time, and BMR high-gain state time. For more information, see table PolarFire Transceiver Receiver Characteristics. - Fiber channel rates were corrected. For more information, see table Fiber Channel. - HiGig and HiGig+ specifications were updated. For more information, see table HiGig and HiGig+. - HiGig II specifications were updated. For more information, see table HiGigII. - The DEVRST_N parameter was correctly classified as ramp time. For more information, see section Dedicated Pins. - Transmitter and receiver return loss characteristics were added. For more information, see section Transceiver Switching Characteristics. - Voltage detector specifications were added and the voltage glitch detector was removed. For more information, see section User Voltage Detector Characteristics.

.....continued

Revision	Date	Description
1.5		- All tables have been reviewed and updated to reflect production silicon characteristics for the 200T, 200TL, 200TS, 200TLS, 100T, 100TL, 100TS, and 100TLS devices in all packages, speed grades, and temperature grades. - The maximum transceiver reference clock input rate was changed from 800 MHz to 400 MHz due to a typo in version 1.4. For more information, see table PolarFire Transceiver Reference Clock AC Requirements.
1.4	09/2018	All tables have been reviewed and updated to reflect production silicon characteristics for the 300T, 300TL, 300TS, and 300TLS devices in all packages, speed grades, and temperature grades.
1.3	06/2018	- The System Services section was updated. - The Non-Volatile Characteristics section was updated. - The Fabric Macros section was updated. - The Transceiver Switching Characteristics section was updated.
1.2	06/2018	The datasheet has moved to preliminary status. Every table has been updated.
1.1	08/2017	- LVDS specifications changed to 1.25G. - LVDS18, LVDS25/LVDS33, and LVDS25 specifications changed to 800 Mbps. - A note was added indicting a zeroization cycle counts as a programming cycle. - A note was added defining power down conditions for programming recovery conditions.
1.0		Initial Revision

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